

SAMSUNG

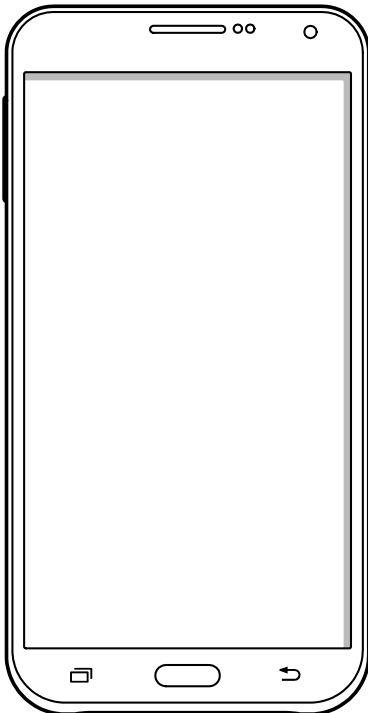
Wireless Device

SM-A700H

SERVICE *Manual*

Wireless Device

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Notice: All functionality, features, specifications, and other product information provided in this document, including but not limited to, benefits, design, pricing, components, performance, availability, and capabilities of the product are subject to change without notice. Samsung reserves the right to alter this document or the product described herein at anytime, without obligation to provide notification of such changes.

**SAMSUNG
ELECTRONICS**



7. Level 2 Repair

7-1. Pre-requisite

	
Tweezers / Disass'y Stick / Screw Driver	Anti-static Gloves
	
OCTA Disassembly Holder	Anti-static Mat
	
Acryl Jig Rework Form	Glass Absorbers (2ea)
	
Tape Rework Form	Mobile Dryer

7-2. Parts which must be changed after repair

OCTA Form Tape	 A photograph of a rectangular, light brown, textured tape with a black border, mounted on a green circuit board.
Bracket Cu Tape	 A photograph of a rectangular, dark brown, textured tape with a black border, mounted on a green circuit board.
Touch Key Top Tape	 A photograph of a white, rectangular tape with four square cutouts, each containing a small, dark, rectangular component.

7-3. Disassembly

1

- 1) Put the device in the chamber for 5~10 minutes under 70~80 °C.
- 2) Detach the OCTA with Disass'y JIG.



※ Caution

- 1) Be care of scratch

2

- 1) Unscrew 11 points

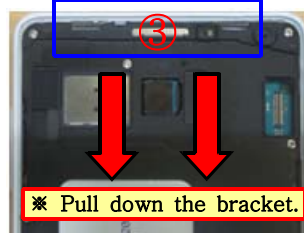


※ Caution

- Be careful not to Damage

3

- 1) Detach the 2 point hooks in order.
- 2) Disassemble the bracket.



※ Pull down the bracket.

※ Caution

- 1) Be Careful not to Damage of PBA
(Must remove the 2nd hook.)

4

- 1) Detach the Bracket and REAR



※ Caution

- Be careful not to Damage

5

- 1) Unscrew 2 points
- 2) Detach Connector and Coaxial Cable from PBA



※ Caution
Be careful not to Damage

6

- 1) Detach the PBA from bottom REAR



※ Caution
Be careful not to Damage

7

- 1) Detach Main& Sub camera on PBA.



※ Caution
Be careful not to Damage

8

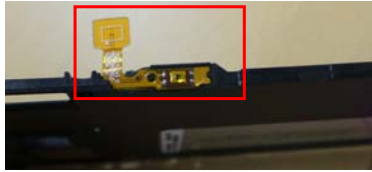
- Detach the Receiver, Speaker, Coaxial Cable and Battery



※ Caution
Be careful not to Damage

9

1)Detach Sub PBA and Power key



※ Caution
Be careful not to Damage

7-4. assembly

1

1) Assemble Sub PBA and Power key



※ Caution
Be careful not to Damage

2

1) Assemble the Coaxial Cable and RCV, Speaker, Battery.



※ Caution

3

1) Attach Main and Sub Camera on PBA



※ Caution
Be careful not to Damage

4

1) Assemble PBA on Bracket
2) Assemble lower Sub PBA and Main PBA



※ Caution
Be careful not to Damage

5

- 1) Assemble Connector on the PBA Assy
- 2) Assemble Coaxial Cable



6

- 1) Tighten a screw
 $1.2 \pm 0.1 \text{ Kgf/cm}^2$



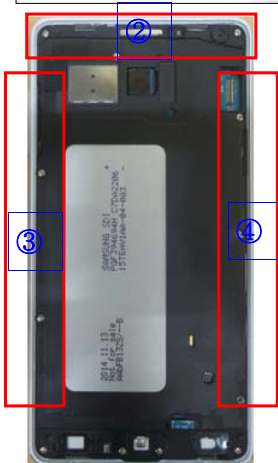
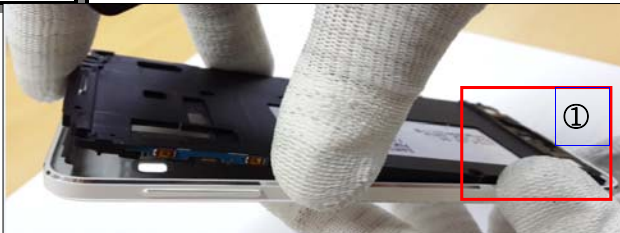
※ Caution

※ Caution

Torque : $1.2 \pm 0.1 \text{ Kgf/cm}^2$
Screw : 1.4 * 2.0(6001-001695, Black)

7

- 1) Assemble the PBA Assy to Rear in order.



8

- 1) Tighten screw the 11 point
 $1.3 \pm 0.1 \text{ Kgf/cm}^2$



※ Caution

※ Caution

Torque : $1.3 \pm 0.1 \text{ Kgf/cm}^2$
Screw : 1.4 * 2.5(6001-003193, Silver)

9

1) Attach OCTA



※ Caution

10

1) Do pre-function test



※ Caution

11

1) Press the set using jig



※ Caution

- Pressure : 1N
- Time: 1 minute

5. MAIN Electrical Parts List

SEC Code	Design Loc	Description
0403-001972	ZD501	DIODE-ZENER
0406-001413	ZD4001,ZD4002,ZD4004	DIODE-TVS
0406-001413	ZD4005	DIODE-TVS
0406-001446	ZD4008	DIODE-TVS
0406-001514	ZD506,ZD507	DIODE-TVS
0406-001633	ZD4007	DIODE-TVS
0406-001645	ZD4003,ZD4006,ZD502	DIODE-TVS
0406-001645	ZD503,ZD601,ZD602	DIODE-TVS
0406-001645	ZD603	DIODE-TVS
0406-001675	ZD4000,ZD508	DIODE-TVS
0406-001687	ZD4011,ZD4012	DIODE-TVS
0504-001171	TR402	TR-DIGITAL
0505-003234	Q600	FET-SILICON
0601-003477	LED4000	LED
1001-001841	U4003	FET-SILICON
1001-001928	U501	IC
1003-002415	U504	IC
1108-000573	UME500	MEMORY
1201-003786	U200	IC
1201-003859	PAM100	IC
1201-003860	PAM101	IC
1201-003861	PAM102	IC
1201-003876	U4004	IC
1203-007324	U610	IC
1203-007513	U601	IC
1203-007790	U604,U605	IC
1203-007791	U606	IC
1203-007796	U505,U603	IC
1203-007842	U608,U609	IC
1203-008167	U4002	IC
1203-008324	PM4000	IC
1203-008379	U1006	IC
1203-008431	U607	IC
1203-008436	U4000	IC
1205-005079	U104	IC
1205-005106	U4001	IC
1205-005142	U201	IC
1205-005213	UCP301	IC
1209-002204	U203	IC
1209-002299	U502	IC

1404-001724	TH100,TH300	THERMISTOR
1405-001177	VR606,VR607,VR608	VARISTOR
1405-001177	VR609,VR610,VR611	VARISTOR
1405-001371	VR601,VR602,VR603	VARISTOR
1405-001371	VR604,VR605	VARISTOR
1405-001390	VR1000,VR1001,VR4002	VARISTOR
1405-001390	VR4003,VR4004,VR4005	VARISTOR
2007-000173	R551	R-CHIP
2007-001284	R4046,R4049	R-CHIP
2007-001306	R4021	R-CHIP
2007-003015	R4031,R4032	R-CHIP
2007-007107	R341	R-CHIP
2007-007156	R4020	R-CHIP
2007-007315	R300	R-CHIP
2007-007318	R4027	R-CHIP
2007-007589	R105	R-CHIP
2007-008045	R4024,R503,R505	R-CHIP
2007-008052	R347,R602	R-CHIP
2007-008055	R353	R-CHIP
2007-008210	R100,R330	R-CHIP
2007-008312	R506	R-CHIP
2007-008419	R4028,R609,R610,R611	R-CHIP
2007-008483	R4008	R-CHIP
2007-008516	R303,R304,R313,R314	R-CHIP
2007-008516	R338,R339,R340,R348	R-CHIP
2007-008516	R4025,R4026,R4036	R-CHIP
2007-008516	R4041,R4042,R4047	R-CHIP
2007-008516	R4050,R508,R526,R541	R-CHIP
2007-008516	R600,R613,R614,R621	R-CHIP
2007-008516	R622,R623,R625,R626	R-CHIP
2007-008516	R635,R638,R641,R643	R-CHIP
2007-008531	R4030	R-CHIP
2007-008582	R101,R102	R-CHIP
2007-008588	R301,R302,R306,R307	R-CHIP
2007-008588	R308,R309,R311,R312	R-CHIP
2007-008588	R317,R318,R355,R356	R-CHIP
2007-008588	R357,R358,R361,R362	R-CHIP
2007-008588	R4038,R4039	R-CHIP
2007-008788	R328	R-CHIP
2007-008806	R103,R111	R-CHIP
2007-009084	R334,R615	R-CHIP

2007-009111	R547	R-CHIP
2007-009155	R504	R-CHIP
2007-009157	R4007	R-CHIP
2007-009158	R4048	R-CHIP
2007-009170	R4019	R-CHIP
2007-009223	R4040	R-CHIP
2007-009793	R4045	R-CHIP
2007-009838	R4022	R-CHIP
2007-009866	R540	R-CHIP
2007-009920	R310,R522,R531	R-CHIP
2007-010856	R4023	R-CHIP
2007-011043	R305	R-CHIP
2203-000725	C545	C-CERAMIC,CHIP
2203-005344	C280	C-CERAMIC,CHIP
2203-005552	C231	C-CERAMIC,CHIP
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2203-007449	C661,C664	C-CERAMIC,CHIP
2203-007474	C201,C213,C219,C4037	C-CERAMIC,CHIP

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2203-007781	C620,C646,C650	C-CERAMIC,CHIP
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2203-007796	C4070,C4072,C4084	C-CERAMIC,CHIP
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2203-008094	C4073	C-CERAMIC,CHIP
2203-008097	C381,C382	C-CERAMIC,CHIP
2203-008243	C202,C203,C204,C207	C-CERAMIC,CHIP
2203-008243	C210,C215,C216	C-CERAMIC,CHIP
2203-008312	C200	C-CERAMIC,CHIP
2203-008394	C600	C-CERAMIC,CHIP
2203-008470	C538,C601	C-CERAMIC,CHIP
2203-008527	C114	C-CERAMIC,CHIP
2203-008654	C4078,C4086	C-CERAMIC,CHIP
2203-009223	C1085,C1106,C1107	C-CERAMIC,CHIP
2203-009223	C1149	C-CERAMIC,CHIP
2203-009276	C244,C245	C-CERAMIC,CHIP
2703-002649	L103,L118,L130	INDUCTOR-SMD
2703-002901	L120,L133	INDUCTOR-SMD
2703-002903	L124,L129	INDUCTOR-SMD
2703-002953	L106,L107	INDUCTOR-SMD
2703-002958	L1004,L1193,L214	INDUCTOR-SMD
2703-002961	L138	INDUCTOR-SMD
2703-003121	L4021	INDUCTOR-SMD
2703-003878	L4019	INDUCTOR-SMD
2703-004013	L102,L104	INDUCTOR-SMD
2703-004014	L110	INDUCTOR-SMD
2703-004034	L117,L1204,L209	INDUCTOR-SMD
2703-004035	L100,L101,L208	INDUCTOR-SMD
2703-004037	L111	INDUCTOR-SMD
2703-004259	L1032	INDUCTOR-SMD
2703-004286	L127	INDUCTOR-SMD
2703-004328	L108,L113,L128	INDUCTOR-SMD
2703-004332	L601	INDUCTOR-SMD
2703-004366	L205	INDUCTOR-SMD
2703-004367	L131	INDUCTOR-SMD
2703-004775	L4000,L503	INDUCTOR-SMD
2703-004786	L4013	INDUCTOR-SMD
2703-004862	L204	INDUCTOR-SMD
2703-005007	L602	INDUCTOR-SMD

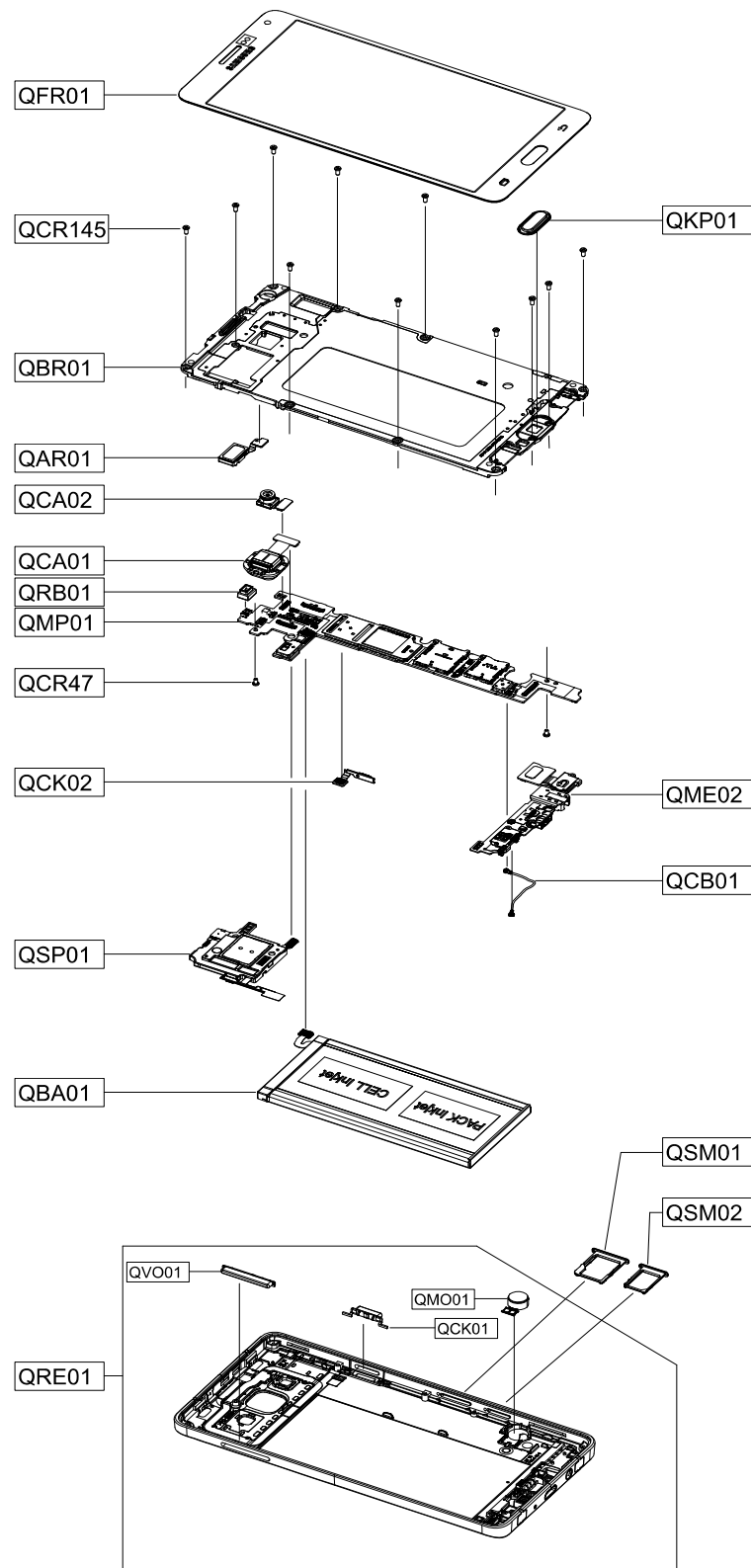
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2703-005066	L4010	INDUCTOR-SMD
2703-005069	L606	INDUCTOR-SMD
2703-005106	L1162	INDUCTOR-SMD
2703-005109	L4001	INDUCTOR-SMD
2703-005136	L4009	INDUCTOR-SMD
2801-005390	OSC4000	CRYSTAL-SMD
2801-005397	OSC200	CRYSTAL-SMD
2901-001635	F4000,F601,F602,F604	FILTER-EMI SMD
2901-001635	F605,F607	FILTER-EMI SMD
2901-001756	F606	FILTER-EMI SMD
2901-001759	F600,F603	FILTER-EMI SMD
2904-002168	F203	FILTER-SAW
2904-002211	F1005	FILTER-SAW
2904-002215	F100	FILTER-SAW
2909-001307	F200	FILTER-SAW
2910-000229	F102	DUPLEXER-SAW
2910-000296	F104	DUPLEXER-SAW
2910-000320	F103	DUPLEXER-SAW
2910-000321	F105	DUPLEXER-SAW
3301-001659	L201	CORE-FERRITE BEAD
3301-001789	L603,L604,L605	CORE-FERRITE BEAD
3301-001885	L4015,L4017,L4020	CORE-FERRITE BEAD
3301-001885	L504	CORE-FERRITE BEAD
3301-001912	L4011	CORE-FERRITE BEAD
3301-002035	L608,L609	CORE-FERRITE BEAD
3301-002179	L1160,L1161	CORE-FERRITE BEAD
3301-002228	L105	CORE-FERRITE BEAD
3301-002236	L4005,L4006,L4007	CORE-FERRITE BEAD
3301-002237	L505,L506	CORE-FERRITE BEAD
3301-002238	L4008	CORE-FERRITE BEAD
3301-002248	L200	CORE-FERRITE BEAD
3301-002254	L4012	CORE-FERRITE BEAD
3301-002286	L4016,L607	CORE-FERRITE BEAD
3301-002304	L610,L611	CORE-FERRITE BEAD
3705-001708	RFS1000	CONNECTOR-COAXIAL
3705-002014	RFS1001	CONNECTOR-COAXIAL
3709-001859	SIM601	CONNECTOR-CARD EDGE
3709-001860	SIM600	CONNECTOR-CARD EDGE
3711-007295	HDC600	CONNECTOR-HEADER
3711-007332	HDC604	CONNECTOR-HEADER

3711-007617	HDC601	CONNECTOR-HEADER
3711-008010	HDC603	CONNECTOR-HEADER
3711-008511	HDC602	CONNECTOR-HEADER
3711-008593	HDC4000	CONNECTOR-HEADER
3711-008847	BTC500	CONNECTOR-HEADER
3712-001501	ANT204	CONNECTOR
3712-001516	ANT1000,ANT1001	CONNECTOR
3712-001516	ANT1002,ANT1003	CONNECTOR
3712-001516	ANT1004,ANT201	CONNECTOR
3712-001516	ANT500,ANT501	CONNECTOR
3712-001529	ANT504,ANT505	CONNECTOR
4709-002285	F201	CONNECTOR
GH61-08634A	ANT1005	RF-MODULE
GH62-00033A	GT1001	RF-MODULE
GH63-09981A	SUS1000	ANTTENA
GH98-34781A	SC1005	SHIELD CAN
GH98-34782A	SC1000	SHIELD CAN
GH98-34783A	SC1001	SHIELD CAN
GH98-34784A	SC1006	SHIELD CAN
GH98-34785A	SC1002	SHIELD CAN
GH98-34786A	SC1003	SHIELD CAN
GH98-34787A	SC1004	SHIELD CAN
GH98-35948A	SC1007	SHIELD CAN

Please consult the GSPN website (Samsung Portal) for the most recent version of the product's part list.

4. Exploded View and Parts List

4-1. Cellular phone Exploded View



2. Specification

2-1. GSM General Specification

	GSM850 Phase 1	EGSM 900 Phase 2	DCS1800 Phase 1	PCS1900
Freq. Band[MHz] Uplink/Downlink	824~849 869~894	880~915 925~960	1710~1785 1805~1880	1850~1910 1930~1990
ARFCN range	128~251	0~124 & 975~1023	512~885	512~810
Tx/Rx spacing	45MHz	45MHz	95MHz	80MHz
Mod. Bit rate/ Bit Period	270.833kbps 3.692us	270.833kbps 3.692us	270.833kbps 3.692us	270.833kbps 3.692us
Time Slot Period/Frame Period	576.9us 4.615ms	576.9us 4.615ms	576.9us 4.615ms	576.9us 4.615ms
Modulation	0.3GMSK	0.3GMSK	0.3GMSK	0.3GMSK
MS Power	33dBm~5dBm	33dBm~5dBm	30dBm~0dBm	30dBm~0dBm
Power Class	5pcl ~ 19pcl	5pcl ~ 19pcl	0pcl ~ 15pcl	0pcl ~ 15pcl
Sensitivity	-102dBm	-102dBm	-100dBm	-100dBm
TDMA Mux	8	8	8	8
Cell Radius	35Km	35Km	2Km	2Km

2-1. GSM General Specification

	WCDMA2100 (Band I)	WCDMA1900 (Band II)	WCDMA850 (Band V)	WCDMA900 (Band VIII)
Freq. Band[MHz] Uplink/Downlink	1922~1977 2110~2170	1852~1907 1932~1987	824~849 869~894	880~915 925~960
ARFCN range	UL:9612~9888 DL:10562~10838	UL:9262~9538 DL:9662~9938	UL: 4132~4233 DL: 4357~4458	UL: 2712~2863 DL: 2937~3088
Tx/Rx spacing	190MHz	80MHz	45MHz	45MHz
Mod. Bit rate/ Bit Period	3.84Mcps	3.84Mcps	3.84Mcps	3.84Mcps
Time Slot Period/Frame Period	FrameLength: 10ms Slotlength: 0.667ms	FrameLength: 10ms Slotlength: 0.667ms	FrameLength: 10ms Slotlength: 0.667ms	FrameLength: 10ms Slotlength: 0.667ms
Modulation	QPSK, HPSK	QPSK, HPSK	QPSKHQPSK	QPSKHQPSK
MS Power	24dBm~-50dBm	24dBm~-50dBm	24dBm~- 50dBm	24dBm~- 50dBm
Power Class	3(max+24dBm)	3(max+24dBm)	3(max+24dBm)	3(max+24dBm)
Sensitivity	-106.7dBm	-106.7dBm	-106.7dBm	-106.7dBm
TDMA Mux	8	8	8	8
Cell Radius	2Km	2Km	2Km	2Km

2-2. GSM Tx Power Class

TX Power control level	GSM850	TX Power control level	EGSM900	TX Power control level	DCS1800	TX Power control level	PCS1900
5	33±2 dBm	5	33±2 dBm	0	30±3 dBm	0	30±3 dBm
6	31±2 dBm	6	31±2 dBm	1	28±3 dBm	1	28±3 dBm
7	29±2 dBm	7	29±2 dBm	2	26±3 dBm	2	26±3 dBm
8	27±2 dBm	8	27±2 dBm	3	24±3 dBm	3	24±3 dBm
9	25±2 dBm	9	25±2 dBm	4	22±3 dBm	4	22±3 dBm
10	23±2 dBm	10	23±2 dBm	5	20±3 dBm	5	20±3 dBm
11	21±2 dBm	11	21±2 dBm	6	18±3 dBm	6	18±3 dBm
12	19±2 dBm	12	19±2 dBm	7	16±3 dBm	7	16±3 dBm
13	17±2 dBm	13	17±2 dBm	8	14±3 dBm	8	14±3 dBm
14	15±2 dBm	14	15±2 dBm	9	12±4 dBm	9	12±4 dBm
15	13±2 dBm	15	13±2 dBm	10	10±4 dBm	10	10±4 dBm
16	11±3 dBm	16	11±3 dBm	11	8±4 dBm	11	8±4 dBm
17	9±3dBm	17	9±3dBm	12	6±4 dBm	12	6±4 dBm
18	7±3 dBm	18	7±3 dBm	13	4±4 dBm	13	4±4 dBm
19	5±3 dBm	19	5±3 dBm	14	2±5 dBm	14	2±5 dBm
				15	0±5 dBm	15	0±5 dBm

3. Operation Instruction and Installation

Main Function

- Android OS: Kitkat 4.4.2
- Qualcomm MSM8239 (1.5 Ghz)
- 2G Quad (850/900/1800/1900)
- 3G Quad (2100/1900/850/900)
- 2 Gbit RAM + 16GB eMMC
- 13.0 MP Main CAM + 5.0 MP Sub CAM
- 5.5" 1920X1080 FHD OLED
- A-GPS / BT 4.0 / USB v2.0 / WiFi (802.11 a/b/g/n)
- 2600 mAh Battery
- Sensors: Accelerometer, Geomagnetic Sensor, Light Sensor, Proximity Sensor
- Additional :
 - Samsung Wearable Device Support\
 - Charger 5V/1.55A
 - Data Cable : 3.3pi, 1m
 - Ear Phone : 3.5pi, 4pin

9. Reference Abbreviate

Reference Abbreviate

- **AAC**: Advanced Audio Coding.
- **AVC** : Advanced Video Coding.
- **BER** : Bit Error Rate
- **BPSK**: Binary Phase Shift Keying
- **CA** : Conditional Access
- **CDM** : Code Division Multiplexing
- **C/I** : Carrier to Interference
- **DMB** : Digital Multimedia Broadcasting
- **EN** : European Standard
- **ES** : Elementary Stream
- **ETSI**: European Telecommunications Standards Institute
- **MPEG**: Moving Picture Experts Group
- **PN** : Pseudo-random Noise
- **PS** : Pilot Symbol
- **QPSK**: Quadrature Phase Shift Keying
- **RS** : Reed-Solomon
- **SI** : Service Information
- **TDM** : Time Division Multiplexing
- **TS** : Transport Stream

1. Safety Precautions

1-1. Repair Precaution

Before attempting any repair or detailed tuning, shield the device from RF noise or static electricity discharges.

Use only demagnetized tools that are specifically designed for small electronic repairs, as most electronic parts are sensitive to electromagnetic forces.

Use only high quality screwdrivers when servicing products. Low quality screwdrivers can easily damage the heads of screws.

Use only conductor wire of the properly gauge and insulation for low resistance, because of the low margin of error of most testing equipment.

We recommend 22-gauge twisted copper wire.

Hand-soldering is not recommended, because printed circuit boards (PCBs) can be easily damaged, even with relatively low heat. Never use a soldering iron with a power rating of more than 100 watts and use only lead-free solder with a melting point below 250°C (482°F).

Prior to disassembling the battery charger for repair, ensure that the AC power is disconnected. Always use the replacement parts that are registered in the SEC system. Third-party replacement parts may not function properly.

1-2. ESD(Electrostatically Sensitive Devices) Precaution

Many semiconductors and ESDs in electronic devices are particularly sensitive to static discharge and can be easily damaged by it. We recommend protecting these components with conductive anti-static bags when you store or transport them.

Always use an anti-static strap or wristband and remove electrostatic buildup or dissipate static electricity from your body before repairing ESDs.

Ensure that soldering irons have AC adapter with ground wires and that the ground wires are properly connected.

Use only desoldering tools with plastic tips to prevent static discharge.

Properly shield the work environment from accidental electrostatic discharge before opening packages containing ESDs.

The potential for static electricity discharge may be increased in low humidity environments, such as air-conditioned rooms. Increase the airflow to the working area to decrease the chance of accidental static electricity discharges.

6. Level 1 Repair

6-1. S/W installation

6-1-1. Required items in order to install S/W

- Installation program: Downloader Program (**Odin3 v3.09.exe with odin3.ini**)
- SM-A700H Mobile Phone
- Data Cable (GH39-01681A)
- JIG BOX (GH81-11888A)
- JIG Cable (GH81-10623A)
- Adapter (GH81-11888K)
- Serial Cable
- Mobile device specific S/W: Binary files

※ Settings



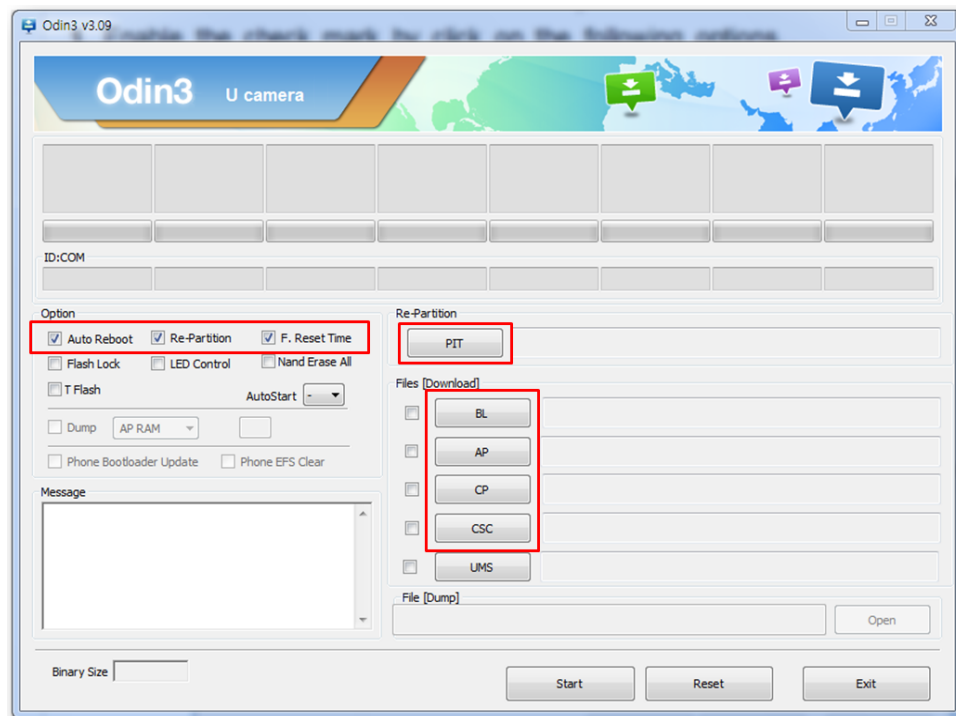
Connect ANYWAY JIG BOX
with JIG CABLE (Phone to JIG)
or PC to Phone Using Data Cable



6-2-2. S/W Installation Program (Downloader program)

- Open up the S/W Installation Program by executing the **"Odin3 v3.09.exe"**
("odin3.ini" file should be in the same folder with odin3 v3.09.exe)

1. Enable the check mark by click on the following options,
 - Check Re-Partition, Auto Reboot, and F. Reset Time
 - Check PIT
 - Check BL,AP,CP and CSC Files

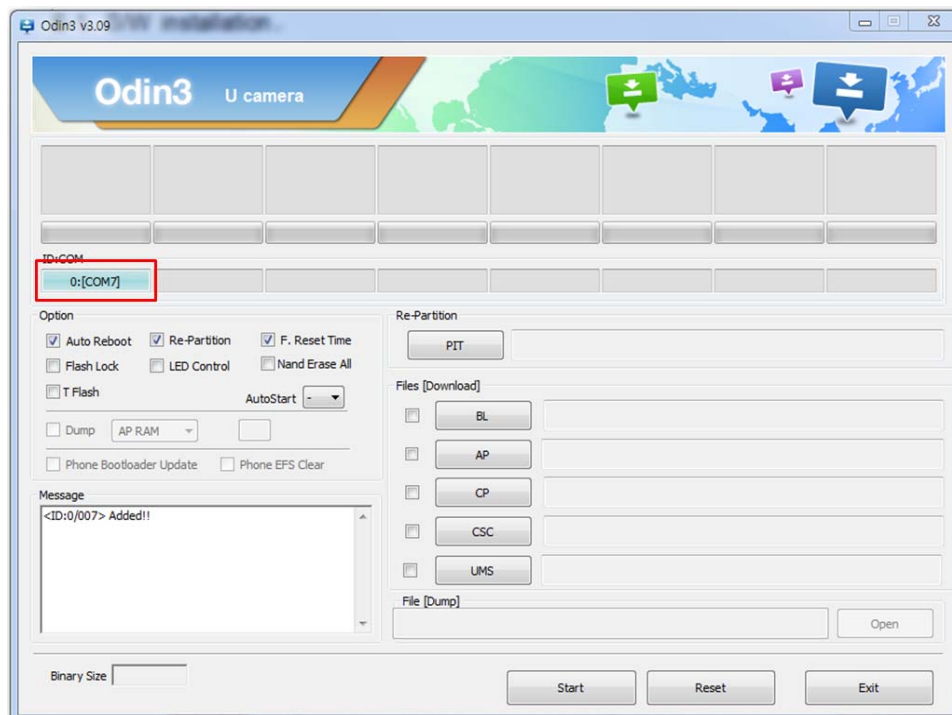


2. Enter into Download Mode

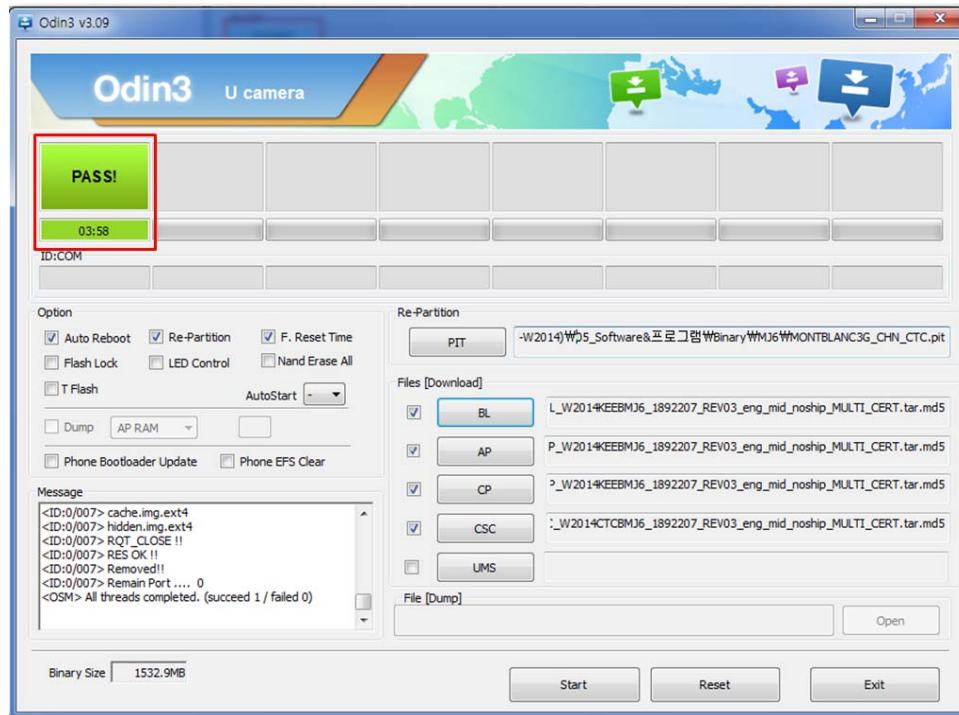
- ① Enter into Download Mode by pressing Volume Down button and ON/OFF Button simultaneously.
- ② Next, press Volume Up button.

3. Connect the device to PC via Data Cable.

Make sure that the one of communication port [ID:COM] box is highlighted in yellow. The device is now connected with the PC and ready to download the binary file into the device.



4. Start downloading binary file into the device by clicking Start Button on the screen. the green colored "PASS!" sign will appear on the upper-left box if the binary file has been successfully downloaded into the device.



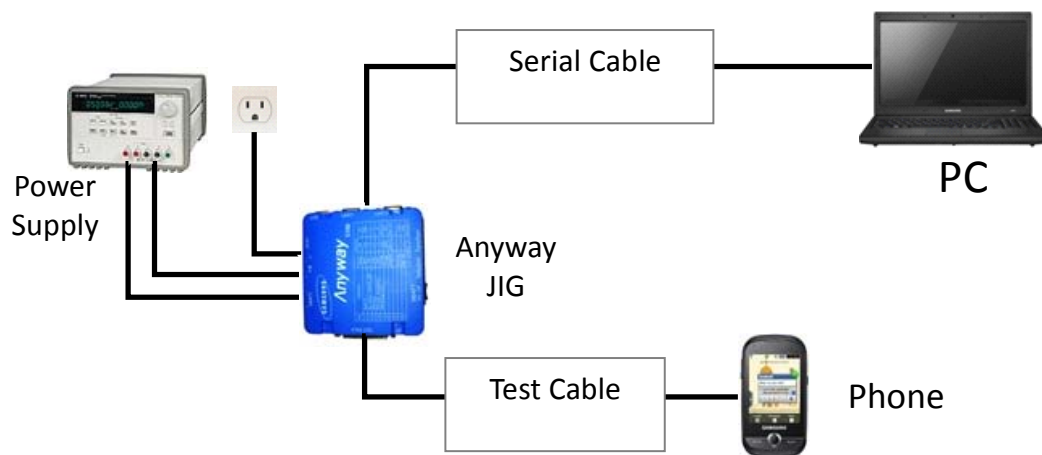
5. Disconnect the device from the Data cable.
6. Once the device boots up, you can check the version of the binary file or name by pressing the following code in sequence;
***#1234#**

6-2 IMEI writing

6-2-1 Preparation

- New IMEI writing Program has been released.
- Supported Model : Models which CAB files are uploaded on HHPsvc INI File category, instead of ini file.
- Refer to below IMEI writing procedure.

- H/W

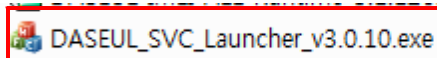


- S/W

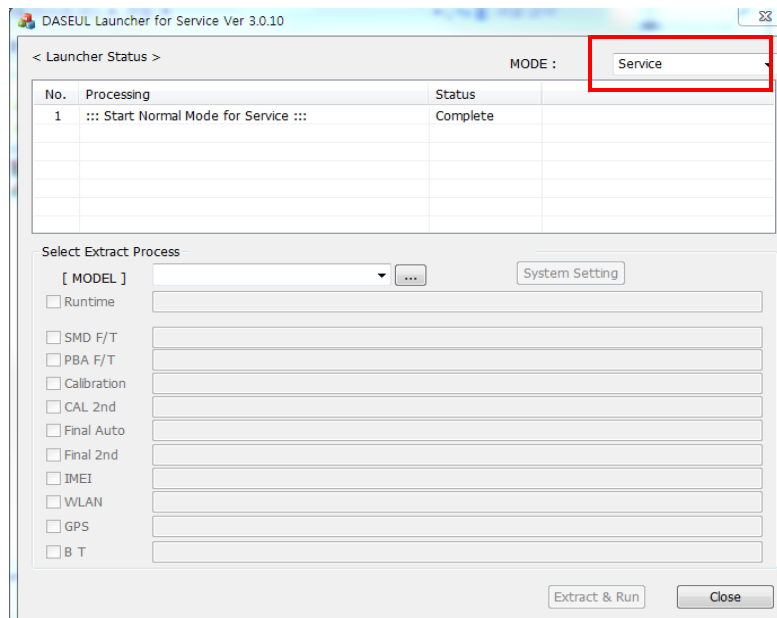
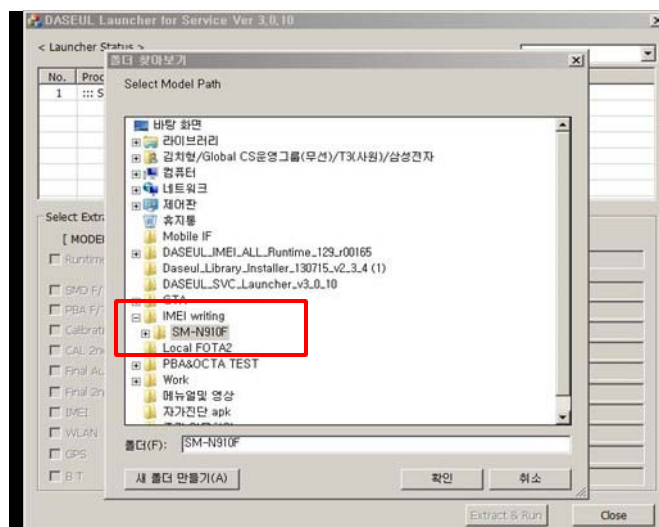
① Library Install	To use Daseul, library files should be installed. Refer to SVC Bulletin “(11-82) Daseul (New IMEI writing Program) Library Install guide_rev1.0”
② Launcher	DASEUL_SVC_Launcher_v3_0_10 or higher -Uploaded on HHPsvc Notice
③ Runtime File	1. DASEUL_IMEI_ALL_Runtime_129_r00165 .CAB or higher -Uploaded on HHPsvc Notice 2. Make 'ModelName' folder at the same position with launcher & Runtime file. SM-A700H DASEUL_IMEI_ALL_Runtime_3,1,129,0,.. DASEUL_SVC_Launcher_v3,0,10,exe
④ Model File	Copy Model File under the 'Model Name' folder

6-2-2 IMEI writing Process

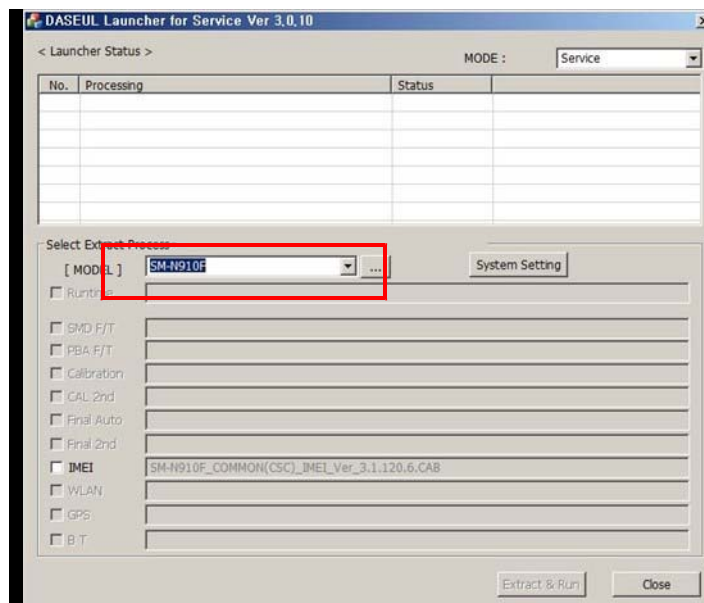
1. Run DASEUL_SVC_Launcher_v3.0.10.exe



2. Select Service Mode

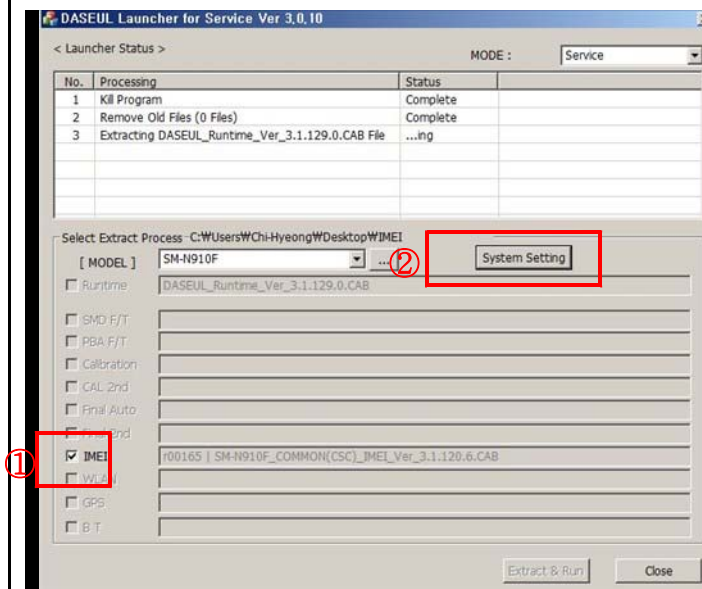
3. Click and Select folder where the Launcher exists

4. Select Model

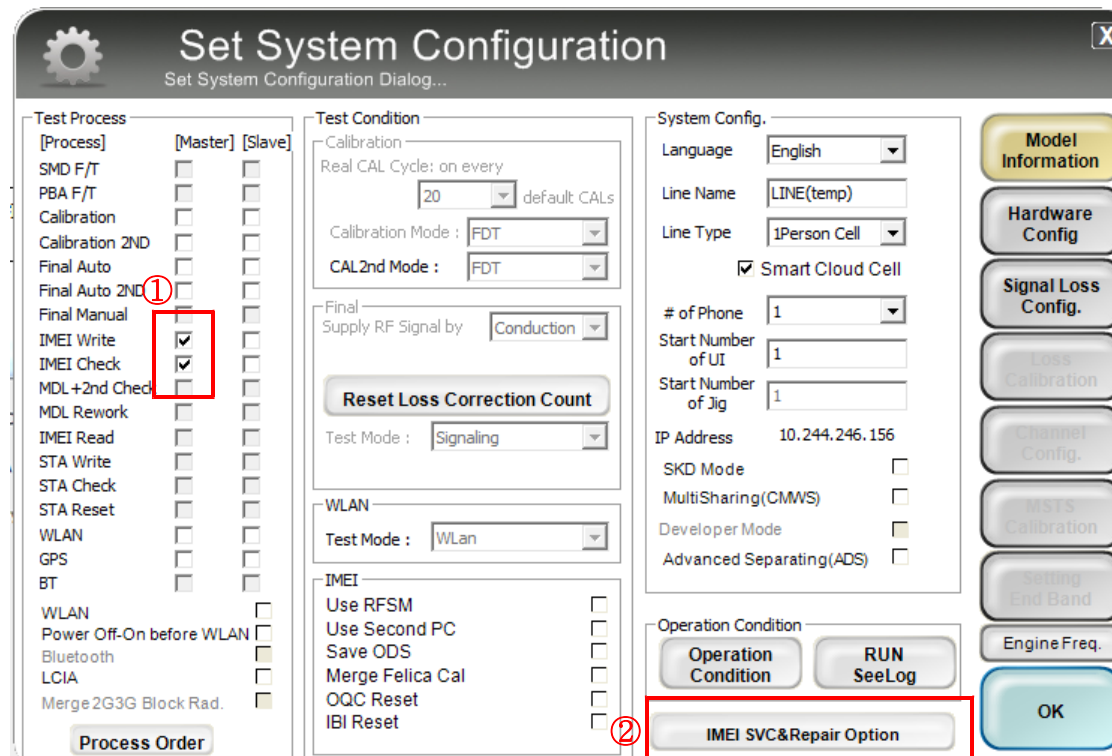


5. Check IMEI and click 'System Setting'

※Once you setup the setting, you don't have to do it again, unless there is change. From second run of the IMEI program, check IMEI and click 'Extract & Run'.



6. Check 'IMEI Write / IMEI Check', and click 'IMEI SVC & Repair Option'



Set System Configuration
Set System Configuration Dialog...

Test Process

[Process]	[Master]	[Slave]
SMD F/T	☐	☐
PBA F/T	☐	☐
Calibration	☐	☐
Calibration 2ND	☐	☐
Final Auto	☐	☐
Final Auto 2ND	☐	☐
Final Manual	☐	☐
IMEI Write	☒	☐
IMEI Check	☒	☐
MDL +2nd Check	☐	☐
MDL Rework	☐	☐
IMEI Read	☐	☐
STA Write	☐	☐
STA Check	☐	☐
STA Reset	☐	☐
WLAN	☐	☐
GPS	☐	☐
BT	☐	☐
WLAN	☐	☐
Power Off-On before WLAN	☐	☐
Bluetooth	☐	☐
LCIA	☐	☐
Merge 2G3G Block Rad.	☐	☐

Test Condition

Calibration
Real CAL Cycle: on every default CALs

Calibration Mode :

CAL2nd Mode :

Final
Supply RF Signal by

Reset Loss Correction Count

Test Mode :

WLAN
Test Mode :

IMEI
☐ Use RFSM
☐ Use Second PC
☐ Save ODS
☐ Merge Felica Cal
☐ OQC Reset
☐ IBI Reset

System Config.

Language

Line Name

Line Type

☒ Smart Cloud Cell

of Phone

Start Number of UI

Start Number of Jig

IP Address

SKD Mode ☐

MultiSharing(CMWS) ☐

Developer Mode ☐

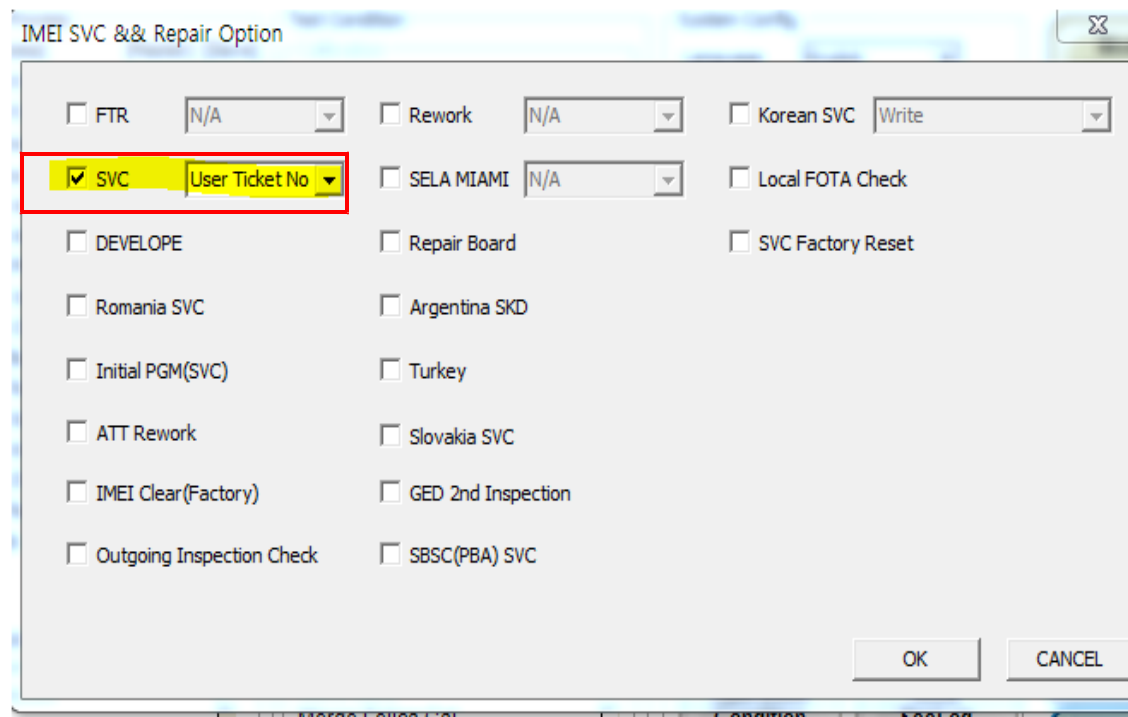
Advanced Separating(ADS) ☐

Operation Condition

IMEI SVC&Repair Option

Model Information

7. Check 'SVC , User Ticket No' and click OK



IMEI SVC & Repair Option

☐ FTR
☐ Rework
☐ Korean SVC

☒ SVC
☐ SELA MIAMI
☐ Local FOTA Check

☐ DEVELOPE
 ☐ Repair Board
 ☐ SVC Factory Reset

☐ Romania SVC
 ☐ Argentina SKD

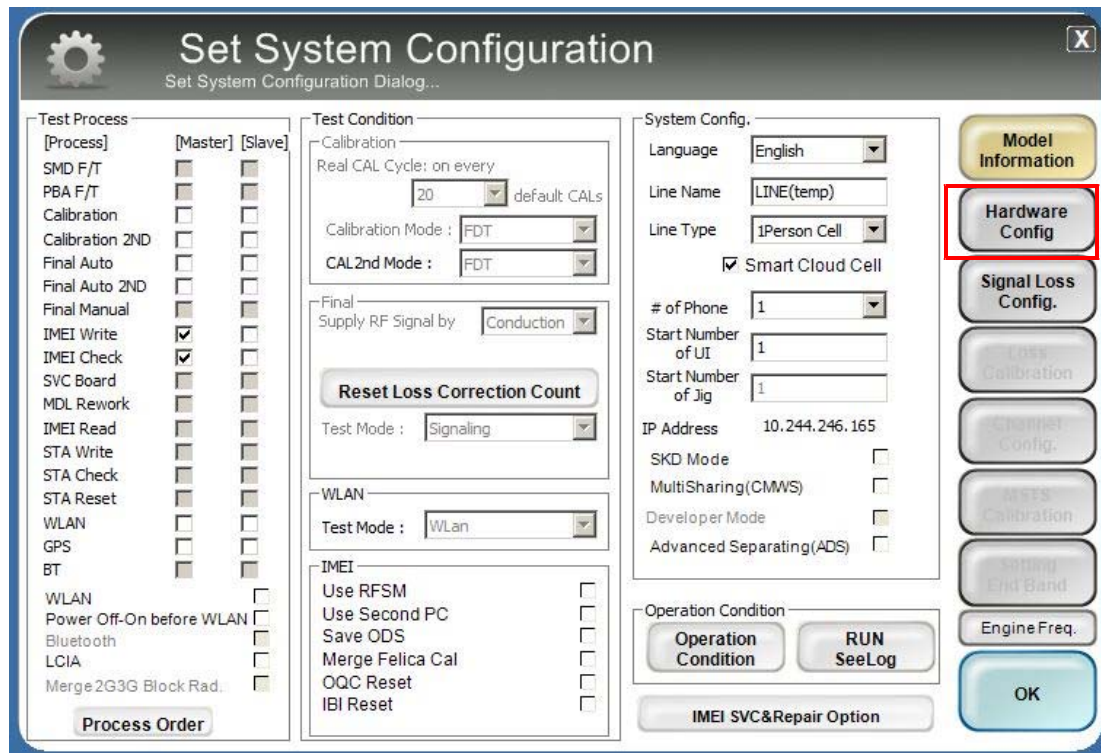
☐ Initial PGM(SVC)
 ☐ Turkey

☐ ATT Rework
 ☐ Slovakia SVC

☐ IMEI Clear(Factory)
 ☐ GED 2nd Inspection

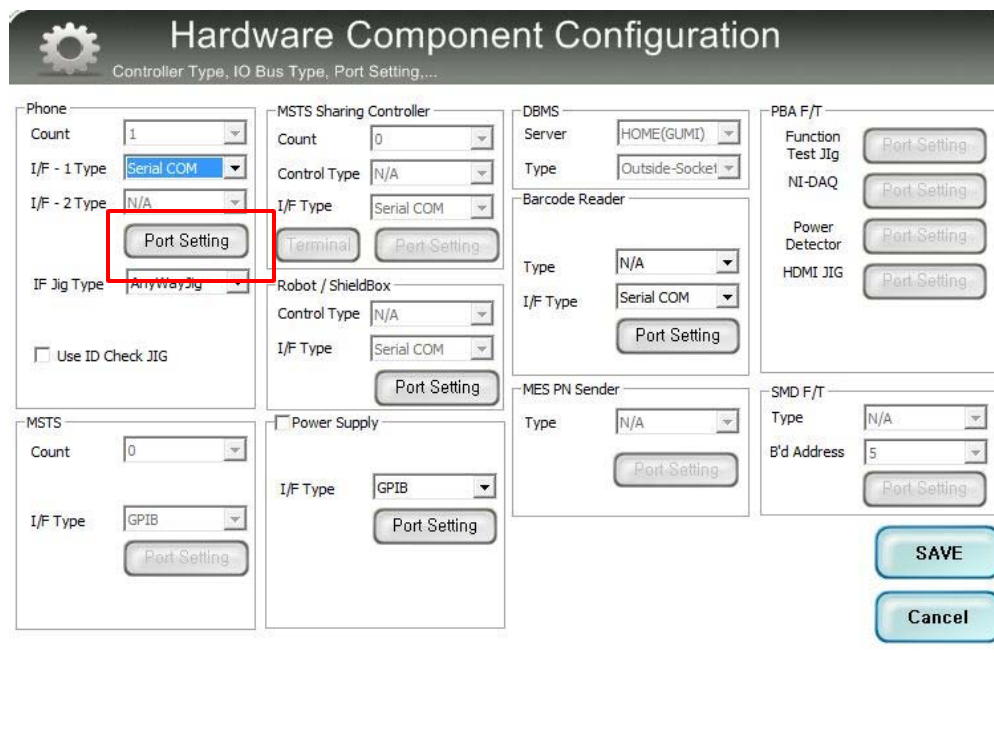
☐ Outgoing Inspection Check
 ☐ SBSC(PBA) SVC

8. Click 'Hardware Config'



The 'Set System Configuration' dialog box is shown. The 'Hardware Config' button is highlighted with a red rectangle. The dialog is divided into several sections: 'Test Process' with checkboxes for various tests; 'Test Condition' with dropdowns for calibration and test modes; 'System Config.' with fields for language, line name, and IP address; and a vertical sidebar on the right with buttons for 'Model Information', 'Hardware Config', 'Signal Loss Config.', 'Loss Calibration', 'Channel Config.', 'MSTC Calibration', 'Setting End Band', and 'Engine Freq.'. At the bottom are 'Operation Condition', 'RUN SeeLog', and 'IMEI SVC&Repair Option' buttons.

9. Click 'Port Setting'



The 'Hardware Component Configuration' dialog box is shown. The 'Port Setting' button for the 'I/F - 1 Type' is highlighted with a red rectangle. The dialog is divided into several sections: 'Phone' with fields for count and I/F types; 'MSTS Sharing Controller' with fields for count, control type, and I/F type; 'DBMS' with fields for server and type; 'Barcode Reader' with fields for type and I/F type; 'MES PN Sender' with fields for type and I/F type; 'SMD F/T' with fields for type and B'd Address; and 'Power Supply' with fields for I/F type. Each section has a 'Port Setting' button. At the bottom are 'SAVE' and 'Cancel' buttons.

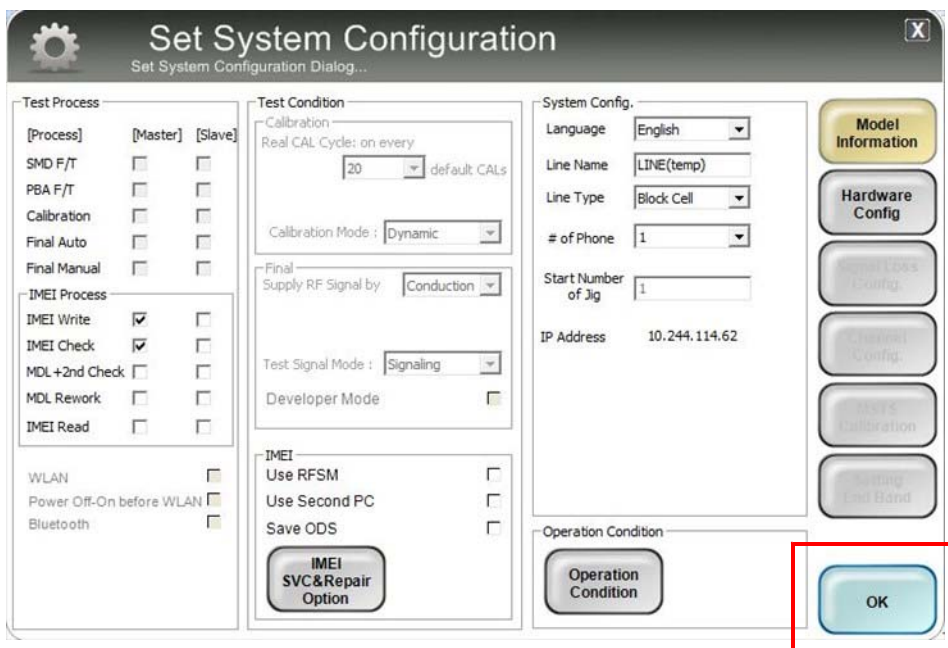
10. Select Port Number and SAVE



The 'Set IO BUS Configuration' dialog box is shown. It has a title bar and a 'Phone IO Bus Setting' section. On the left, under the 'Common' tab, are four settings: BaudRate (115200), Data Bit (8), Parity (No), and Stop Bit (1). On the right, there is a table with two columns: 'No.' and 'Port #1'. The first row shows '1' in the 'No.' column and '1' in the 'Port #1' column. Below the table are two buttons: 'SAVE' and 'Cancel'. Both the 'Port #1' dropdown menu and the 'SAVE' button are highlighted with red rectangles.

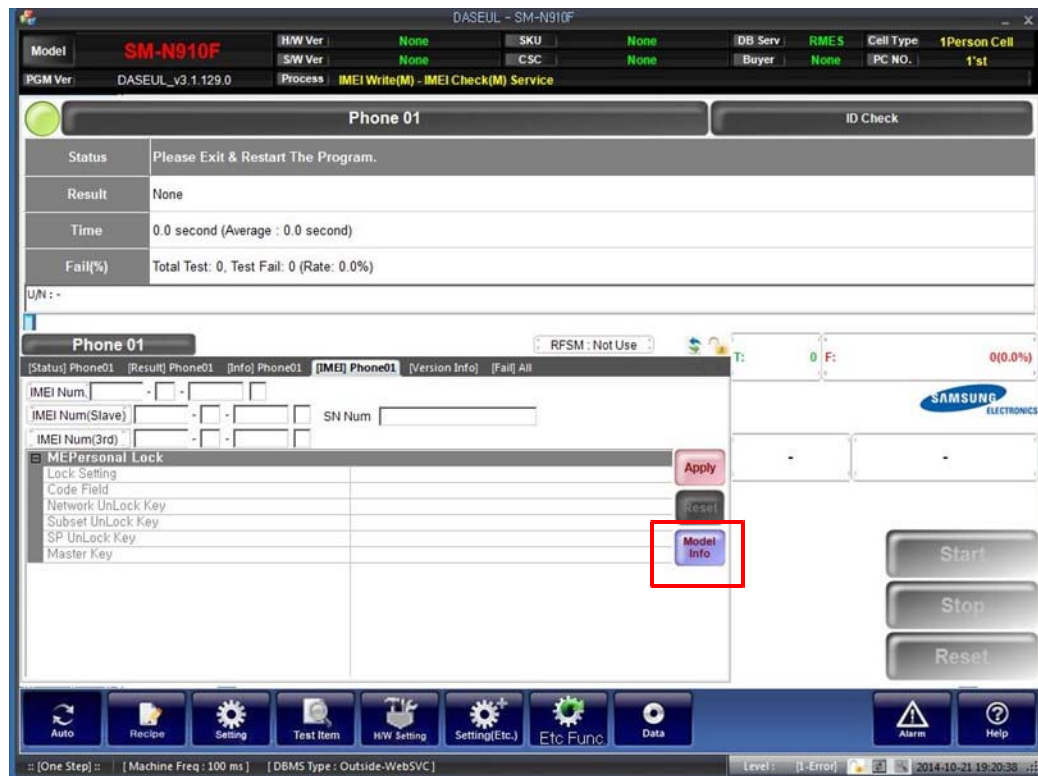
No.	Port #1
1	1

11. Click OK to proceed

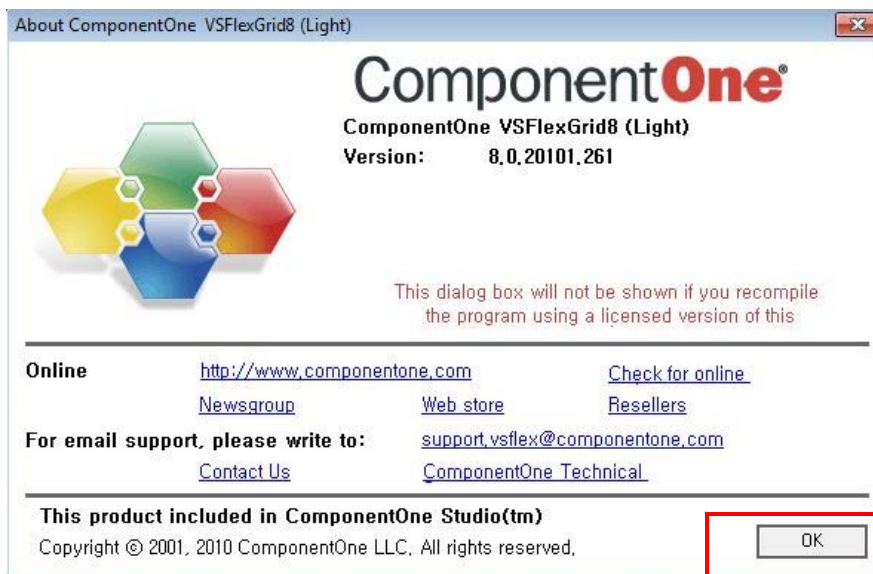


The 'Set System Configuration' dialog box is shown. It has a title bar and a 'Set System Configuration Dialog...' subtitle. The dialog is divided into several sections: 'Test Process' (with checkboxes for SMD F/T, PBA F/T, Calibration, Final Auto, Final Manual, IMEI Process, IMEI Write, IMEI Check, MDL+2nd Check, MDL Rework, IMEI Read, WLAN, Power Off-On before WLAN, and Bluetooth), 'Test Condition' (with dropdowns for Real CAL Cycle, Calibration Mode, Final Supply RF Signal by, and Test Signal Mode, and checkboxes for Developer Mode, IMEI, Use RFSM, Use Second PC, and Save ODS), 'System Config.' (with dropdowns for Language, Line Name, Line Type, and # of Phone, and text fields for Start Number of Jig and IP Address), and 'Operation Condition'. On the right side, there is a vertical stack of buttons: 'Model Information', 'Hardware Config', 'Signal Des Config', 'Channel Config', 'Users Calibration', and 'Setting Red Band'. At the bottom right, there is an 'OK' button highlighted with a red rectangle.

12. Click Model Info and OK when pop-up shows



13. Click OK



14. Input SKU_CODE and BUYER, then click Save button.

※ Refer to HHPsvc→IMEI Review to check SKU Code and buyer

CSC	N098DCM1ANB5
PDA	N098OMU1ANB5
Software2	1
LPD	
Contents	
DMB	
SKU_CODE	SM-A700HXXXXCAC
BUYER	DBT
Material_Code	
Boot	
Factory Software	N098OMU11&NR1

☐ 2nd Func Test (AT&T) ☐ STA Option
☐ FactoryReset+Check ☐ Don't DB Upload ☐ Tizen Download
☐ Pre Product ☐ Packing Rework ☐ Android Download
☐ Main Repair

Save Load Cancel

15. Input IMEI Number and click Apply

Model: SM-N910F HW Ver: None SW Ver: None SKU: None DB Serv: RME-S Cell Type: 1Person Cell
 PGM Ver: DASEUL_V3.1.129.0 Process: IMEI Write(M) - IMEI Check(M) Service

Phone 01 ID Check

Status: Please Exit & Restart The Program.
 Result: None
 Time: 0.0 second (Average : 0.0 second)
 Fail(%): Total Test: 0, Test Fail: 0 (Rate: 0.0%)

UN: -

Phone 01 RFSM: Not Use

IMEI Num: 111111 - 11 - 111111

IMEI Num(Slave): SN Num

IMEI Personal Lock

Lock Setting
 Code Field
 Network UnLock Key
 Subset UnLock Key
 SP UnLock Key
 Master Key

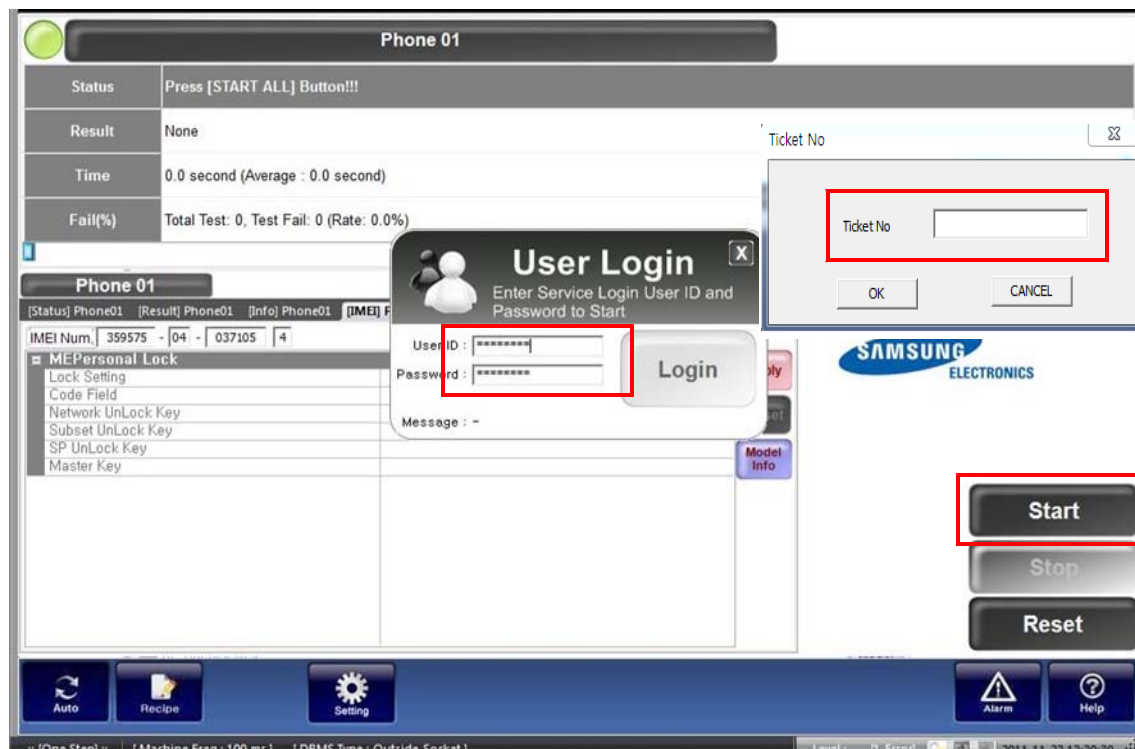
Apply

Start
 Stop
 Reset

Auto Recipe Setting Test Item HW Setting Setting(Etc.) Etc Func Data Alarm Help

[One Step] [Machine Freq: 100 ms] [DBMS Type: Outside-WebSVC] Level: [I-Error] 2014-10-21 19:21:38

16. ① Click Start, and input IMEI writing ID and Password → ② input Ticket No

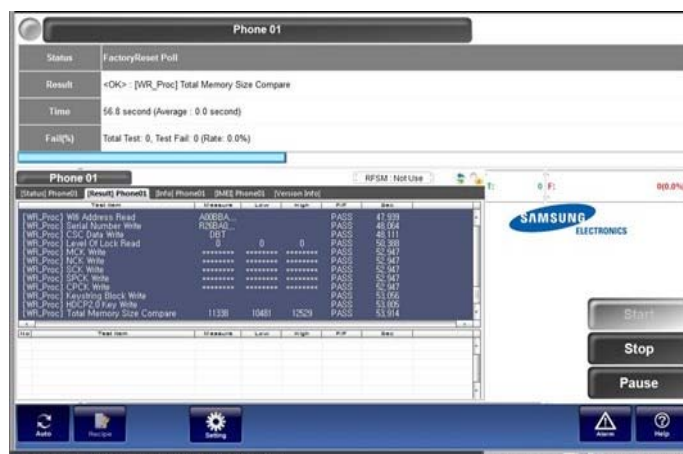


17. Connect the phone to Anyway JIG

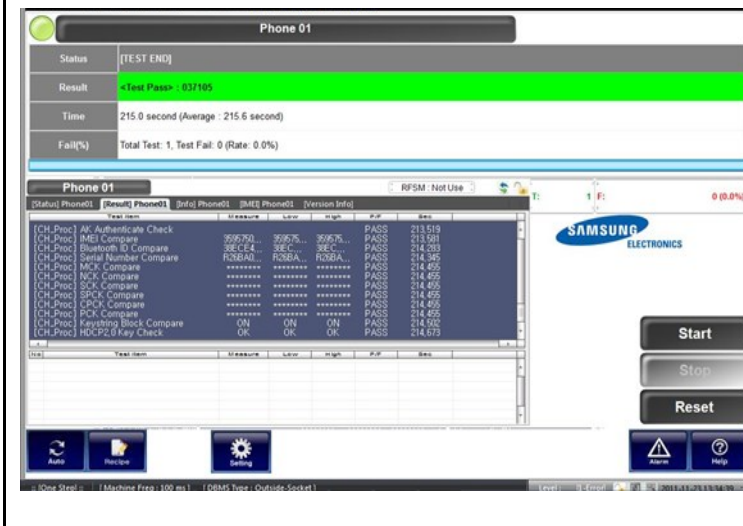
※ When you connect the phone, the phone should be turned off.

After connecting the phone, the phone will be booted automatically.

18. IMEI Writing Proceeding



19. IMEI Writing Success



6-3. Boot Recovery

6-3-1. Symptom

- No Power on, Unable to enter download mode.

6-3-2. Coverage

- The device which get damaged for bootloader.

6-3-3. Required items in order to do Boot Recovery

- Downloader Program ([Odin3 v3.09.3.exe](#))
- SM-A700H Mobile Phone(Normal device)
- Data Cable (GH39-01578K)
- Micro SD Card (Higher than SDHC type and 4GB)
- Full S/W binary(pit, BL, AP, CP)
- Recovery pit file and bootloader
 - pit file: A73G_EUR_OPEN.pit
 - boot loader: normal bootloader(BL)

6-3-4. Brief process for Boot Recovery

1. Download recovery pit and bootloader to SD card by using normal device
2. Insert SD card to no power device and try to enter download mode.
3. Download full S/W to the defected device

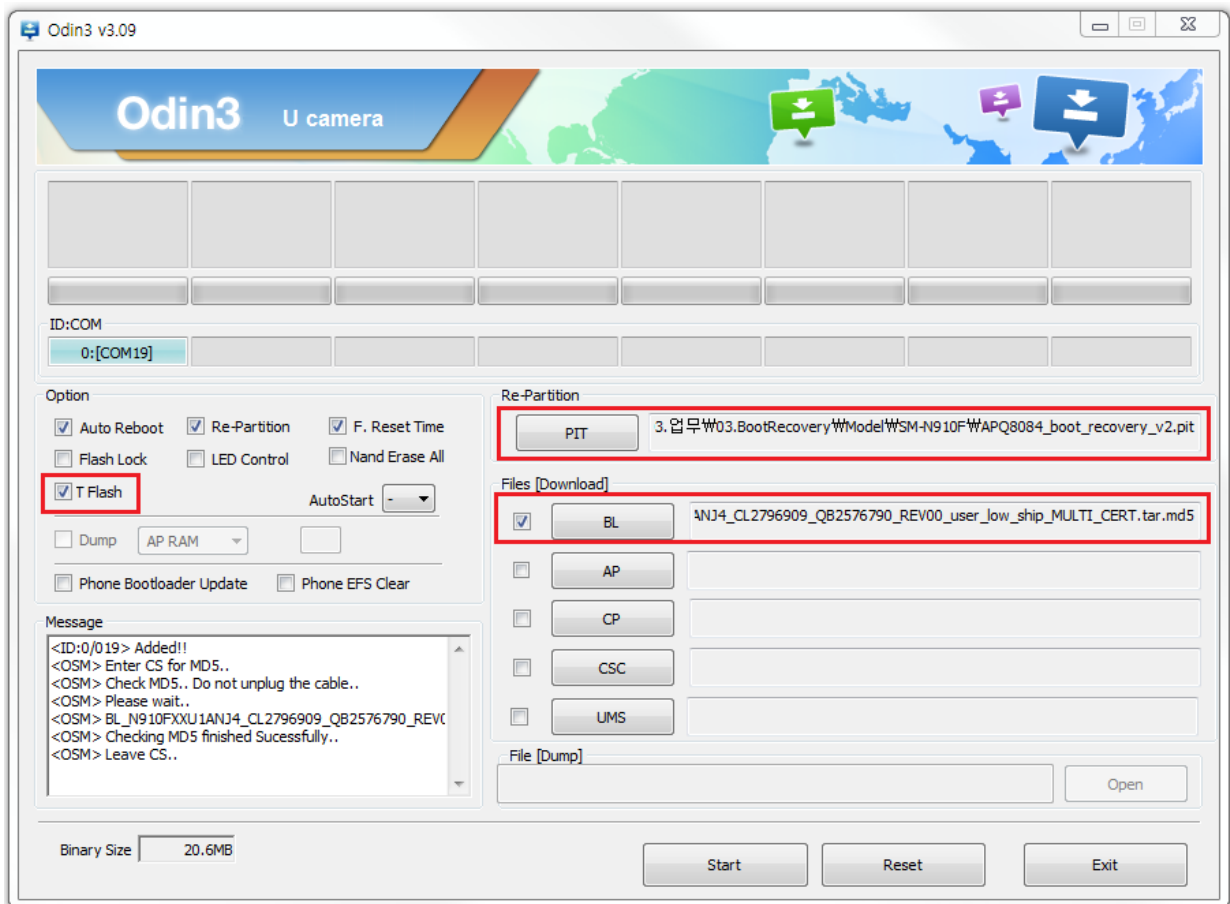
6-3-5. Process of Boot Recovery

1. SW download

- (1) Download full S/W(BL, AP, CP, CSC) to normal device.

2. Make SD card for Recovery

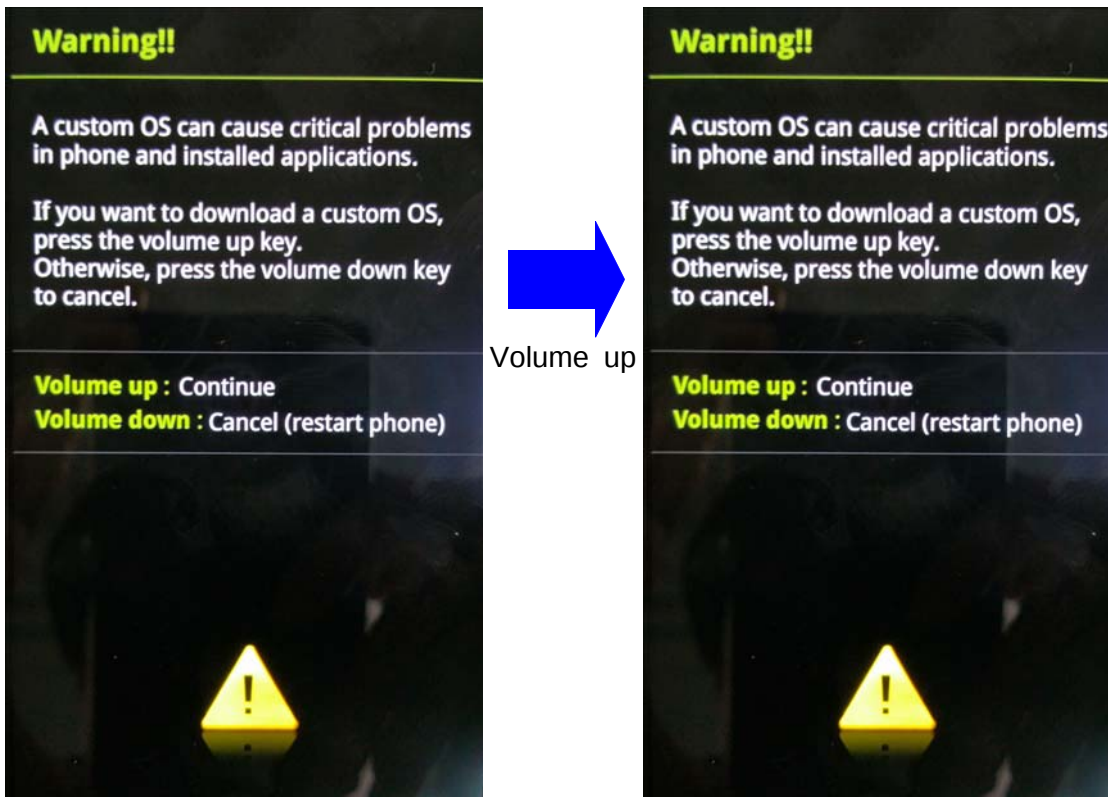
- (1) Run Odin3 v3.09.3 exe
- (2) Load "[A73G_EUR_OPEN.pit](#)" in PIT tap and "[normal bootloader file](#)" in BL tap.
- (3) Check "T-Flash" option
- (4) Insert SD card to normal device and enter to download mode.
- (5) Connect the device to PC



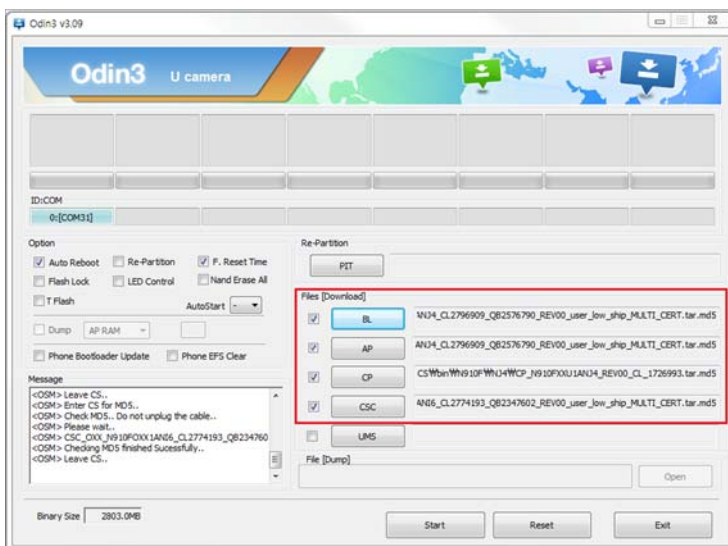
- (6) Click "Start" button to download Recovery pit and bootloader files to SD card.
 - If it is **Pass**, SD card has successfully made for boot recovery.
 - If it is **Fail**, try to this with another SD card.(It would be defect of SD card)

3. Boot Recovery for damaged device

- (1) Insert SD card to "No power" device
- (2) Enter to download mode, using key combination(Volume down + Home + Power)
- (3) If the device is successfully recovered, the device will enter download mode.



- (4) After entering download mode, download full S/W to the device including BL(Bootloader), AP(Platform binary), CP(Modem binary) and CSC.



6-4. RF Calibration

6-1-1. Required items in order to calibrate RF

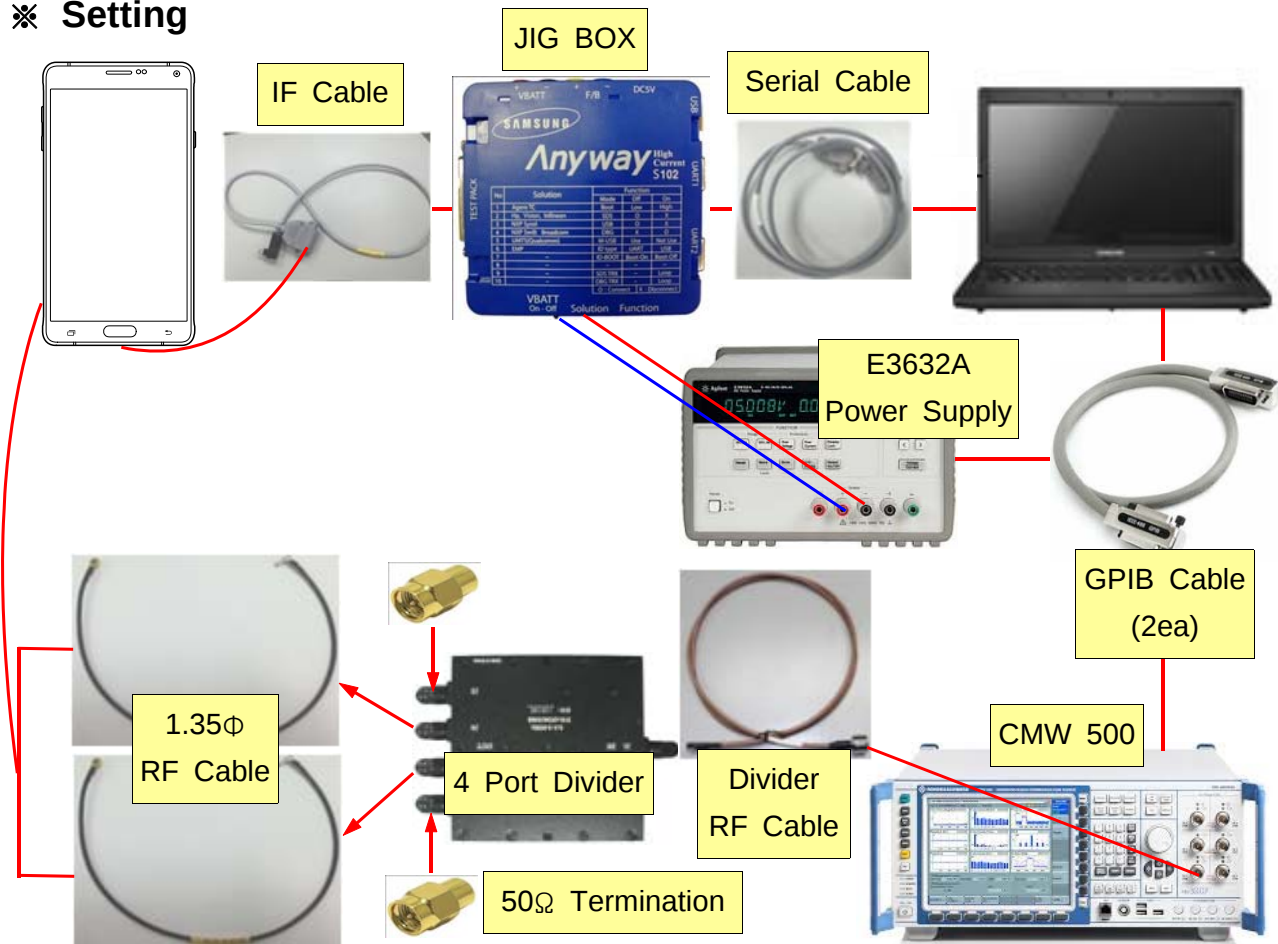
- Installation program: RF Calibration Program

- Daseul_Launcher_vx.x.xx.exe
- Daseul_CAL_ALL_Runtime_x.x.xxx.x.CAB
- Model File (SM-A700FD_OPEN_CALIBRATION_VER_x.x.xxx.xx.CAB)

※ It is required to use the latest program.

- SM-A700H Mobile Phone
- E3632A Power Supply
- JIG BOX (GH81-11888A)
- Adapter (GH81-11888K)
- 4 Port Divider (GH81-11962A)
- 1.35Φ RF Cable (GH81-11962D, 2ea)
- R&S CMW500
- GPIB Cable (2ea)
- IF Cable (GH81-10623A)
- UART Serial Cable
- 50Ω Termination (GH81-11962E, 2ea)
- Divider RF Cable (GH81-11962B)

※ Setting

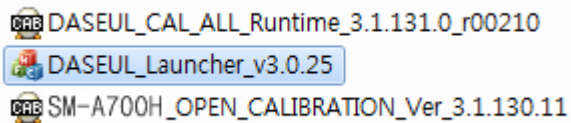


- Table of test cables

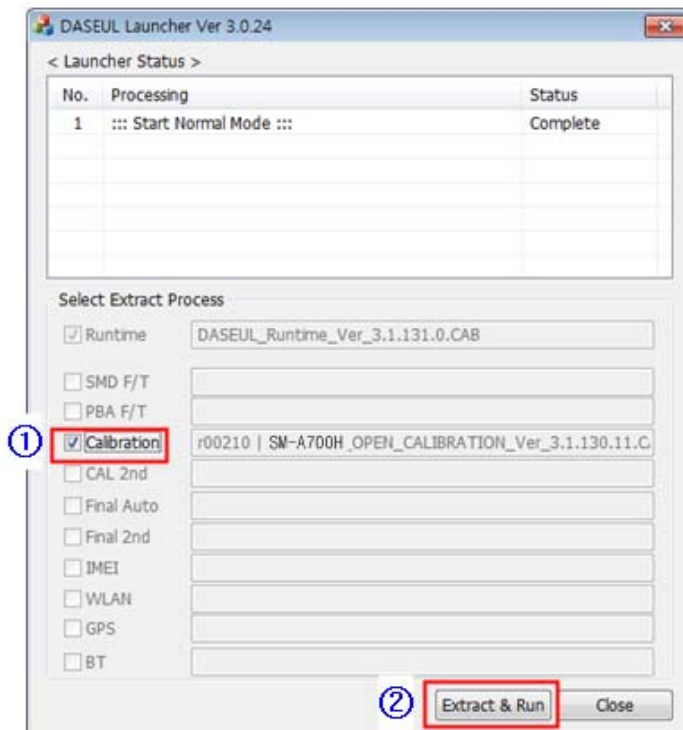
IF Cable	GH81-10623	GH81-10952A	GH81-11171A	
	11 pin	7 pin (New)	7 pin (Old)	
RF Cable	GH81-11962D	GH81-11962G	GH81-11962C	GH81-11962F
	1.35T, Short	1.35T, Long	1.6T, Short	1.6T, Long
4 Port Divider	GH81-11962A			
	Use			

6-1-2. RF Calibration Program

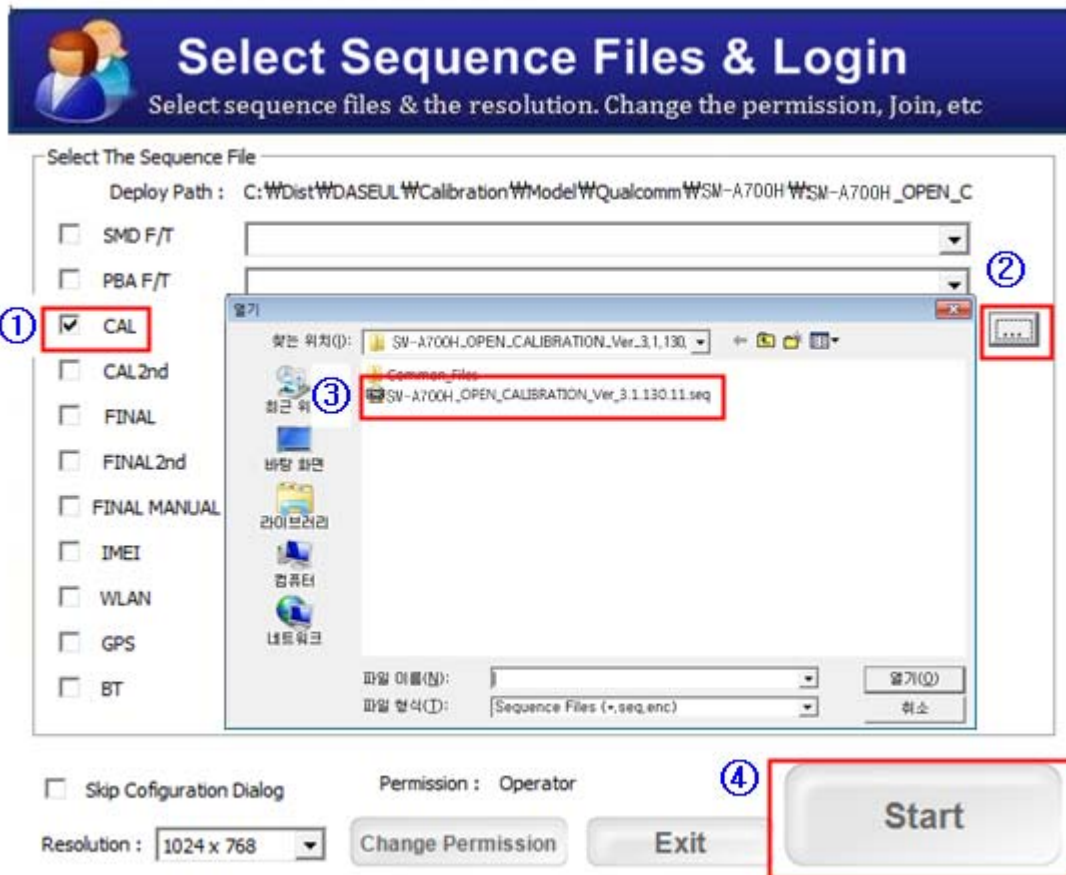
- Run the RF Calibration Program Launcher, '[DASEUL_Launcher_vx.x.xx.exe](#)'.



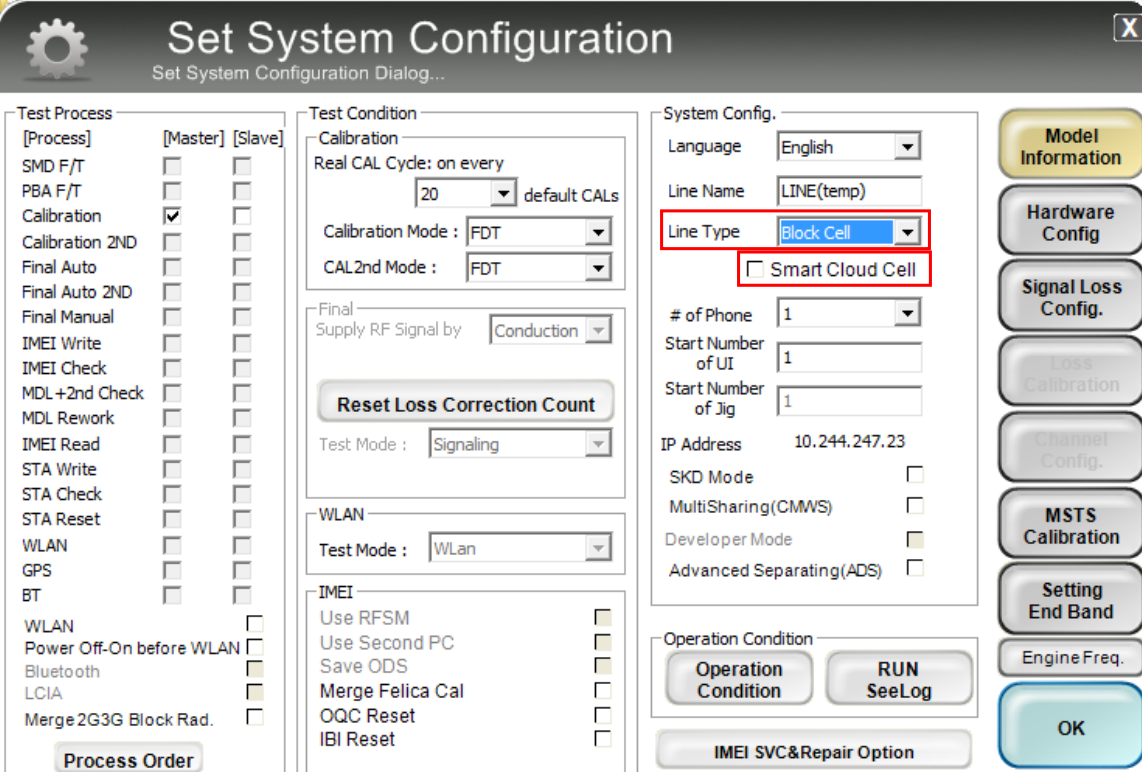
- Check the '[Calibration](#)' menu, and select '[Extract & Run](#)'.



3. Check the 'CAL' and open the [model file](#), then select 'Start' button.



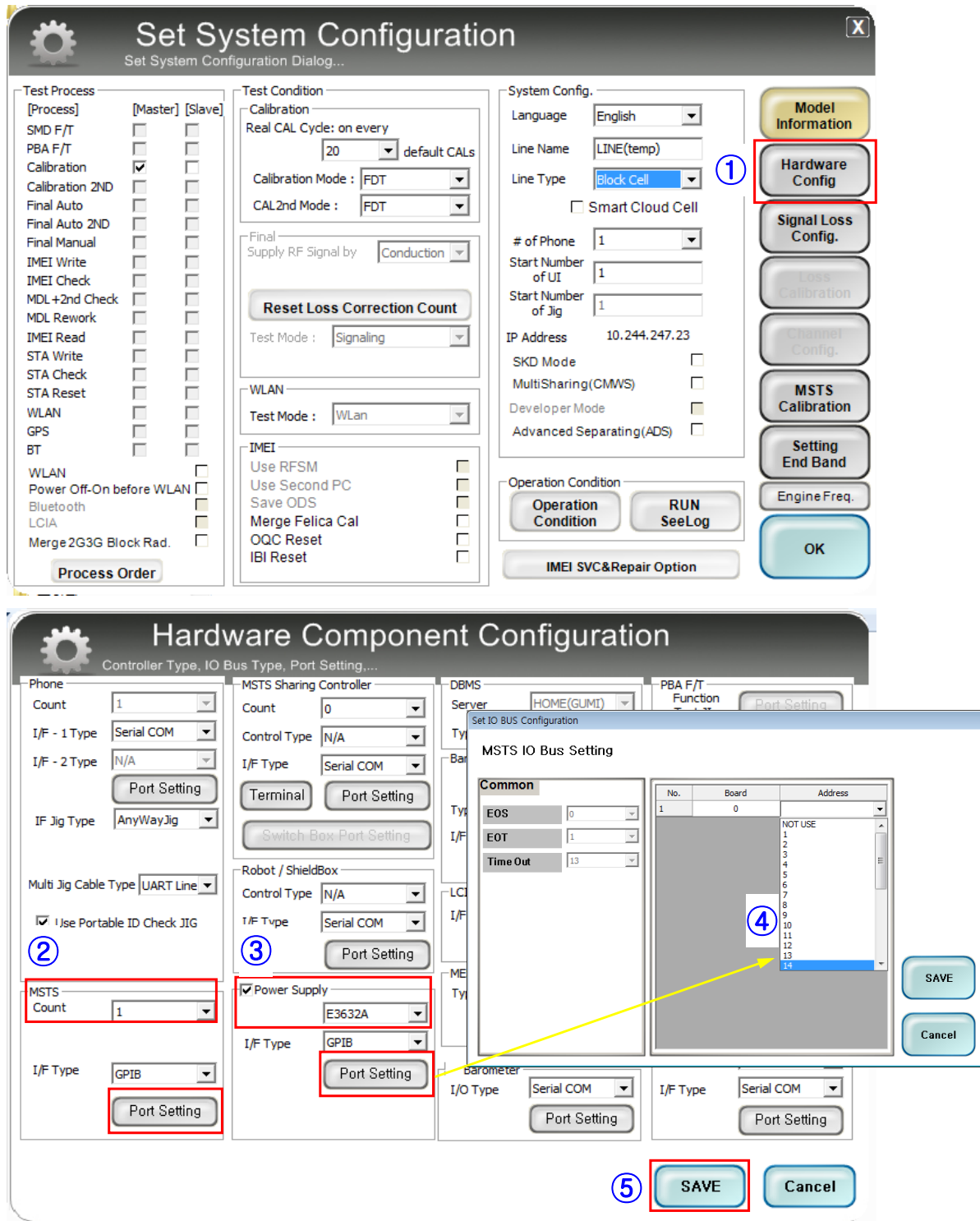
4. Change the Line Type to 'Block Cell' and disable 'Smart Cloud Cell'.



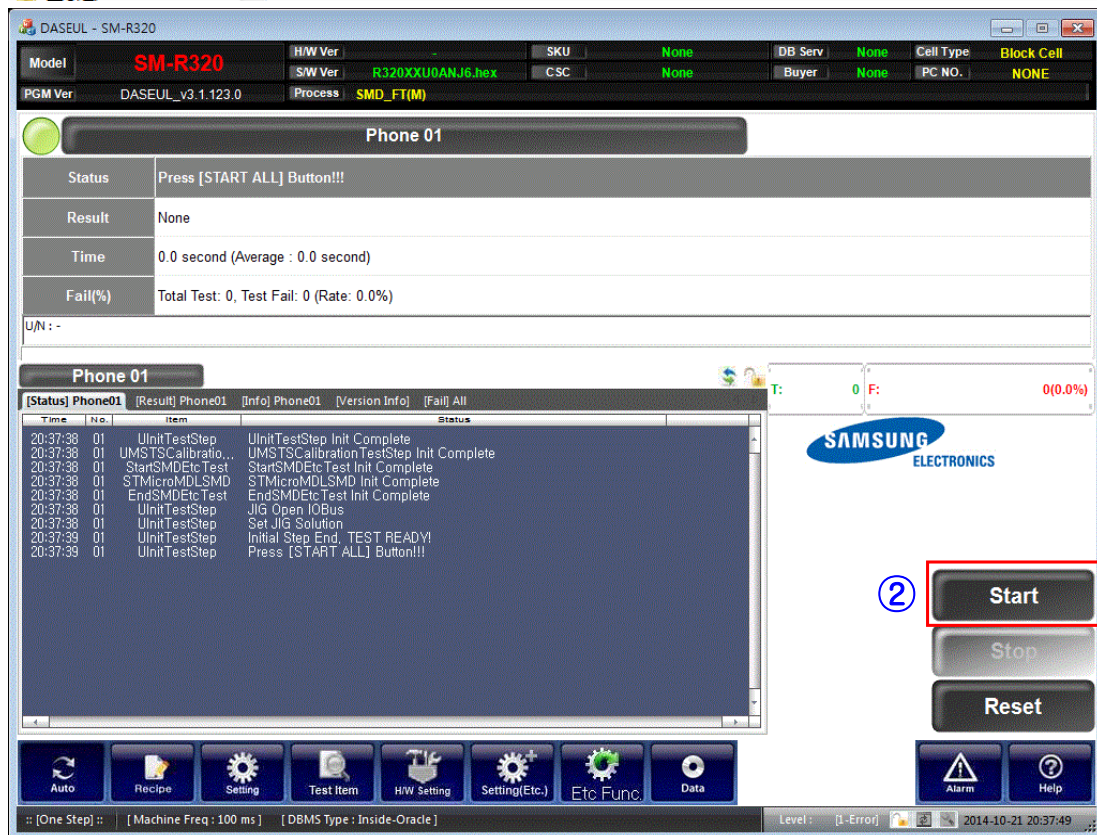
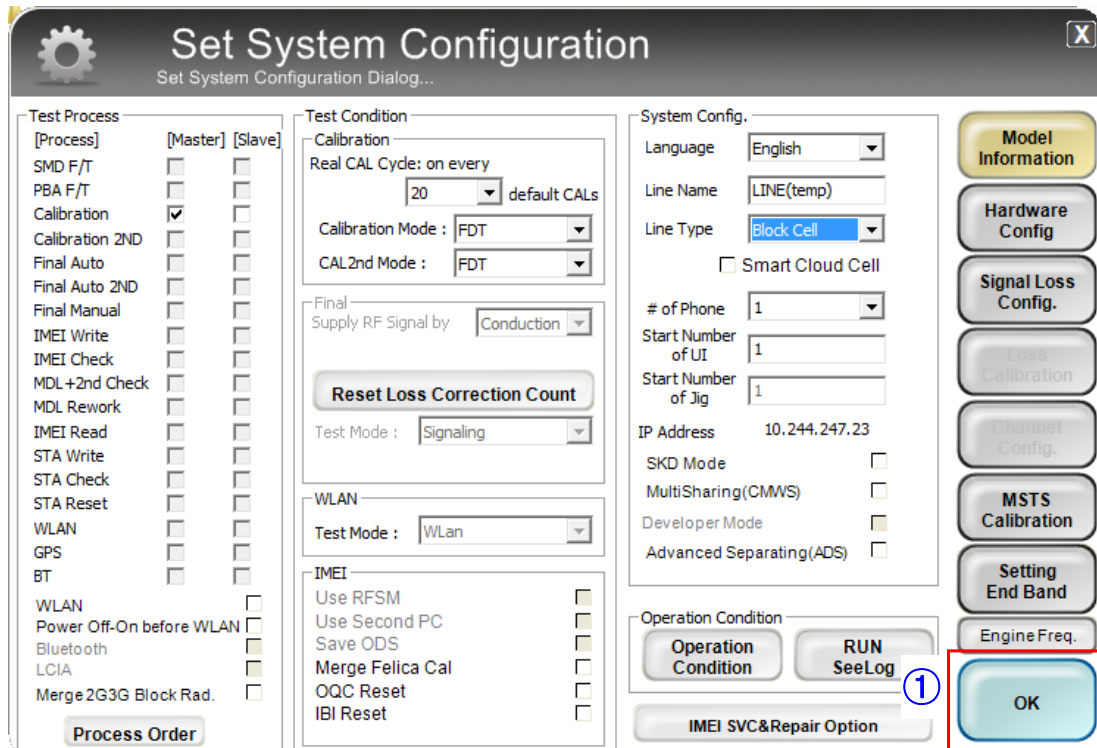
The image shows a 'Set System Configuration' dialog box with a title bar and a close button (X). The dialog is divided into several sections:

- Test Process:** A list of test processes with checkboxes for [Process], [Master], and [Slave]. The 'Calibration' checkbox is checked under [Process].
- Test Condition:** Includes 'Calibration' settings (Real CAL Cycle: on every 20, default CALs), 'Calibration Mode' (FDT), 'CAL2nd Mode' (FDT), 'Final Supply RF Signal by' (Conduction), 'Reset Loss Correction Count' button, 'Test Mode' (Signaling), 'WLAN Test Mode' (WLAN), and 'IMEI' settings (Use RFSM, Use Second PC, Save ODS, Merge Felica Cal, OQC Reset, IBI Reset).
- System Config.:** Includes 'Language' (English), 'Line Name' (LINE(temp)), 'Line Type' (Block Cell), 'Smart Cloud Cell' (unchecked), '# of Phone' (1), 'Start Number of UI' (1), 'Start Number of Jig' (1), 'IP Address' (10.244.247.23), 'SKD Mode' (unchecked), 'MultiSharing(CMWS)' (unchecked), 'Developer Mode' (unchecked), and 'Advanced Separating(ADS)' (unchecked).
- Operation Condition:** Includes 'Operation Condition' button, 'RUN SeeLog' button, and 'IMEI SVC&Repair Option' button.
- Model Information:** A vertical stack of buttons: Model Information, Hardware Config, Signal Loss Config., Loss Calibration, Channel Config., MSTs Calibration, Setting End Band, Engine Freq., and OK.

5. Set the GPIB address of MSTS(CMW500) and Power Supply(E3632A) to enter 'Hardware Config' and 'Save'. (Check the GPIB address of equipments in advance)



6. Press 'OK' to start RF Calibration after completing all settings.

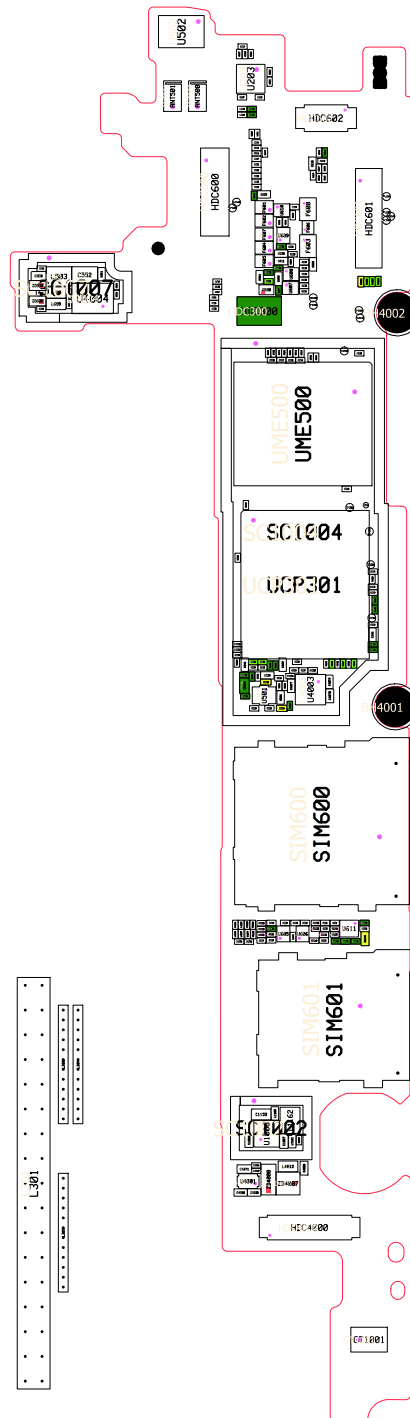


8-1. Block Diagram

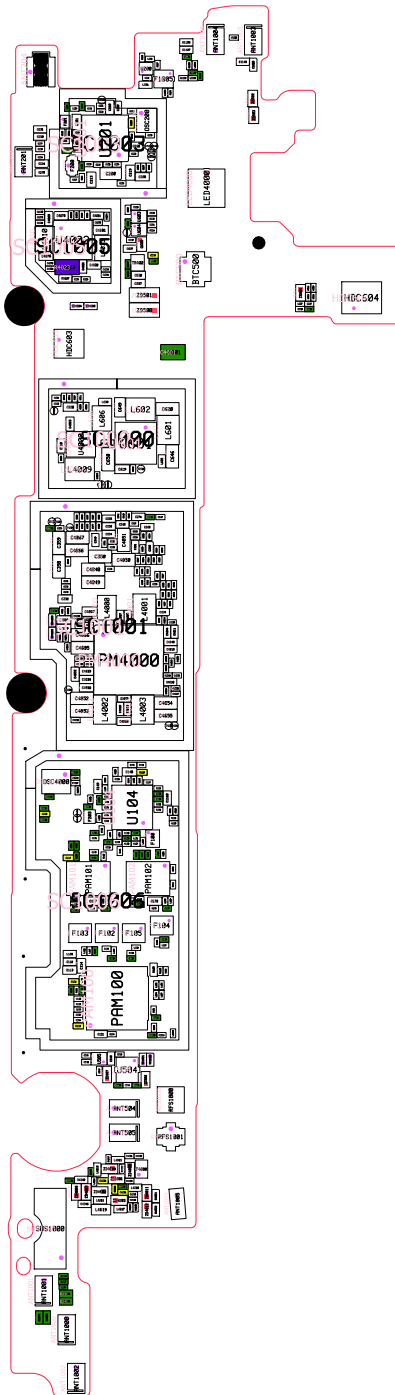
[illegible]

8-2. PCB Diagrams

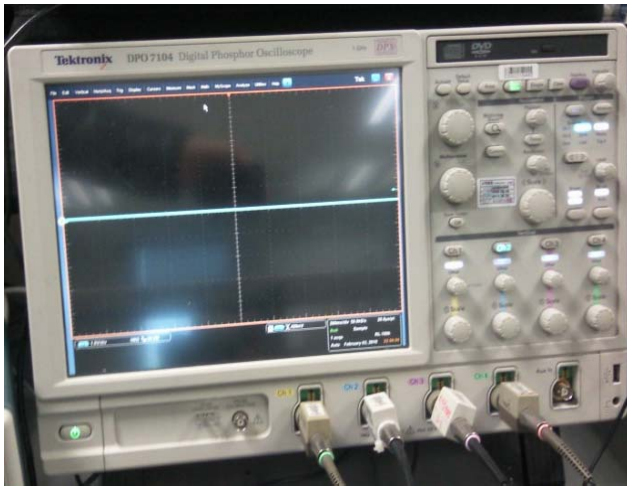
8-2-1. Main PCB Top



8-2-2. Bottom



8-2-3. Equipments



↑ Oscilloscope



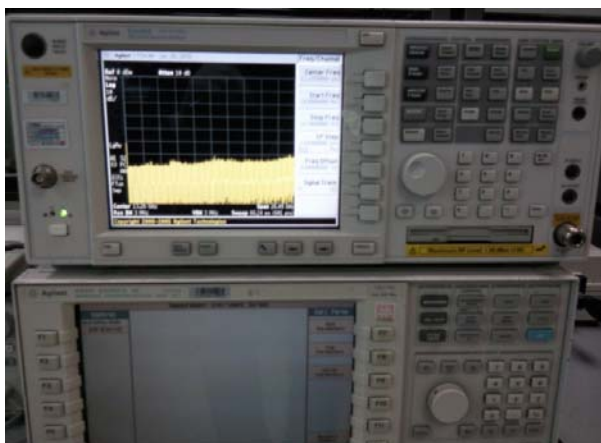
↑ Digital Multimeter



↑ Power Supply



↑ + driver, ESD Safe Tweezer



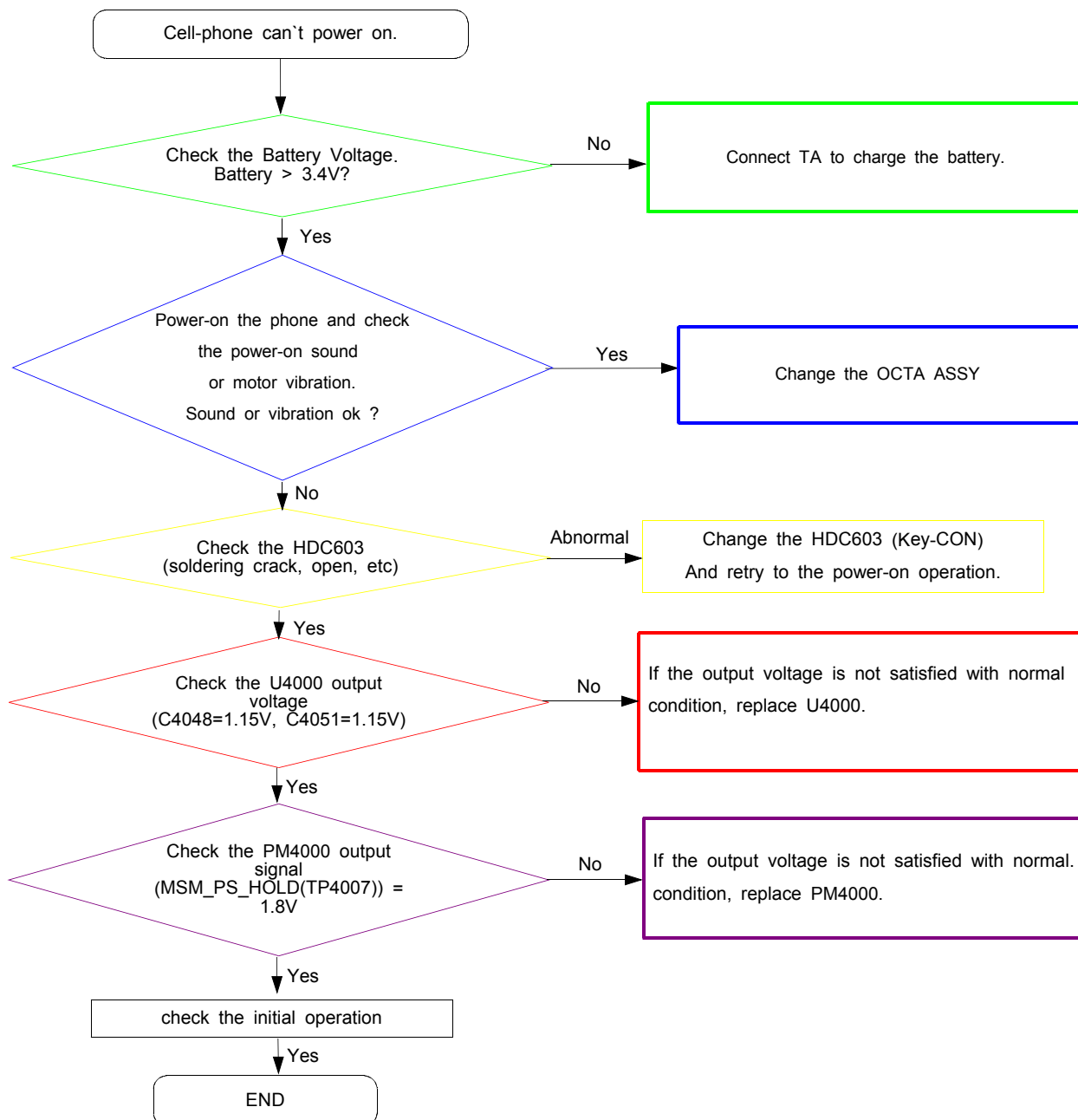
↑ 8960 & Spectrum Analyzer



↑ Soldering iron

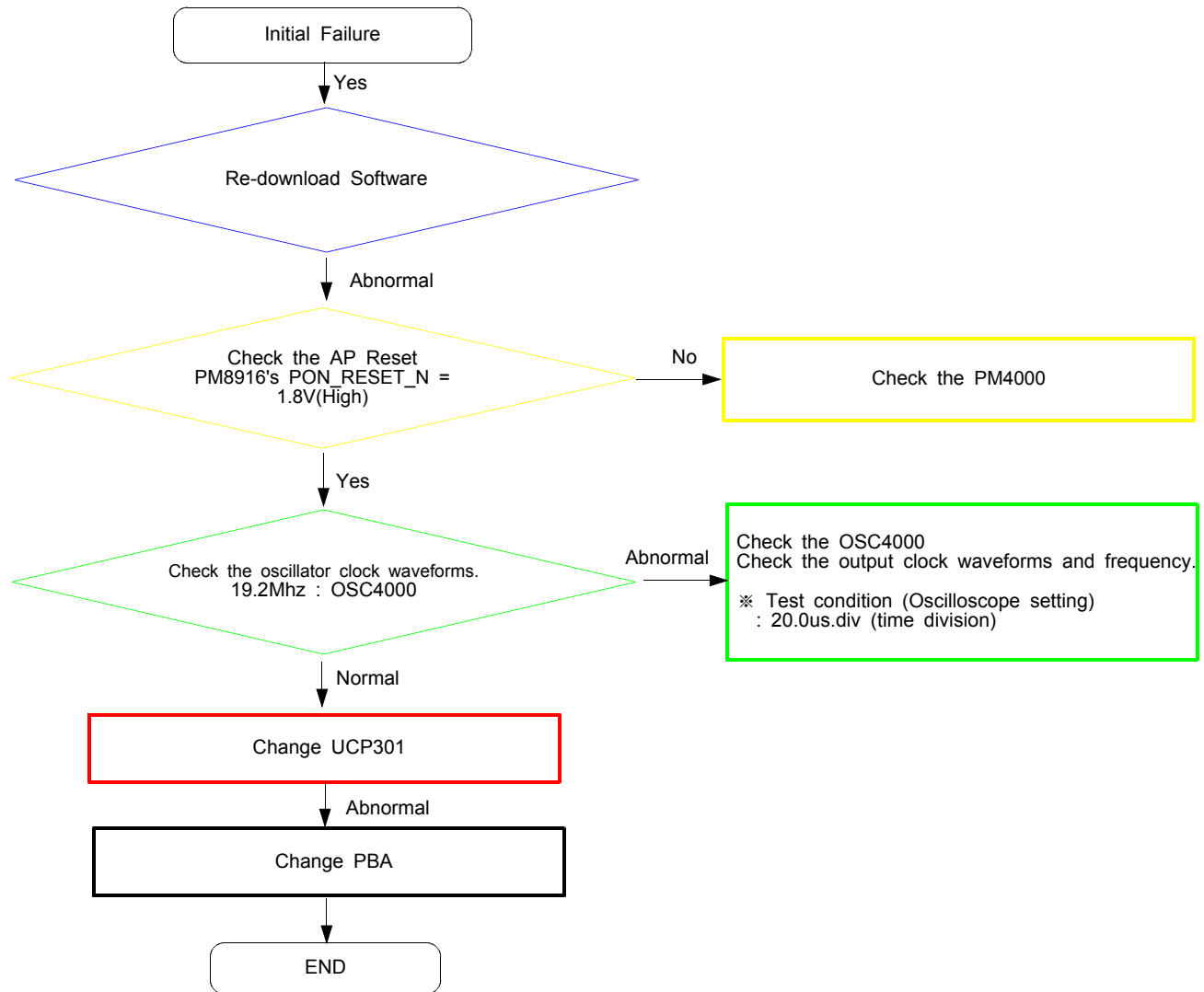
8-3. Flow Chart of Troubleshooting

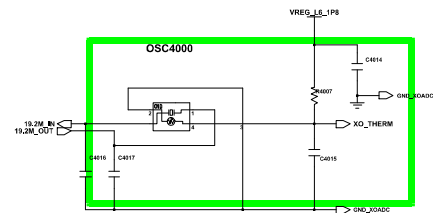
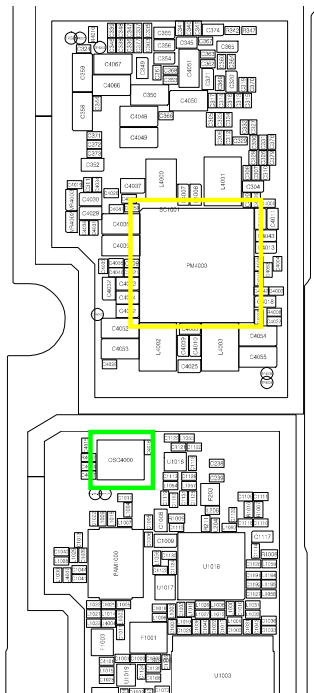
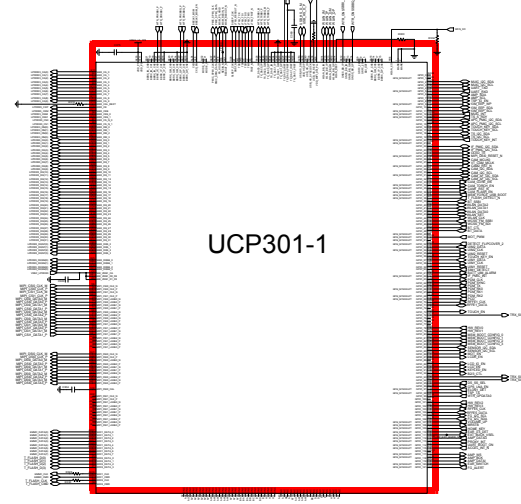
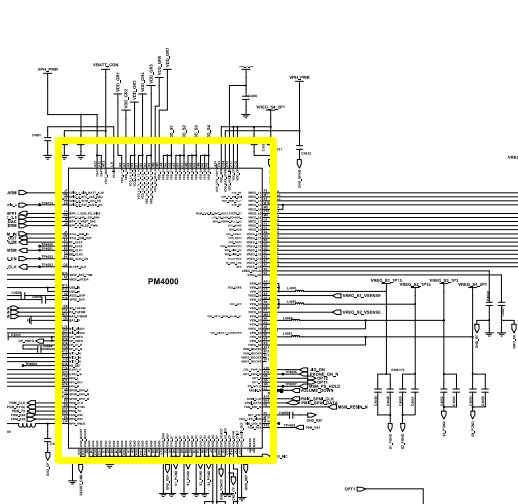
8-3-1. Power On



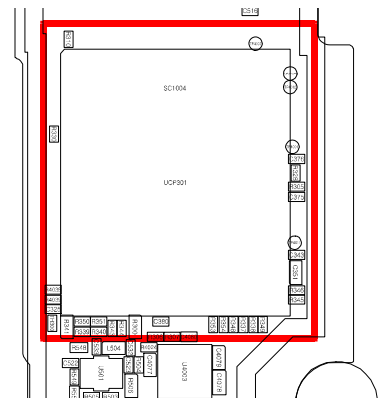


8-3-2. Initial

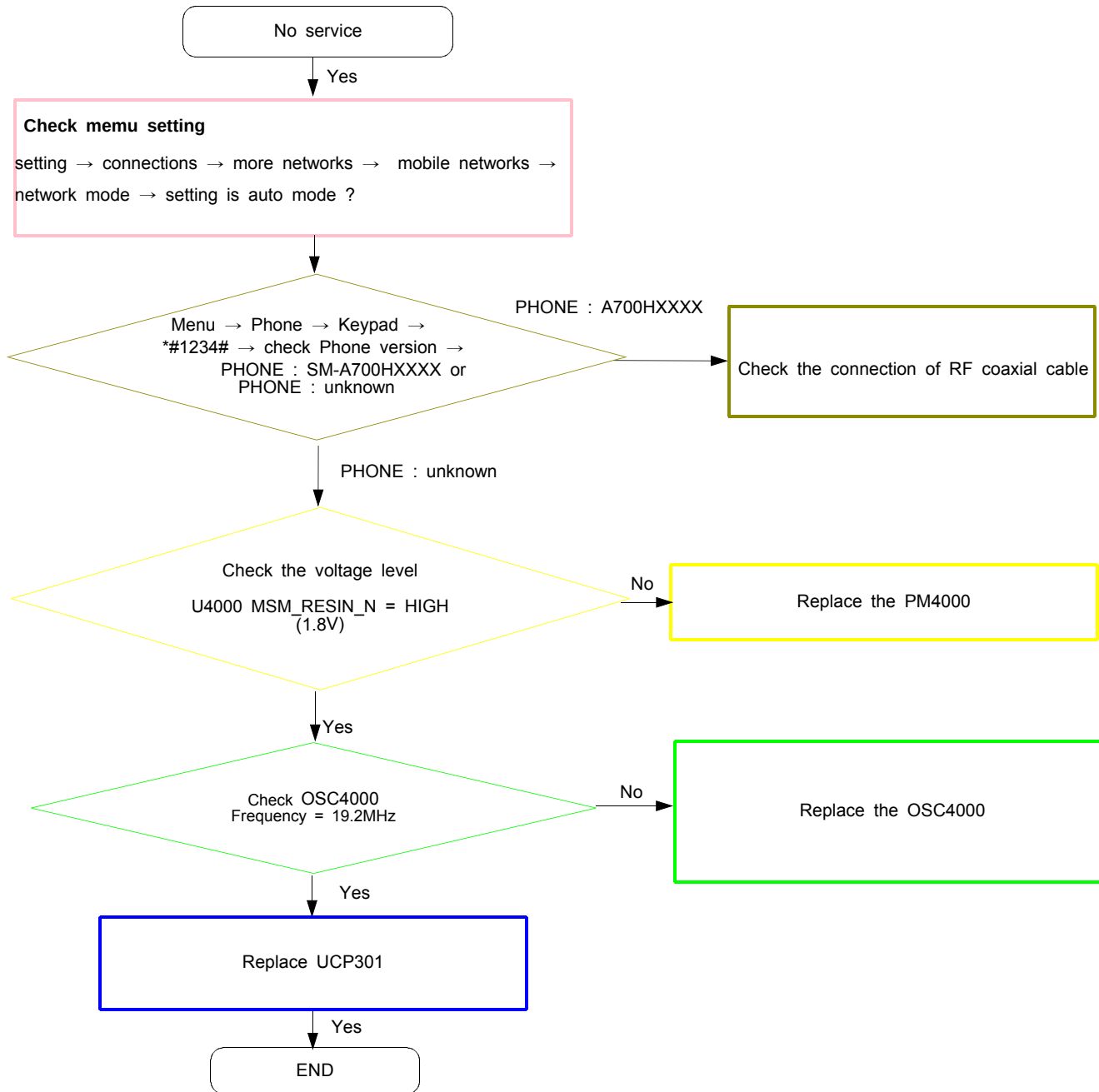


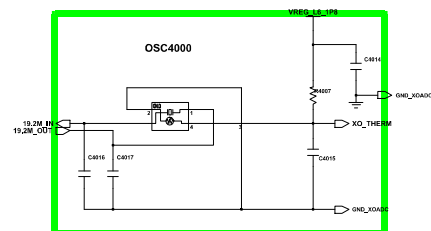
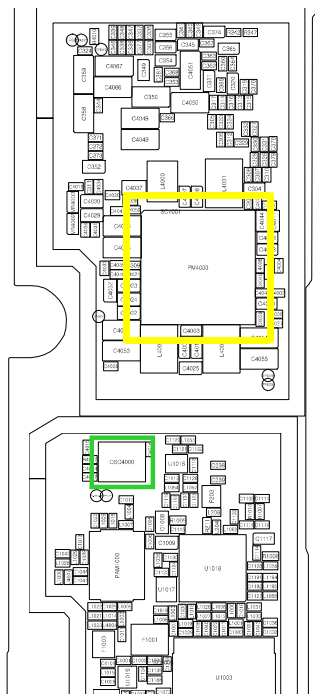
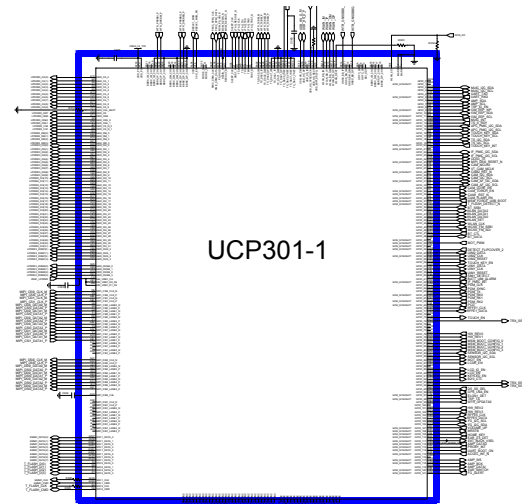
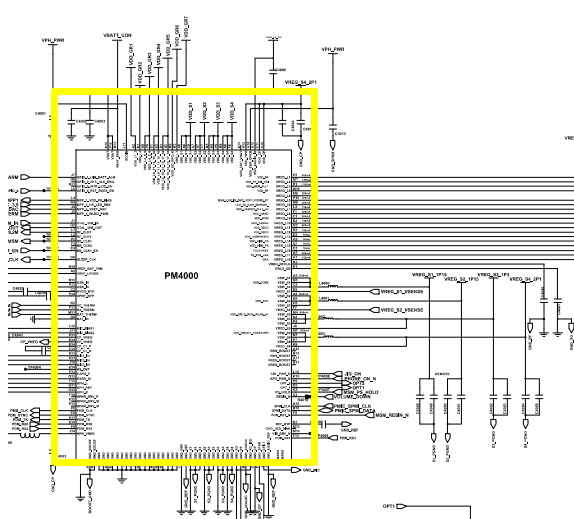


19.2MHz OSC

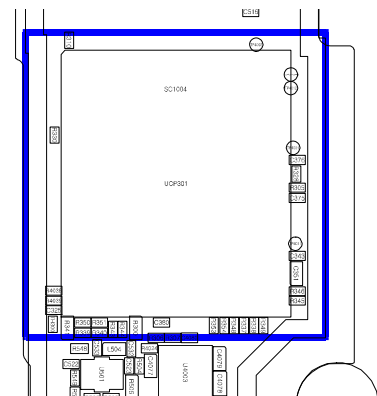


8-3-3. No Service

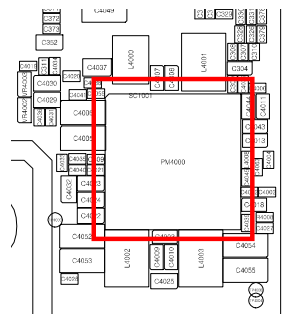
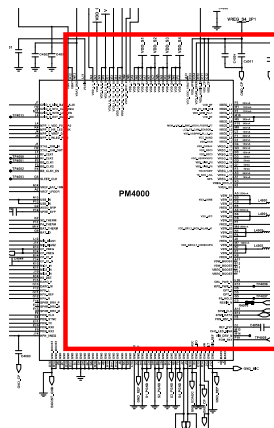
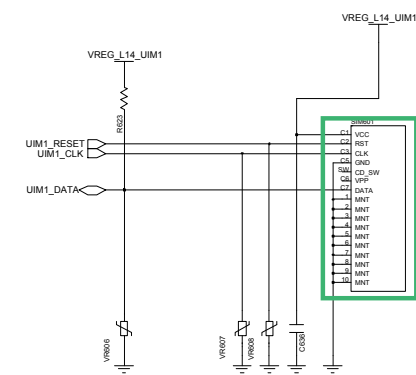
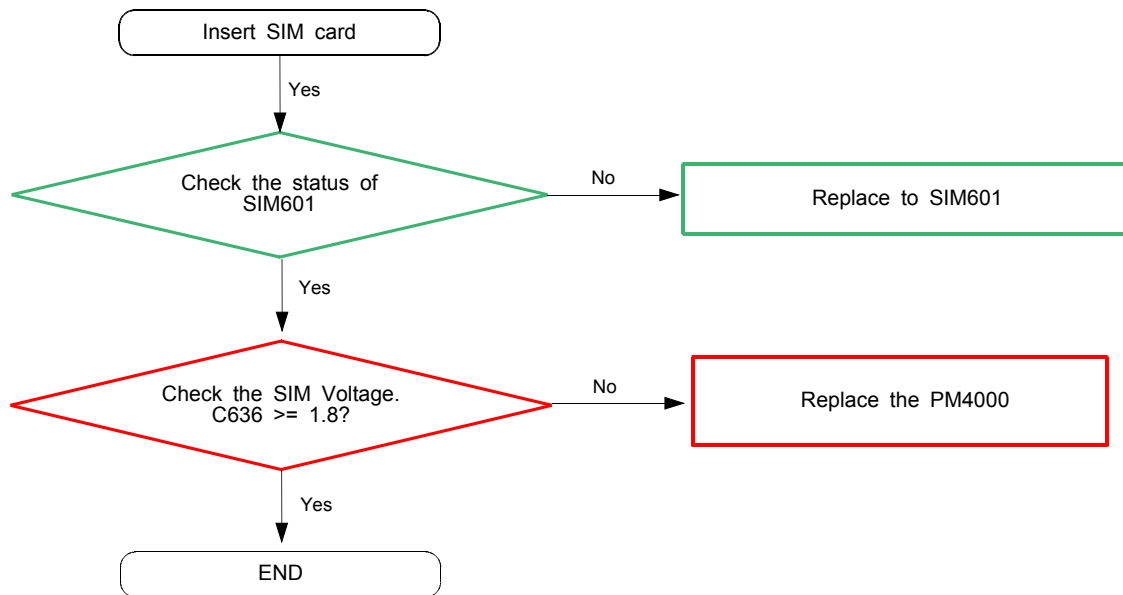




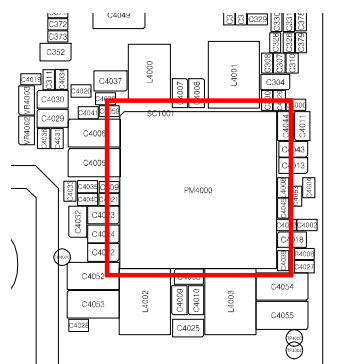
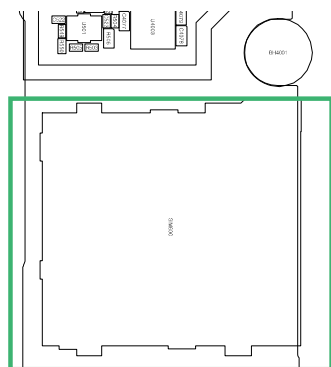
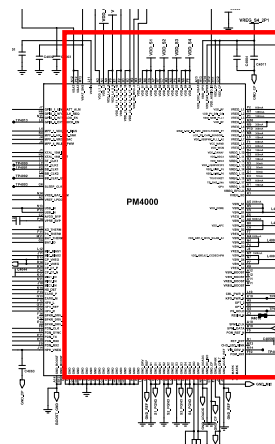
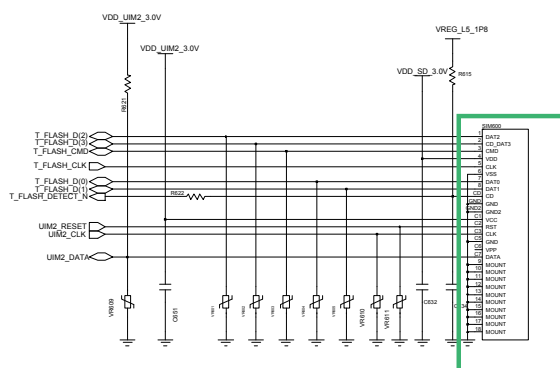
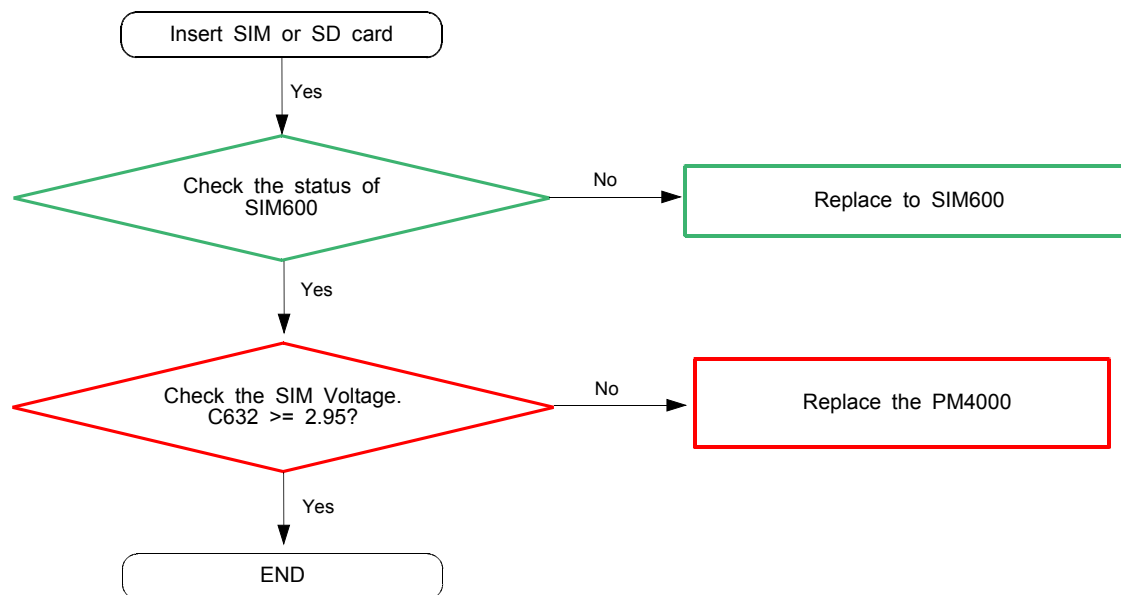
19.2MHz OSC



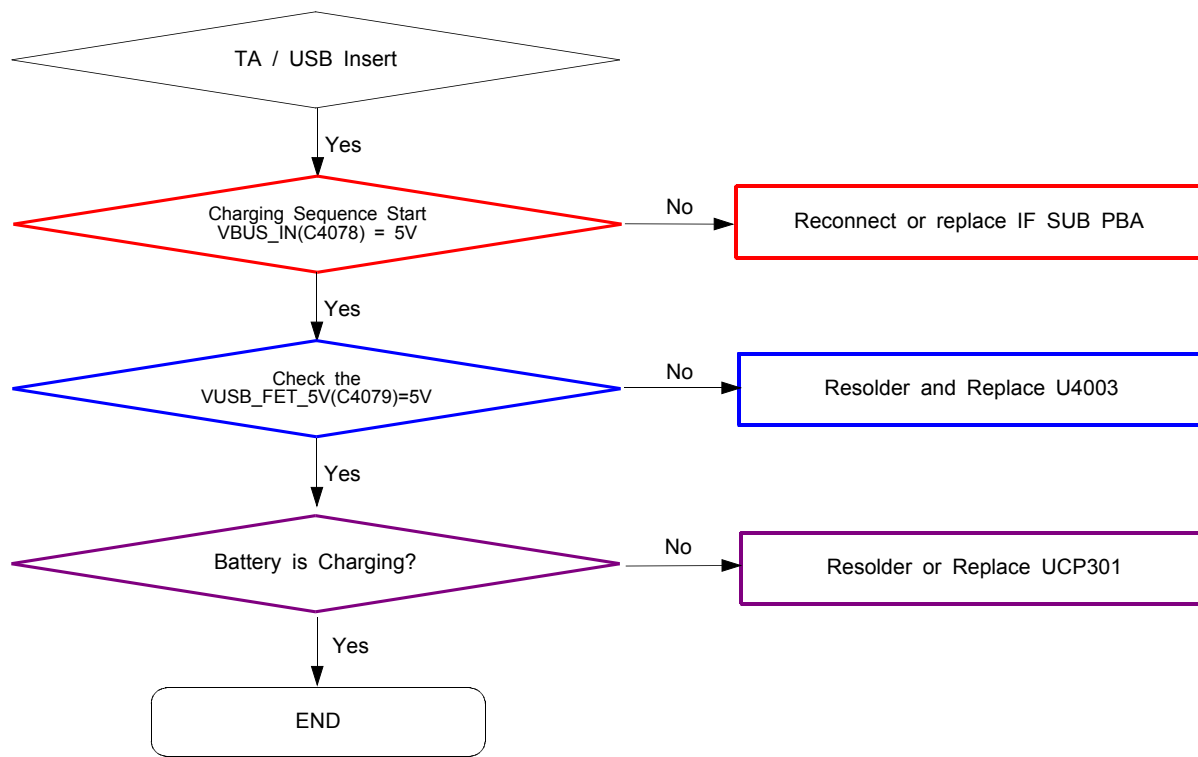
8-3-4. SIM1 Part

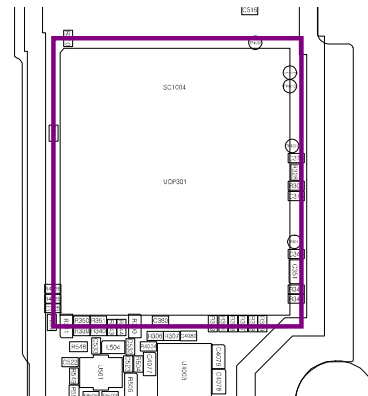
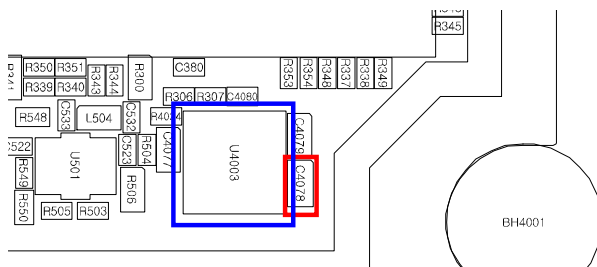
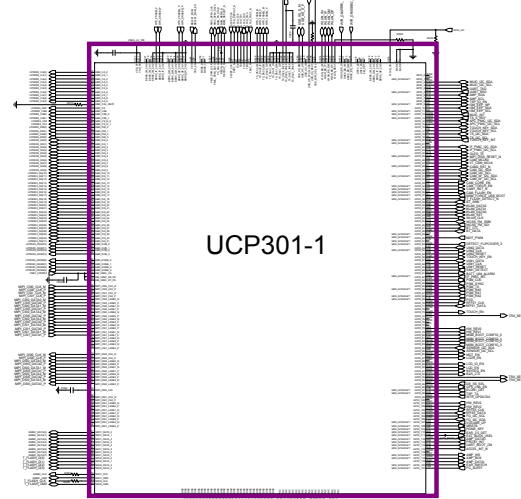
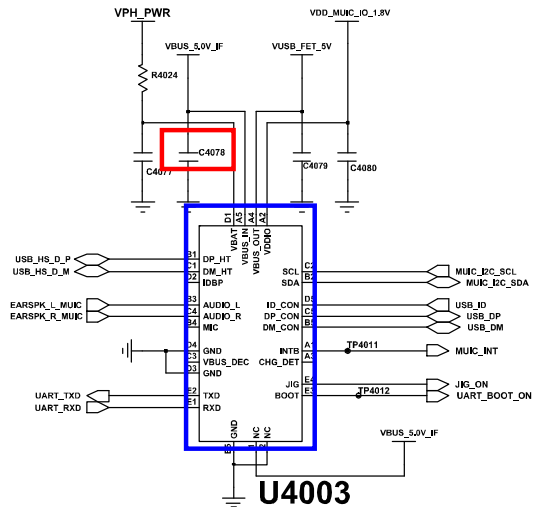


8-3-5. Hybrid Socket Part

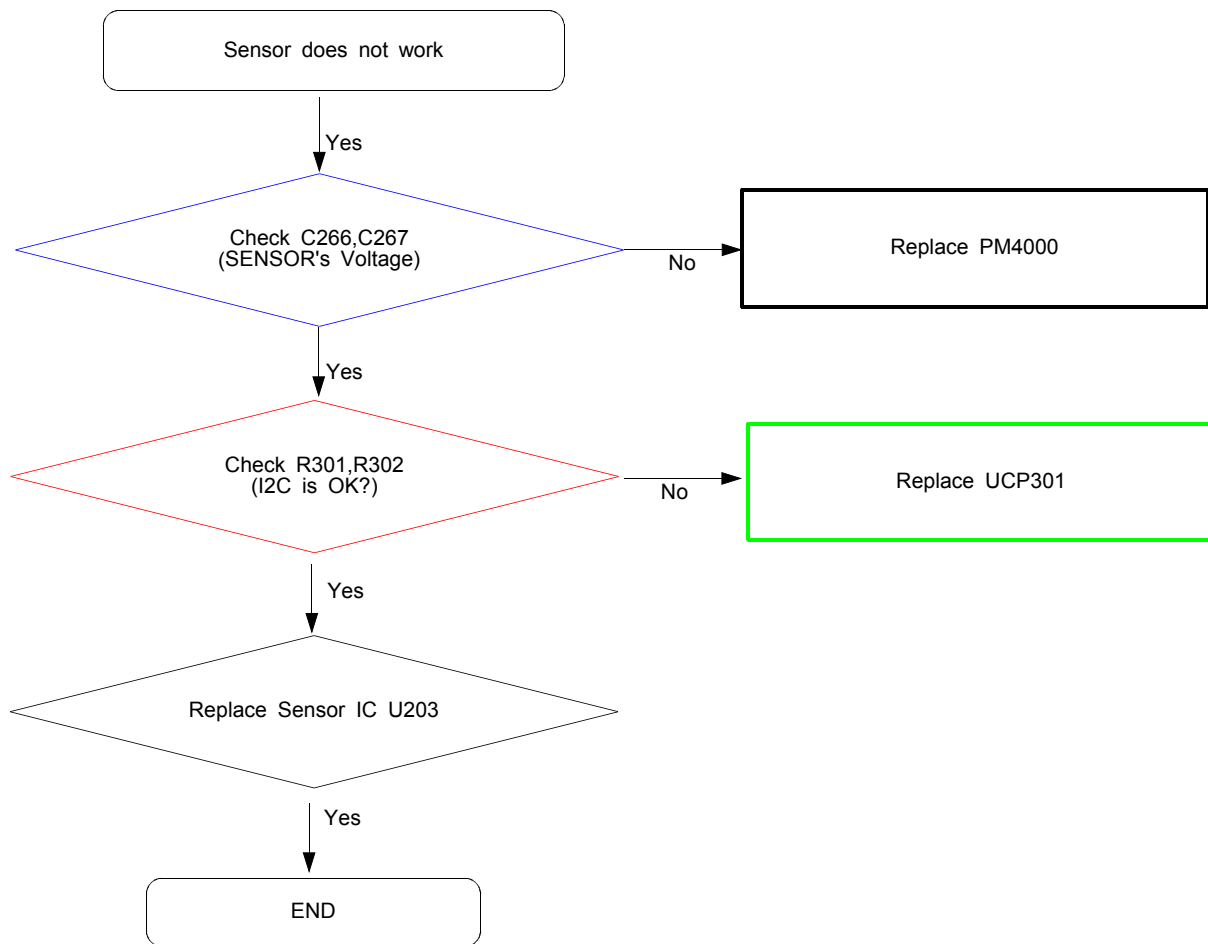


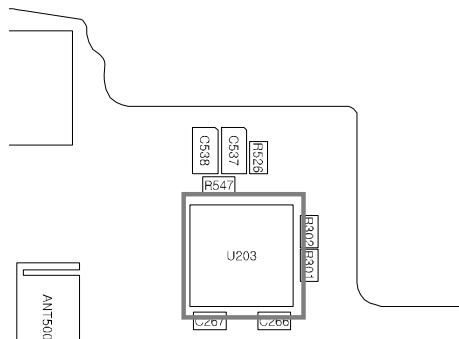
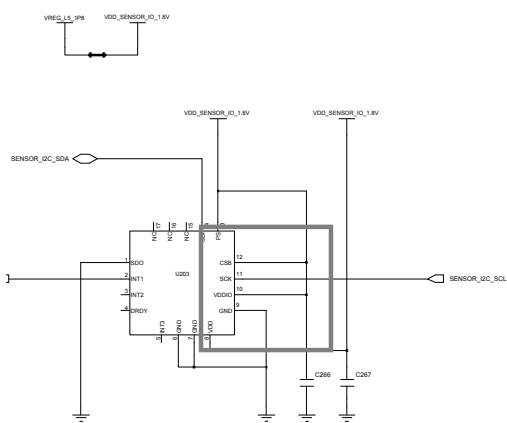
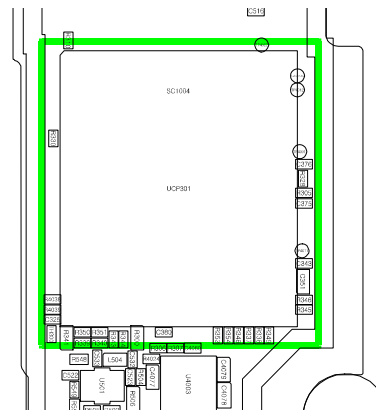
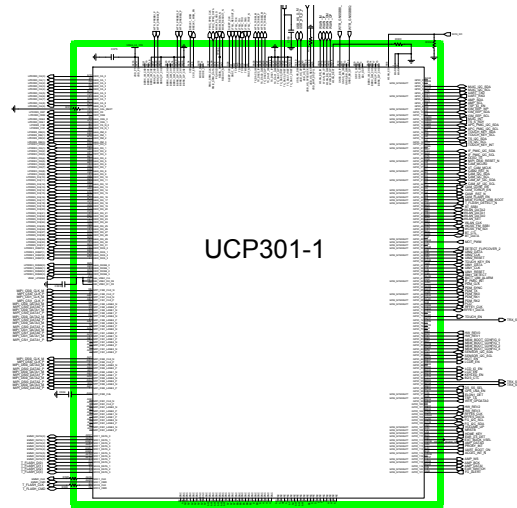
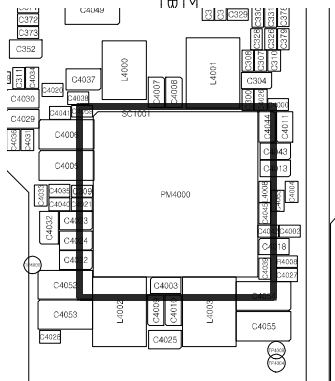
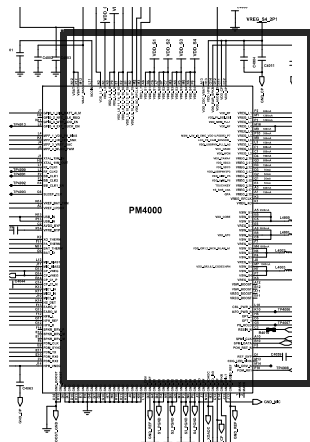
8-3-6. Charging Part



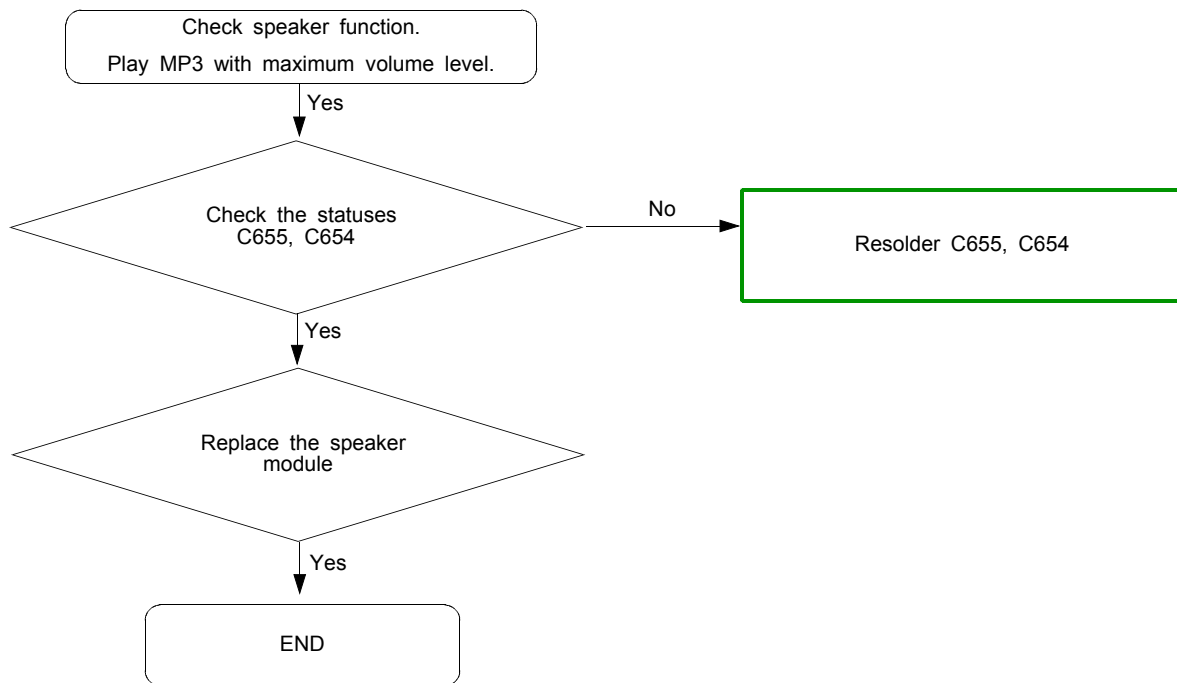


8-3-7. 6Axis Sensor

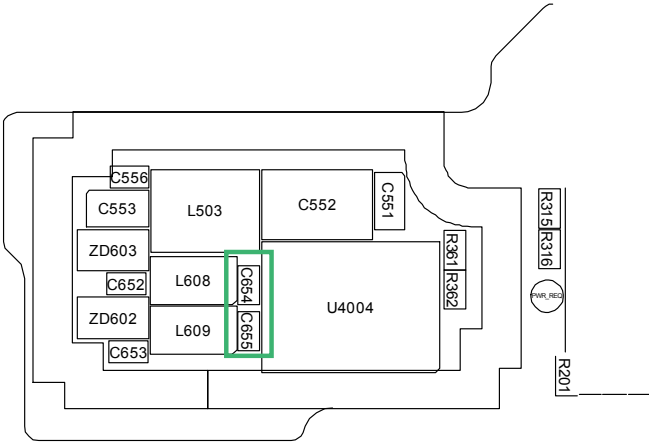




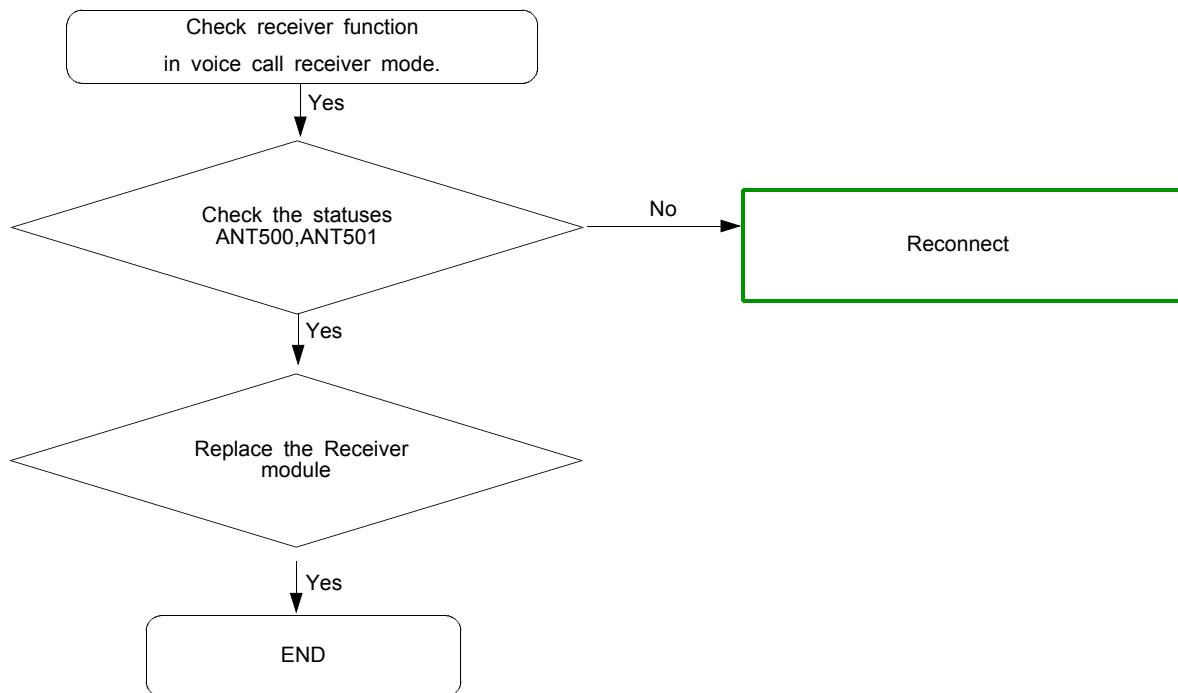
8-3-8. Speaker Part

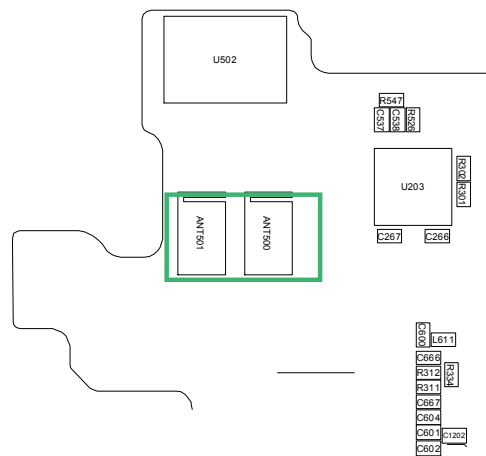
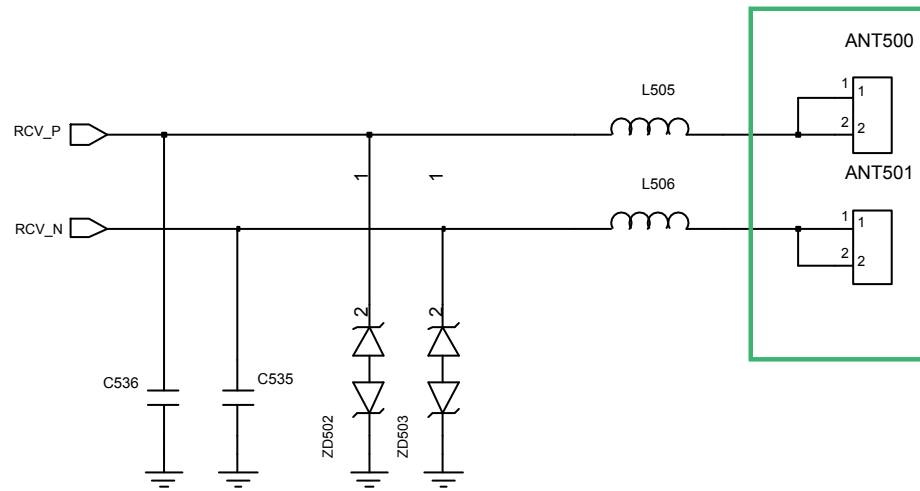


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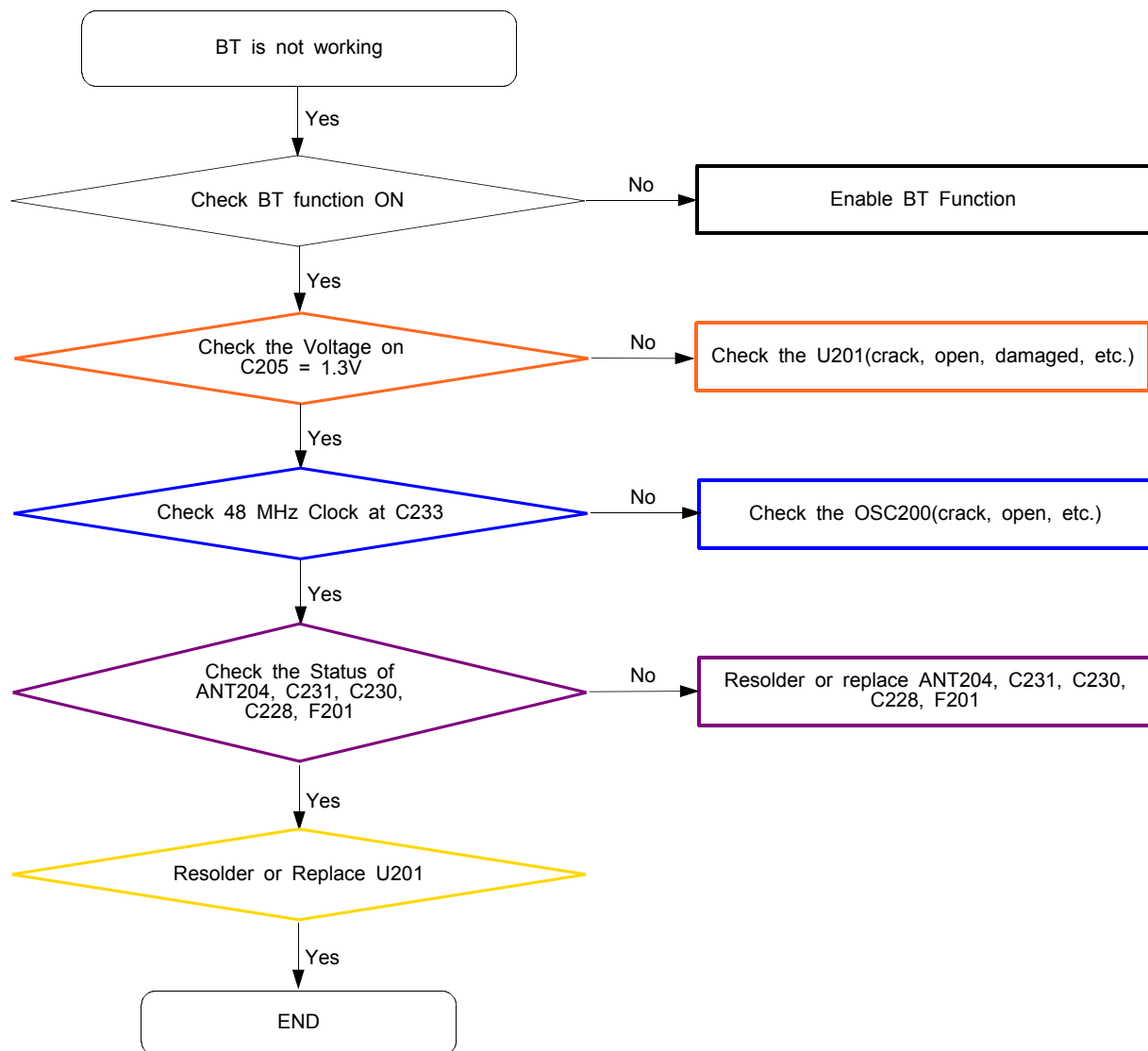


8-3-9. Receiver Part



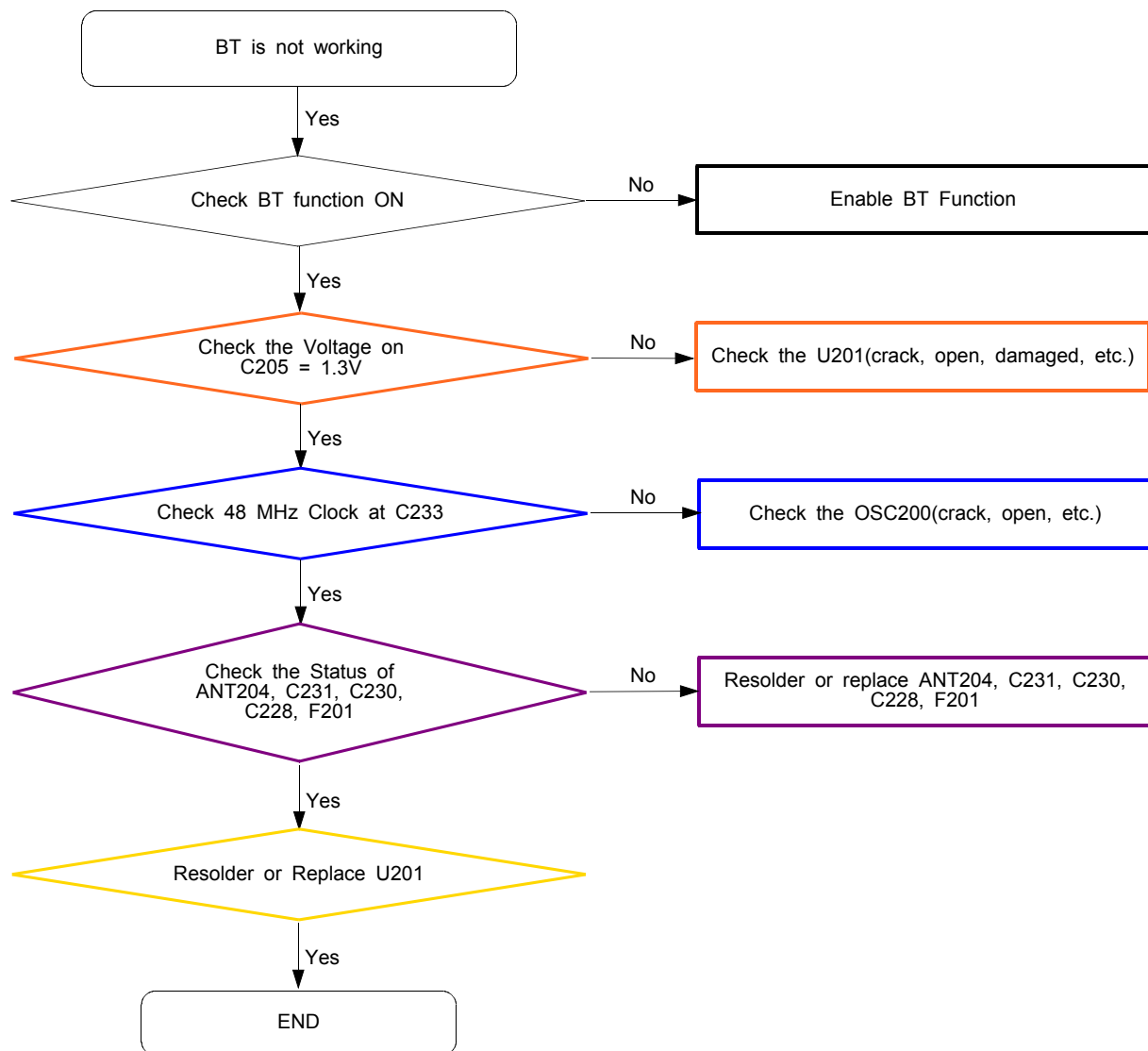


8-3-10. BT Part



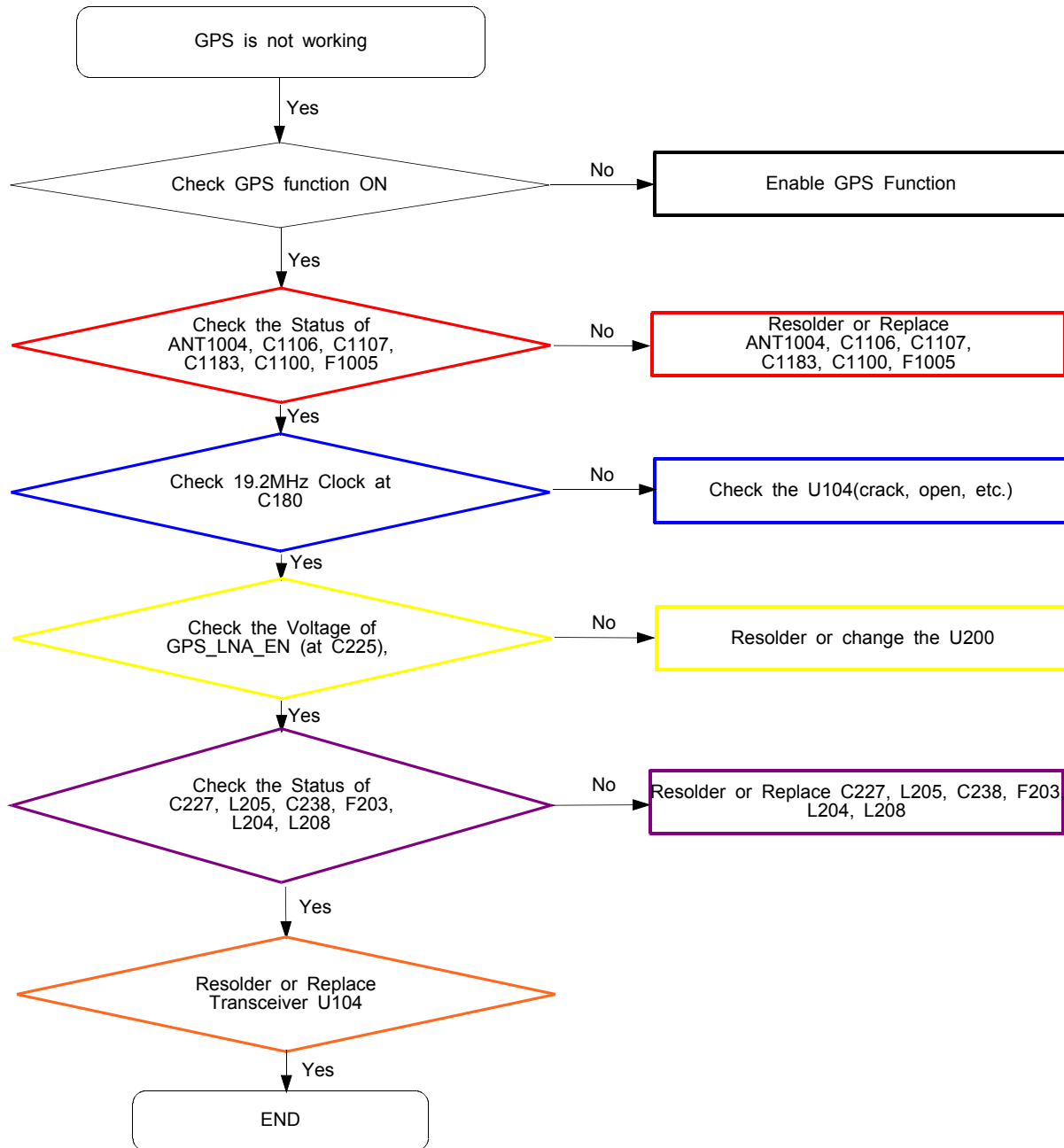


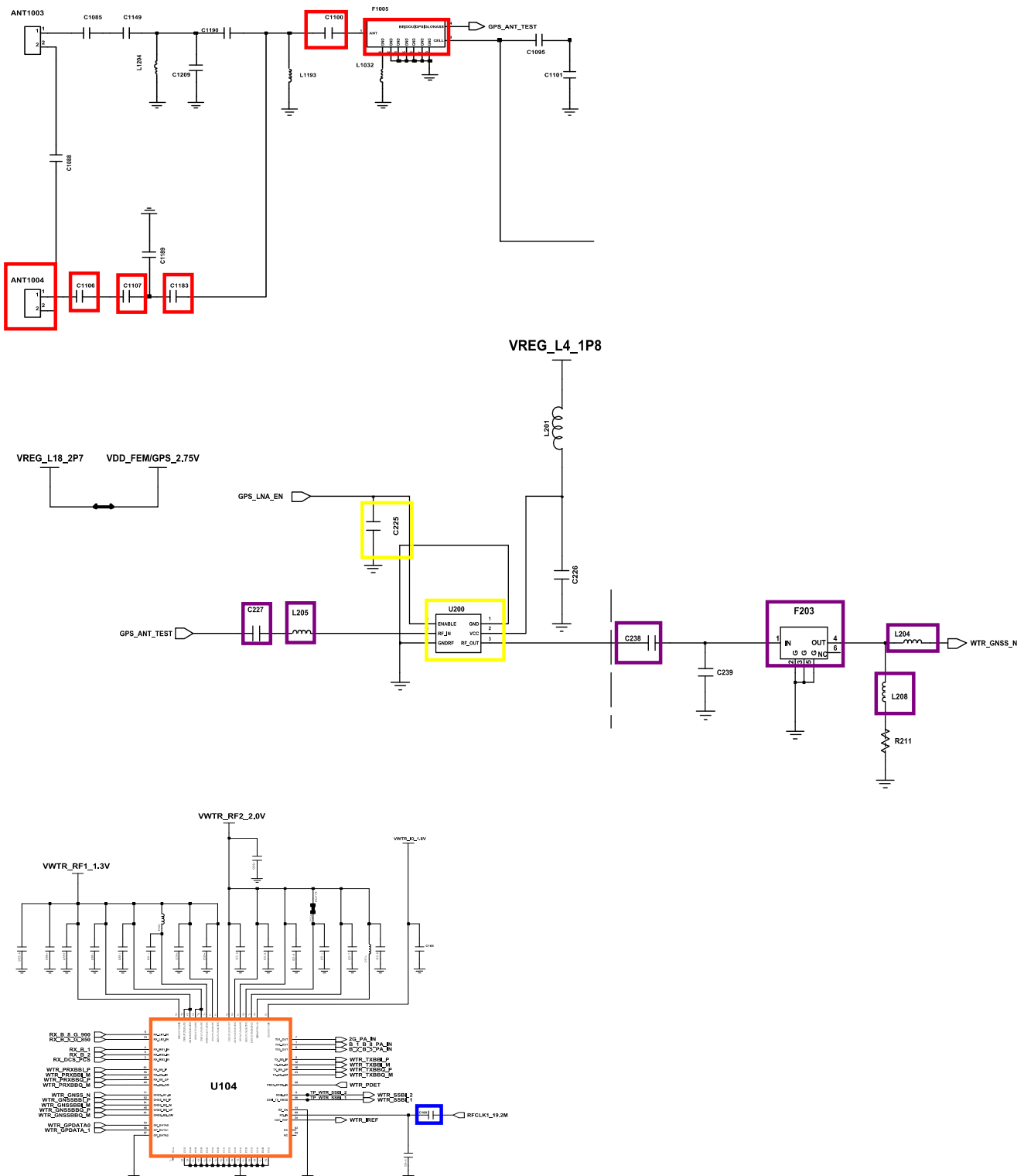
8-3-11. WiFi Part

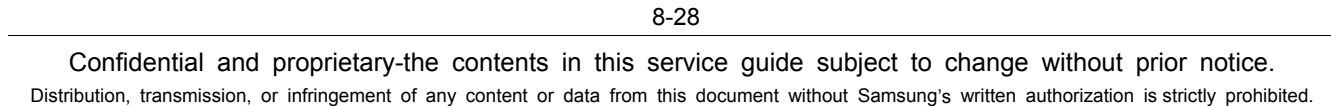




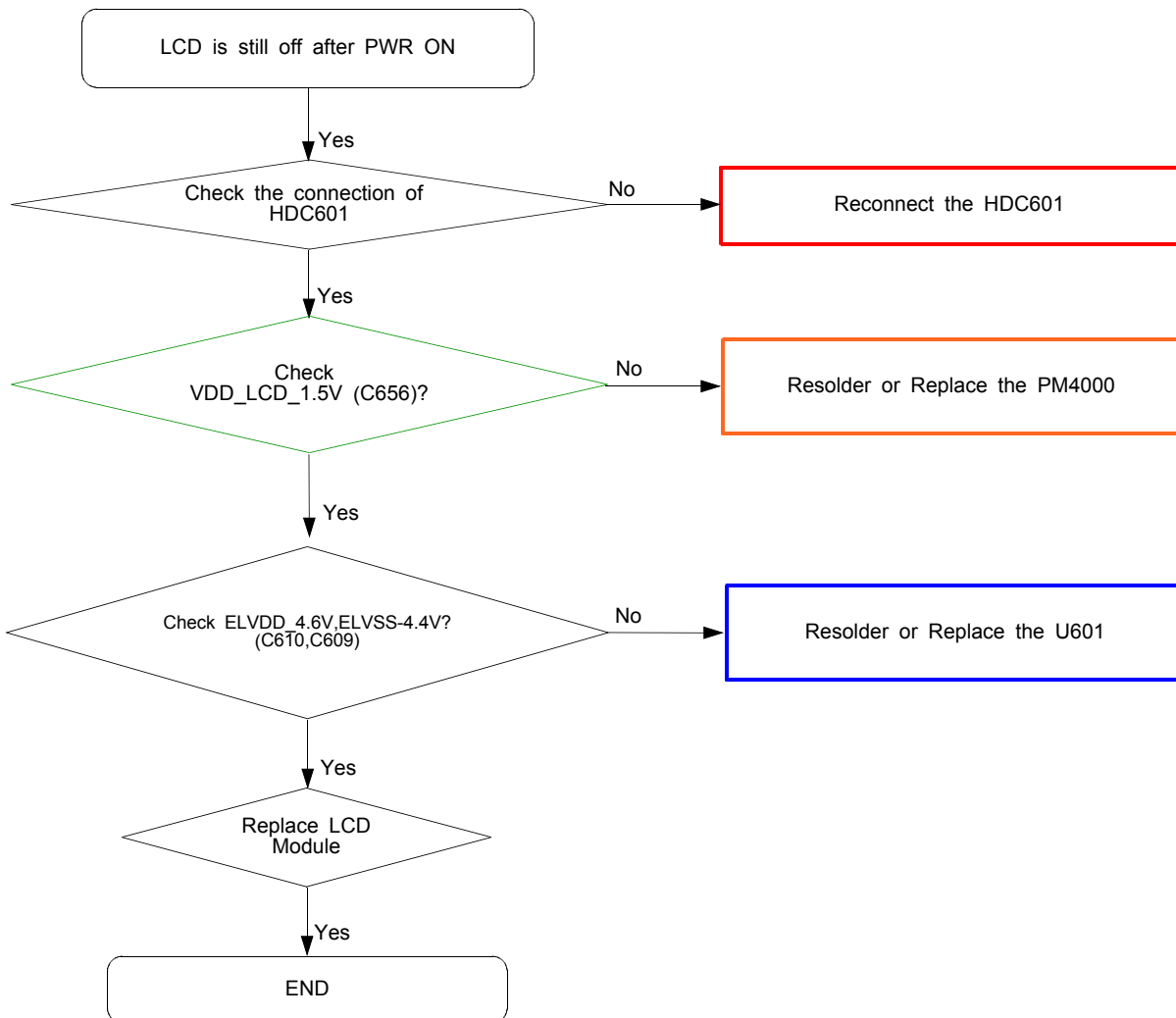
8-3-12. GPS Part

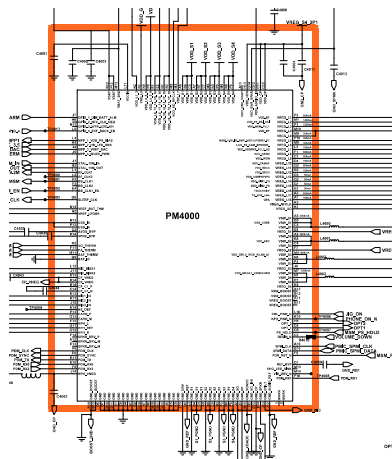
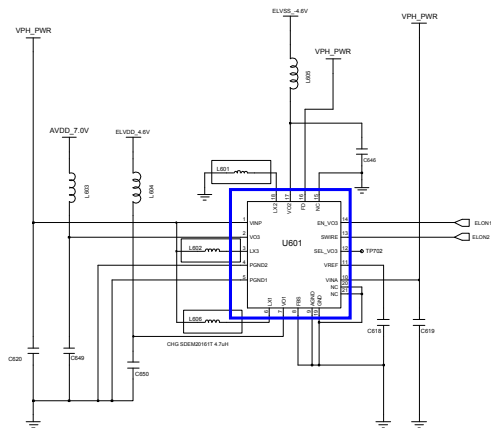
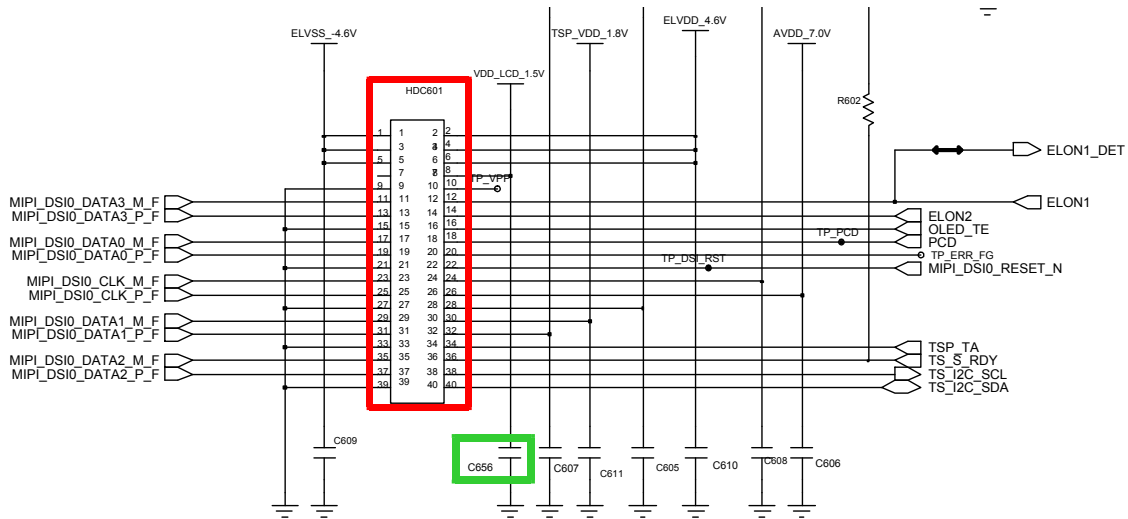


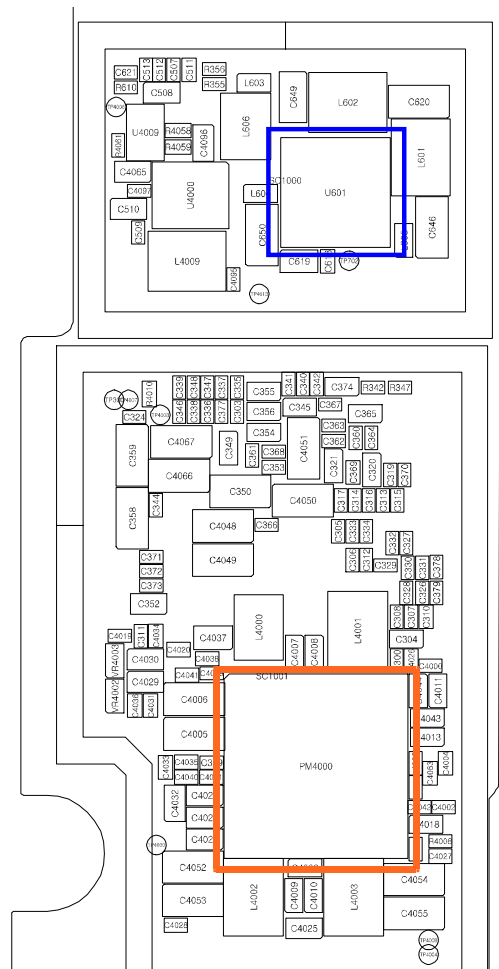
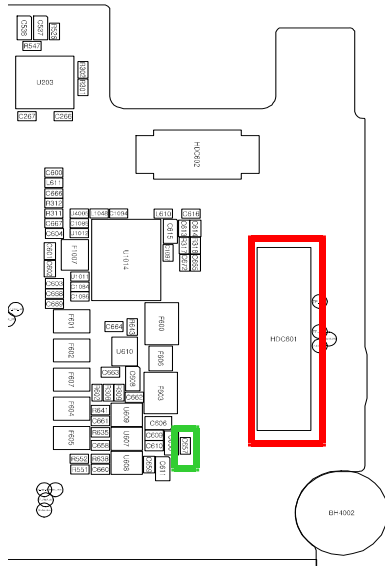




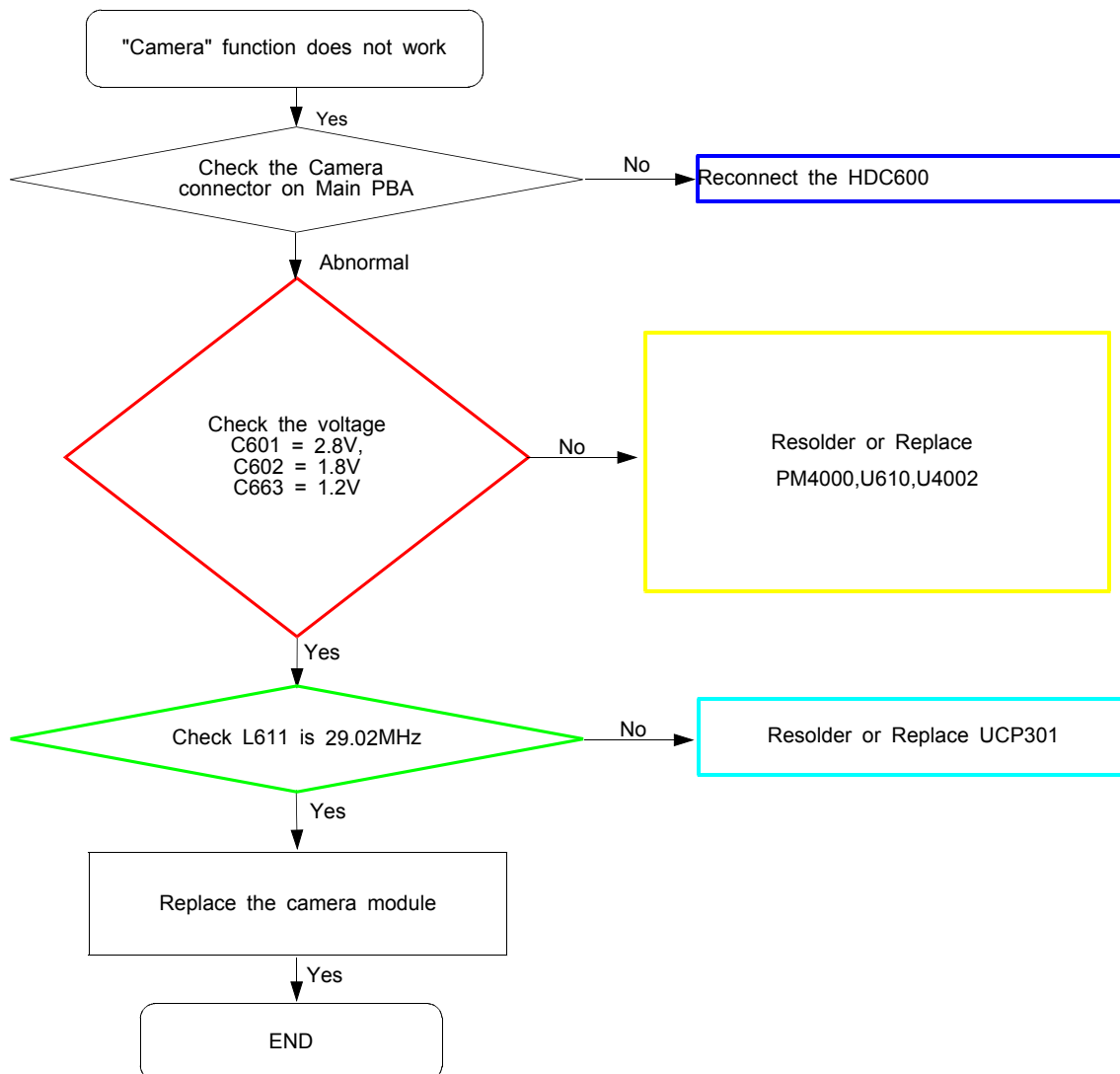
8-3-13. LCD

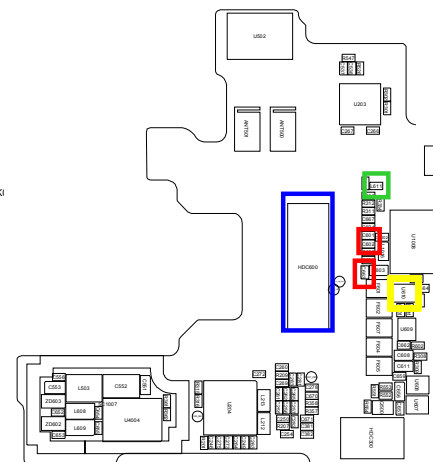




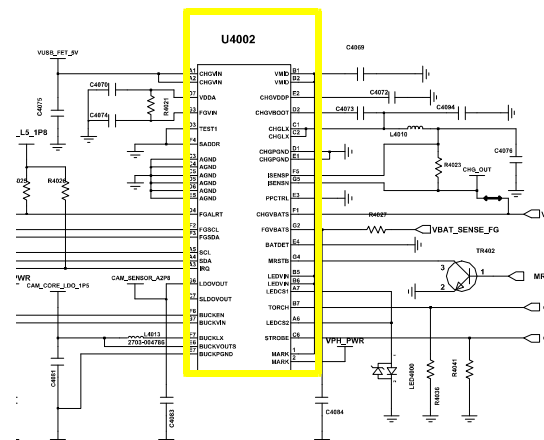
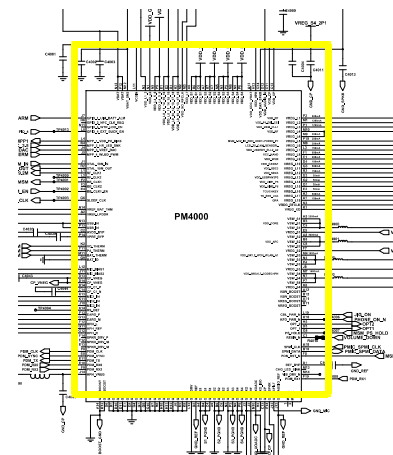


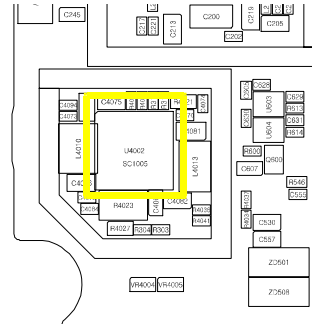
8-3-14. 13M CAM



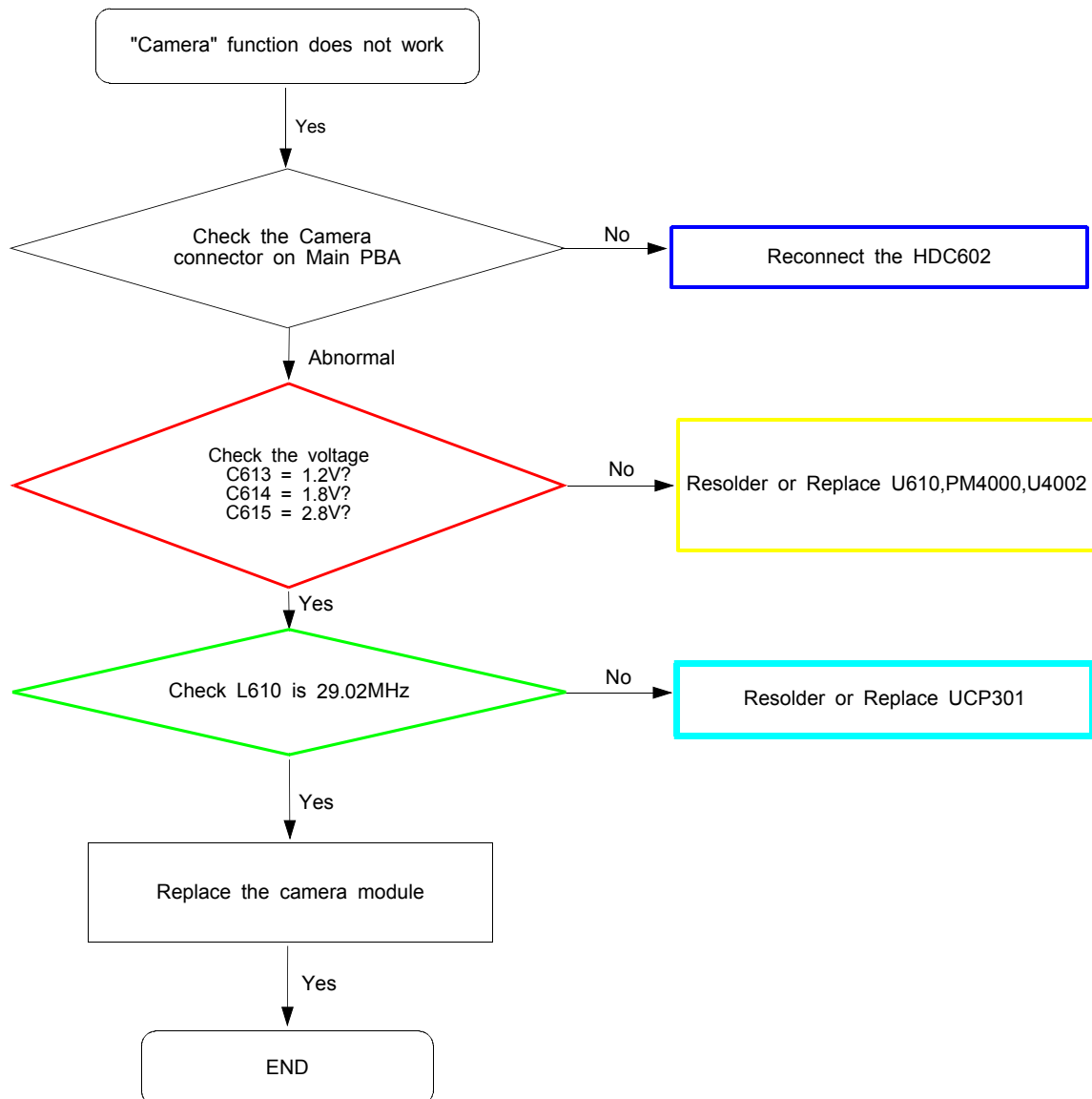


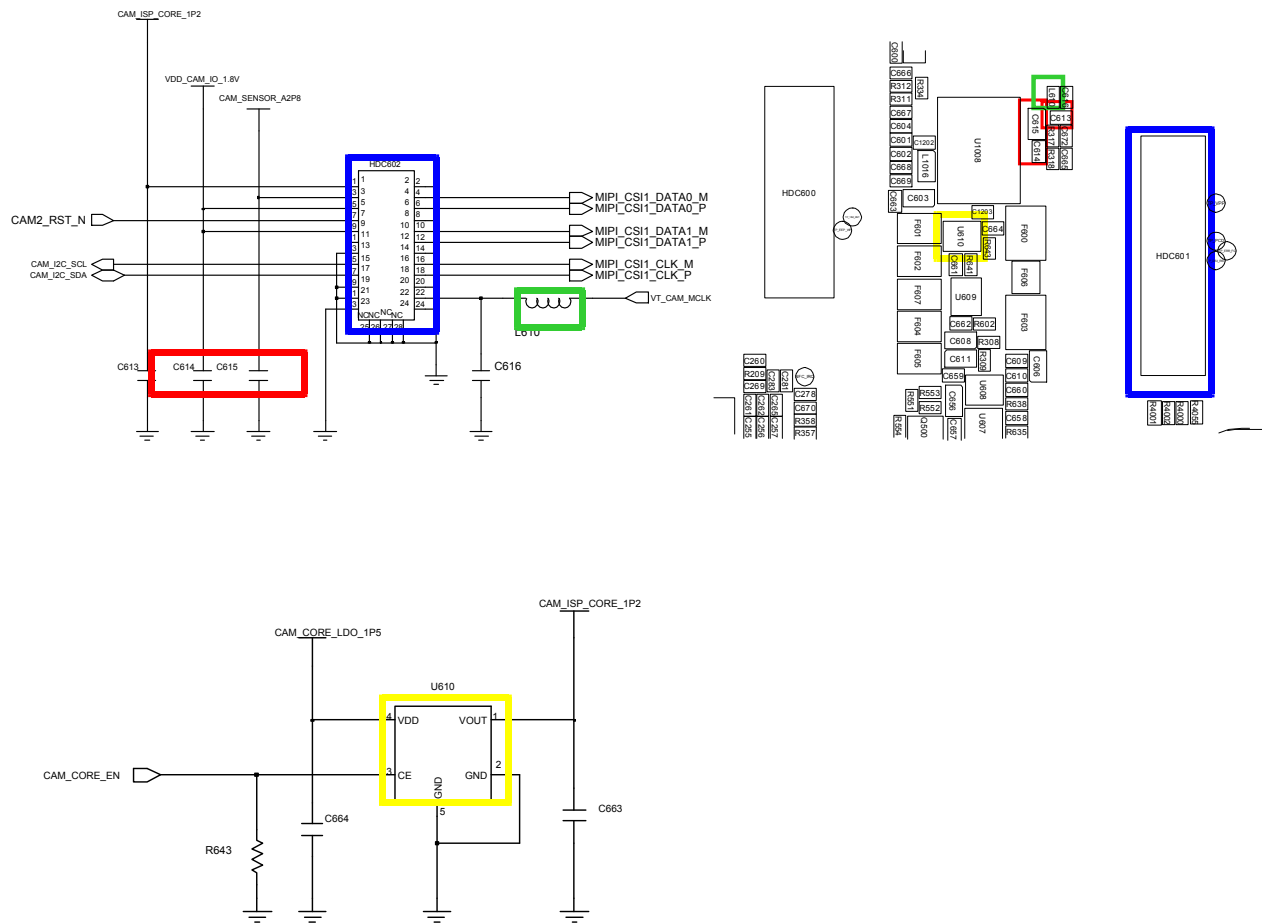
13M Camera CON

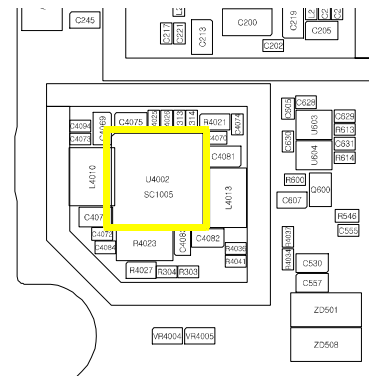
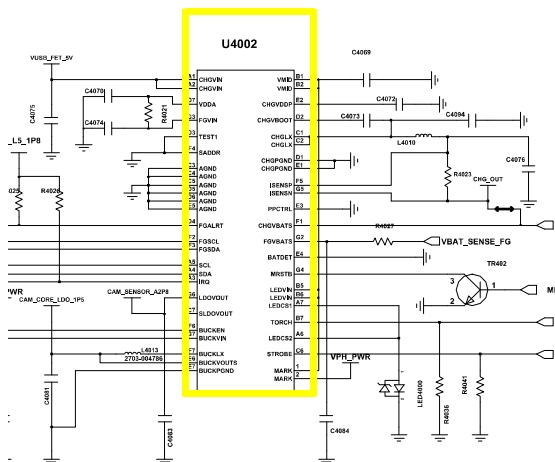
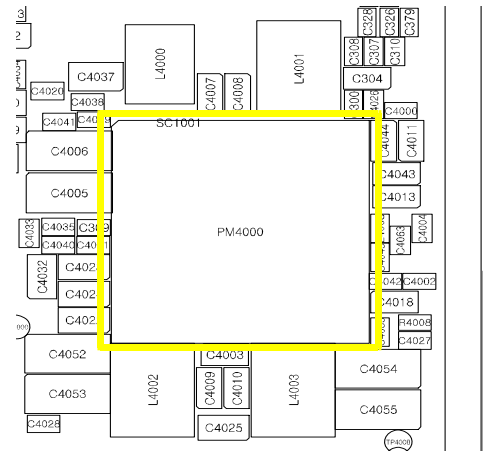
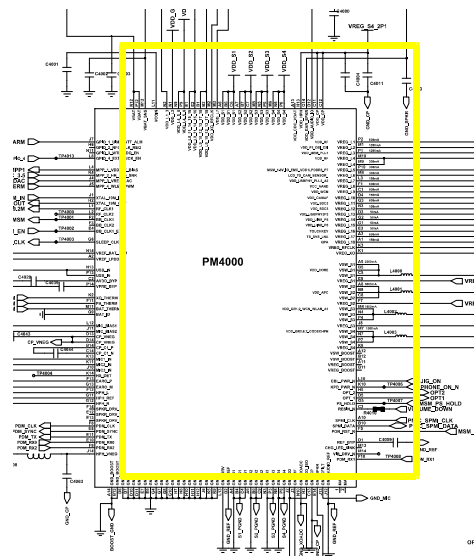
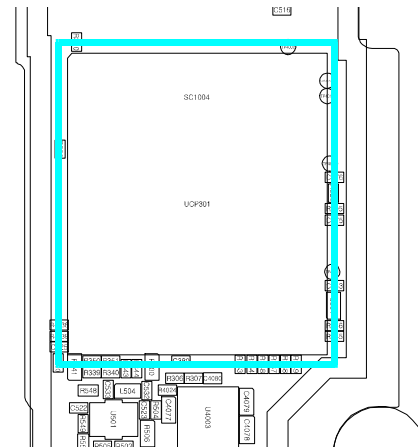
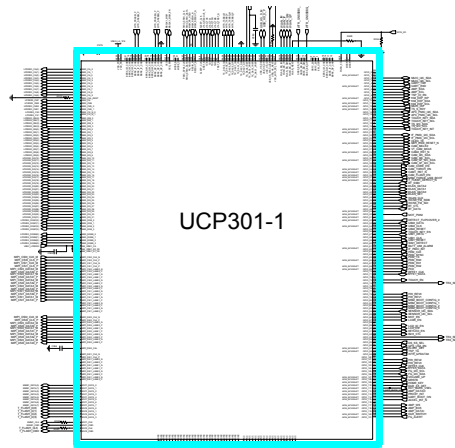




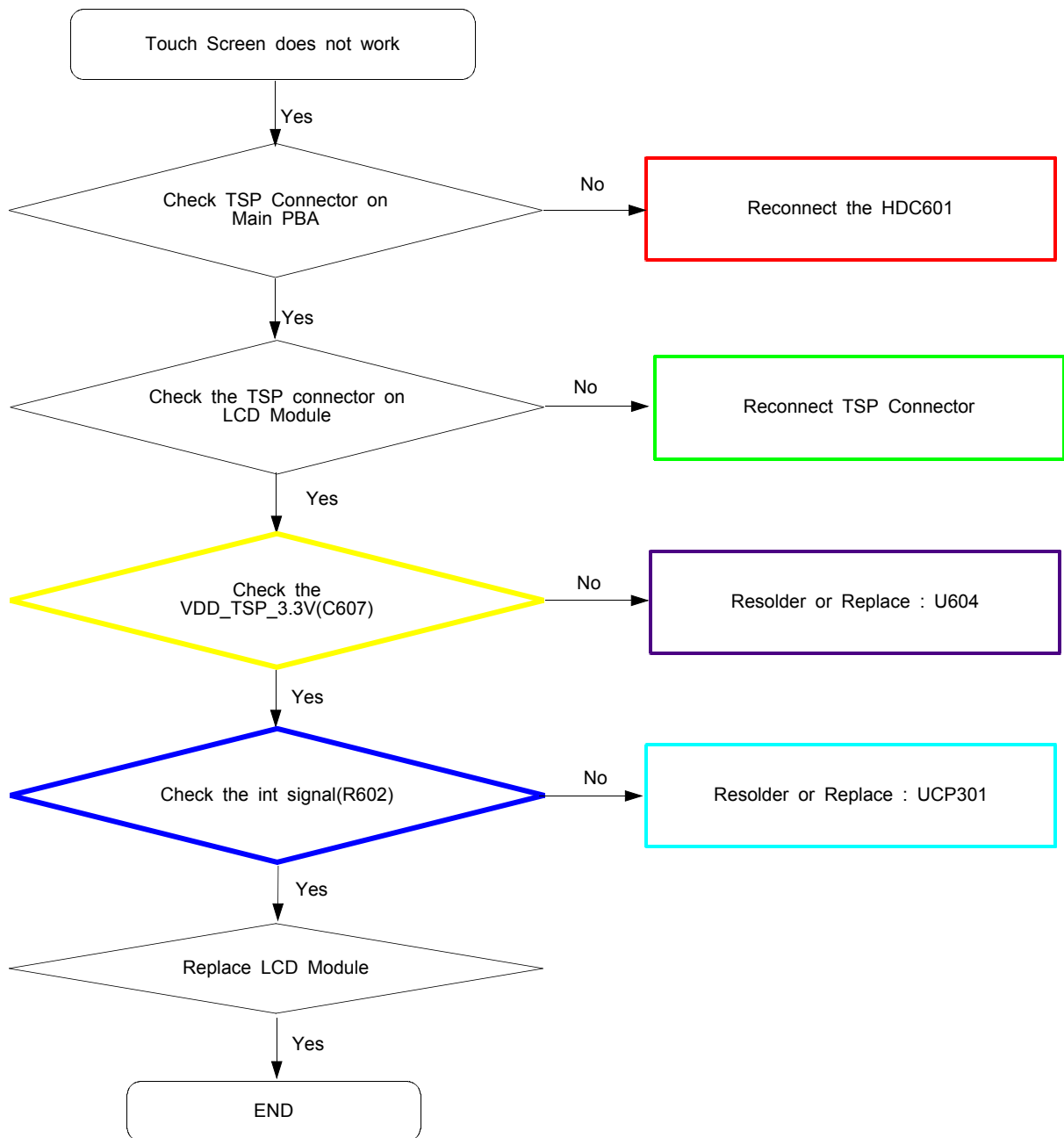
8-3-15. 5M CAM

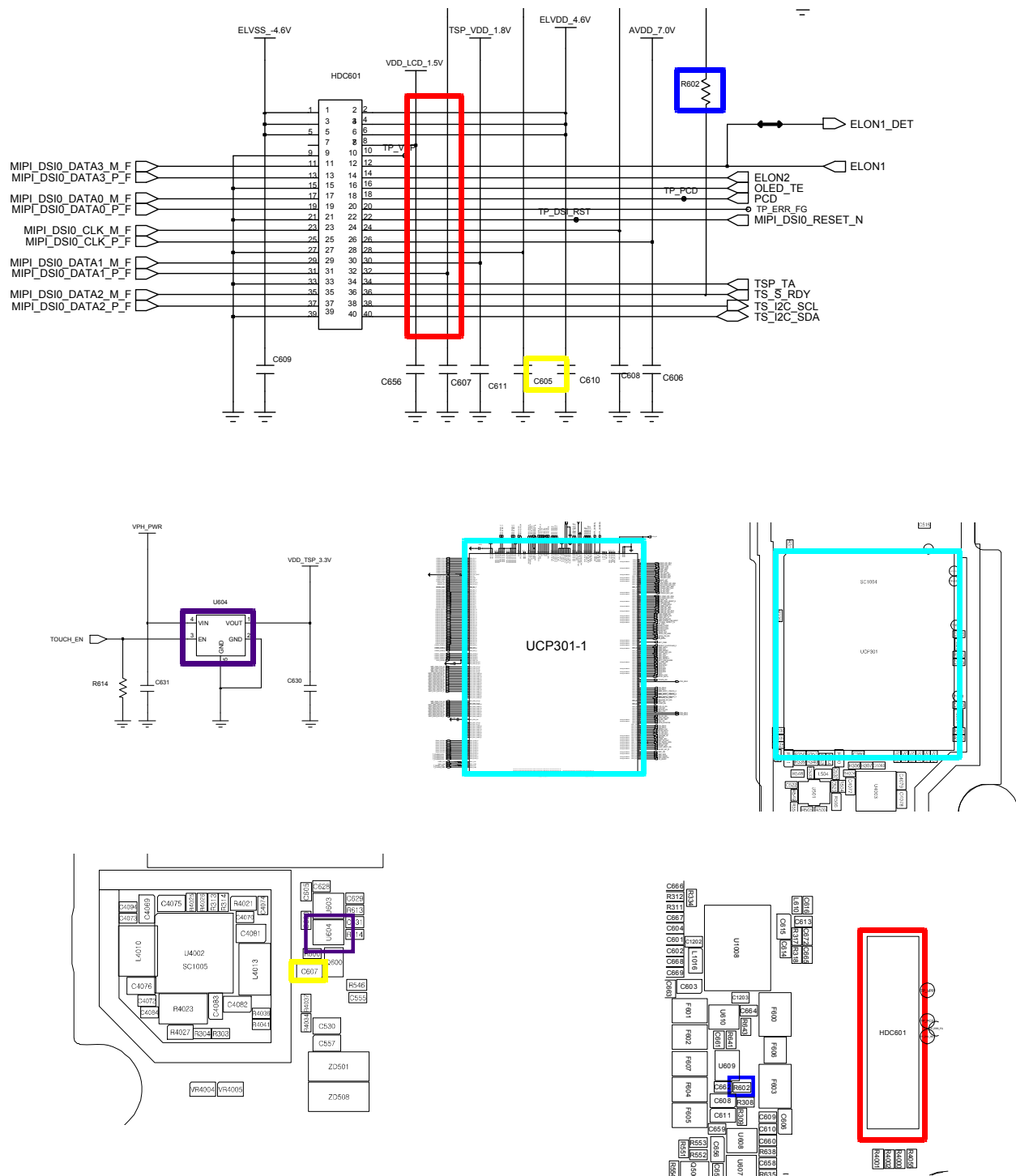




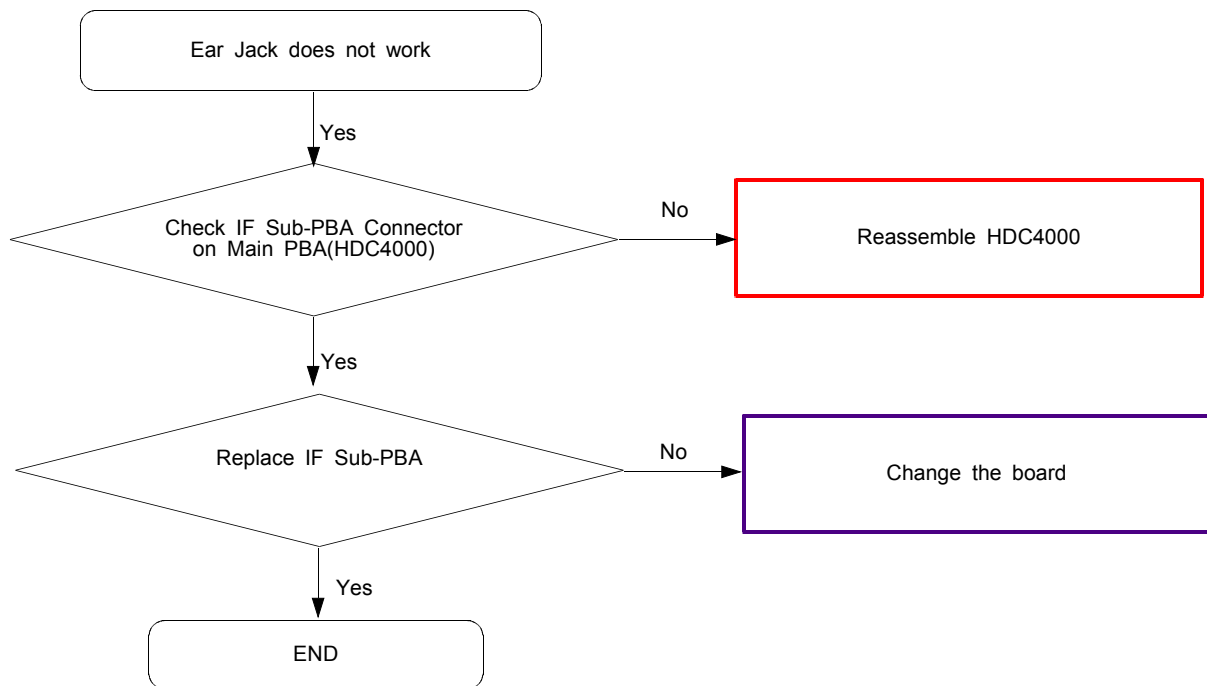


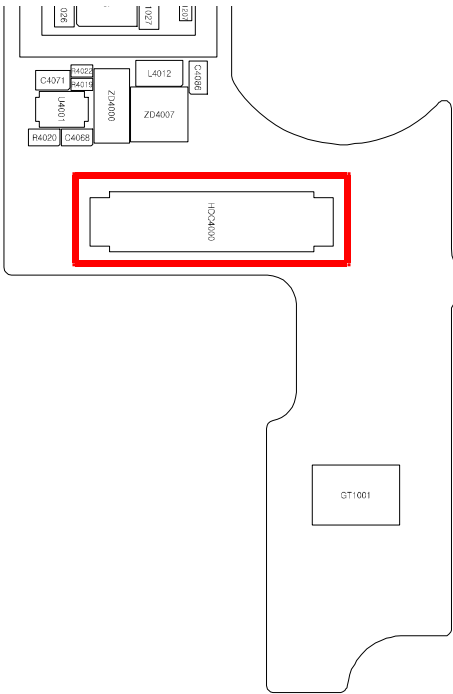
8-3-16. TSP



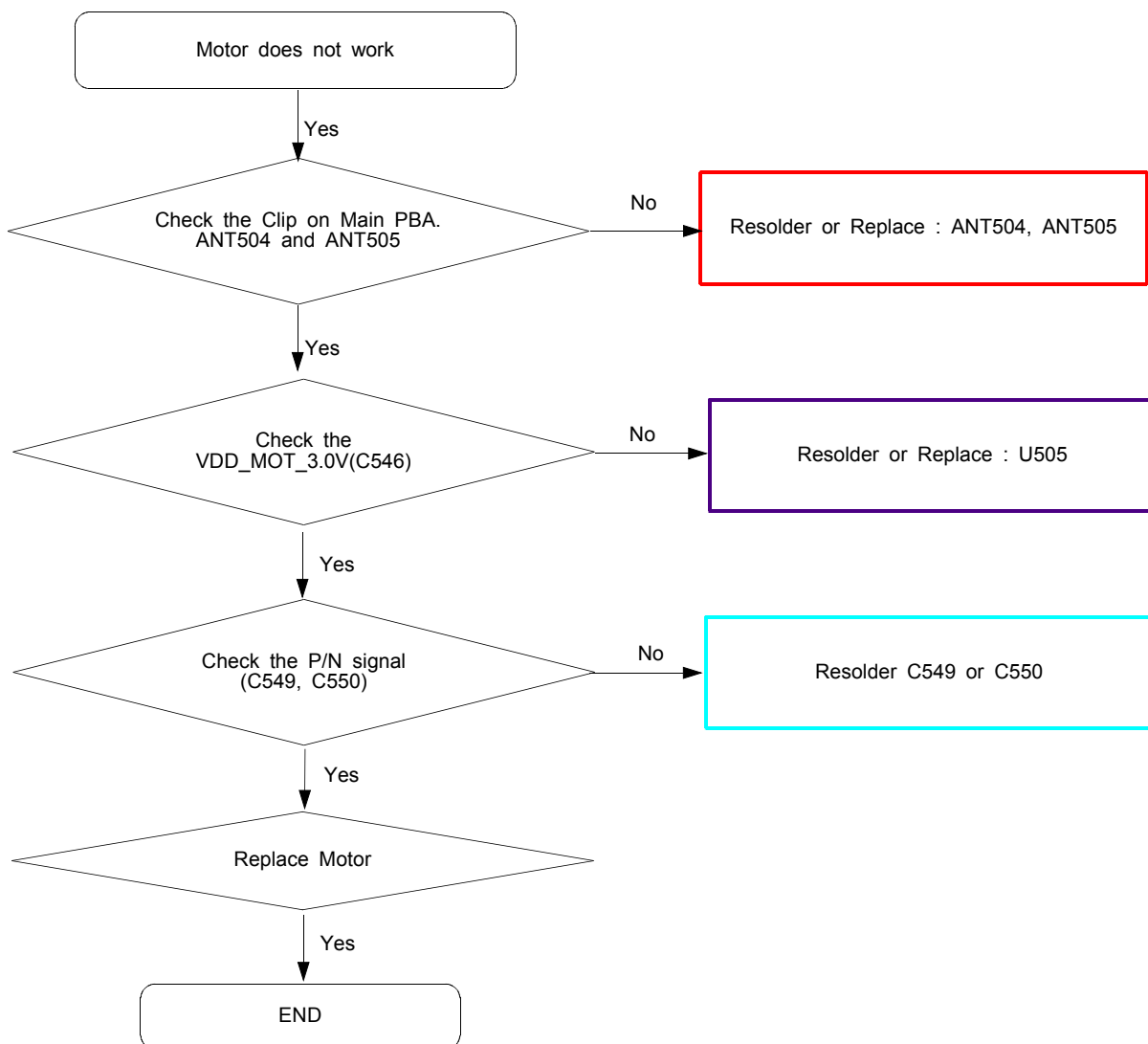


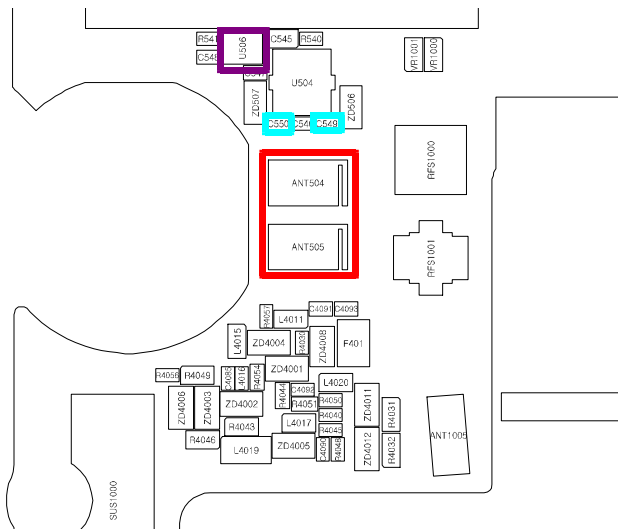
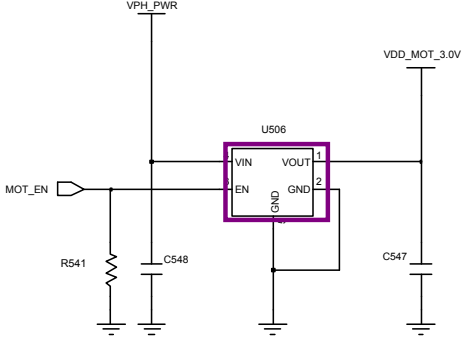
8-3-17. Ear Jack



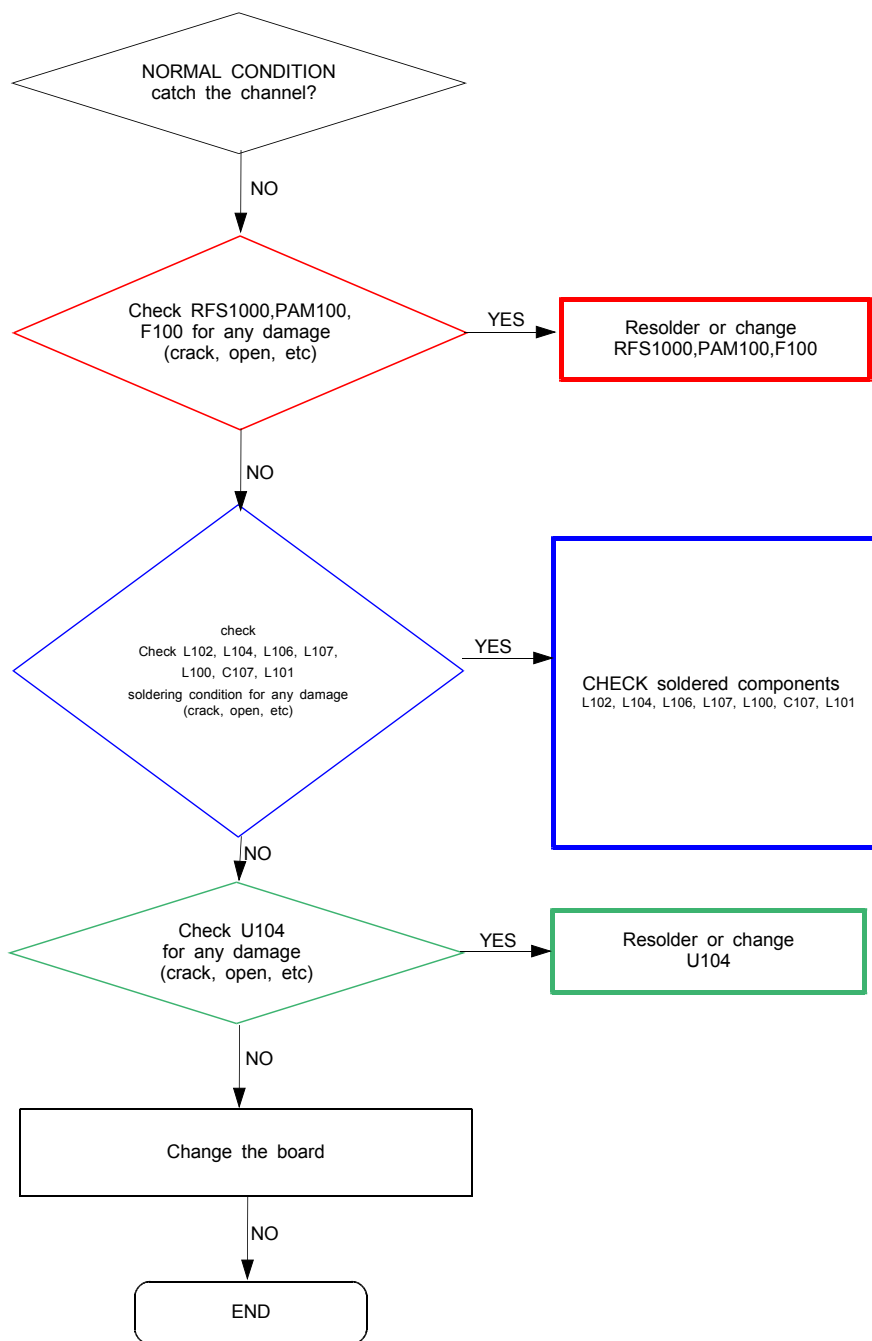


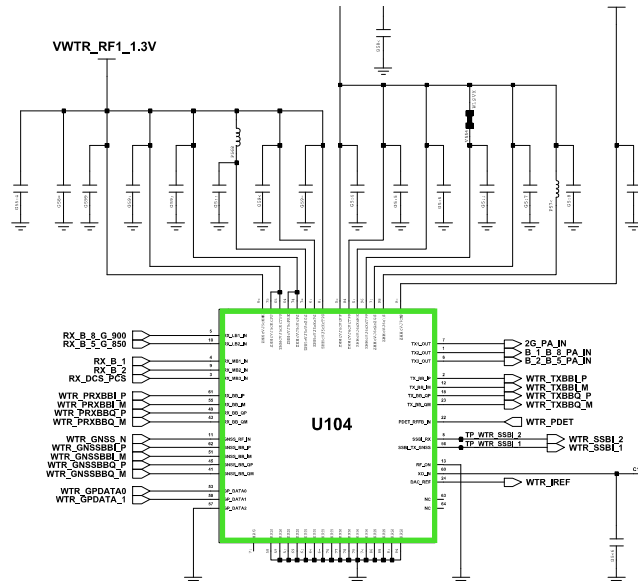
8-3-18. Motor

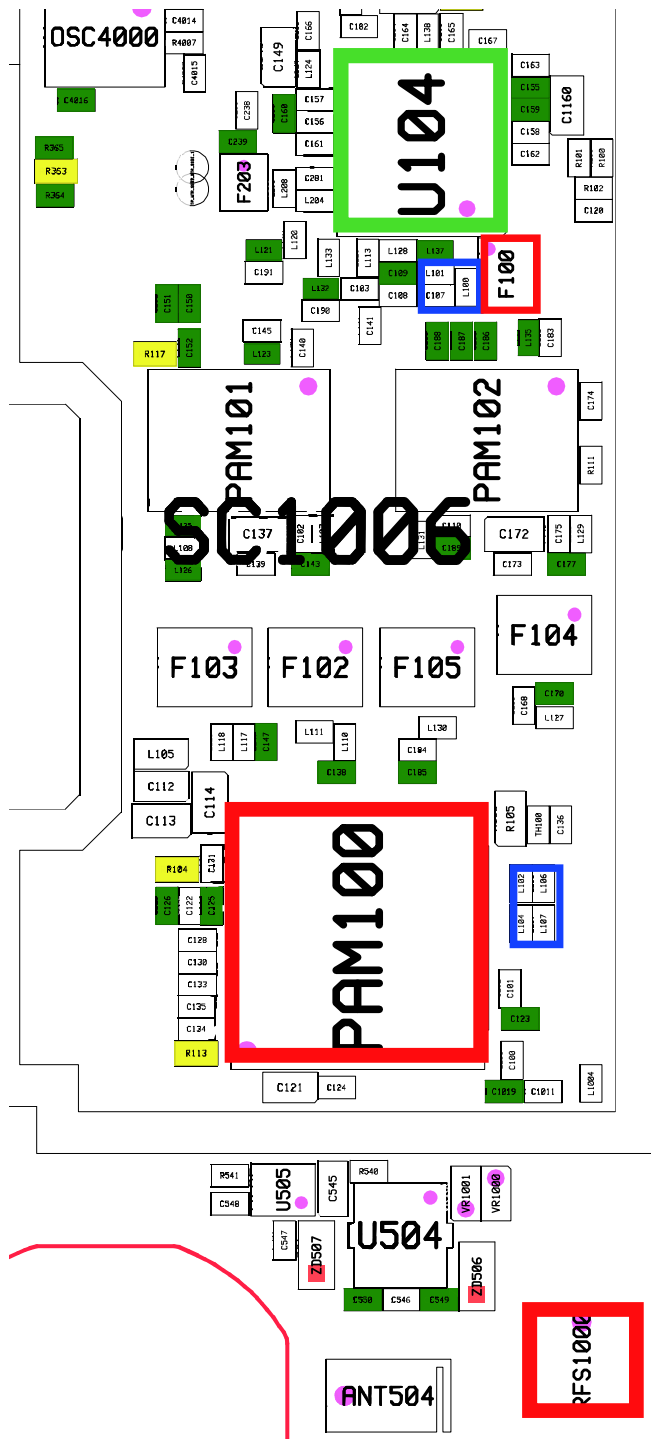




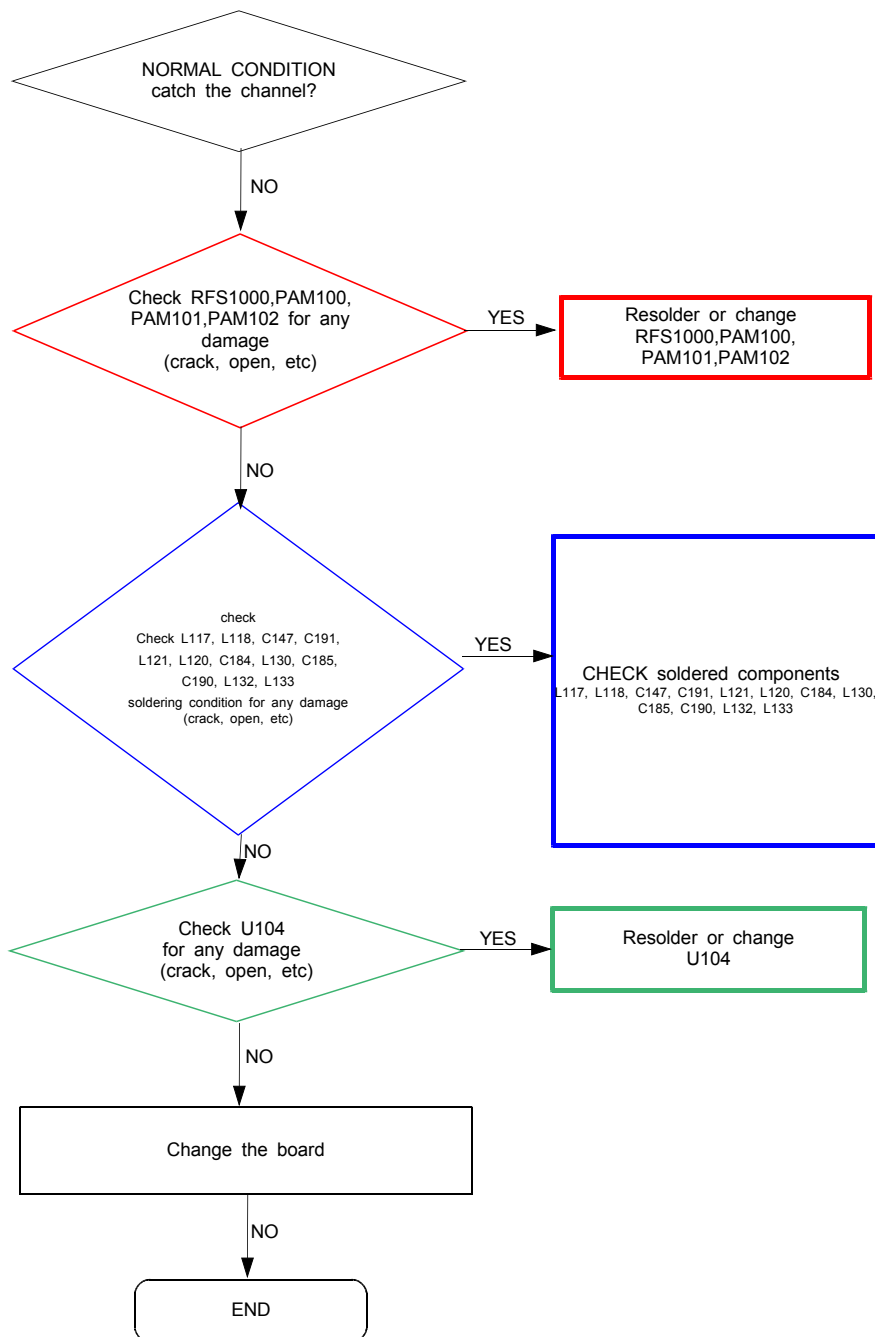
8-3-19. GSM 850,900 Rx

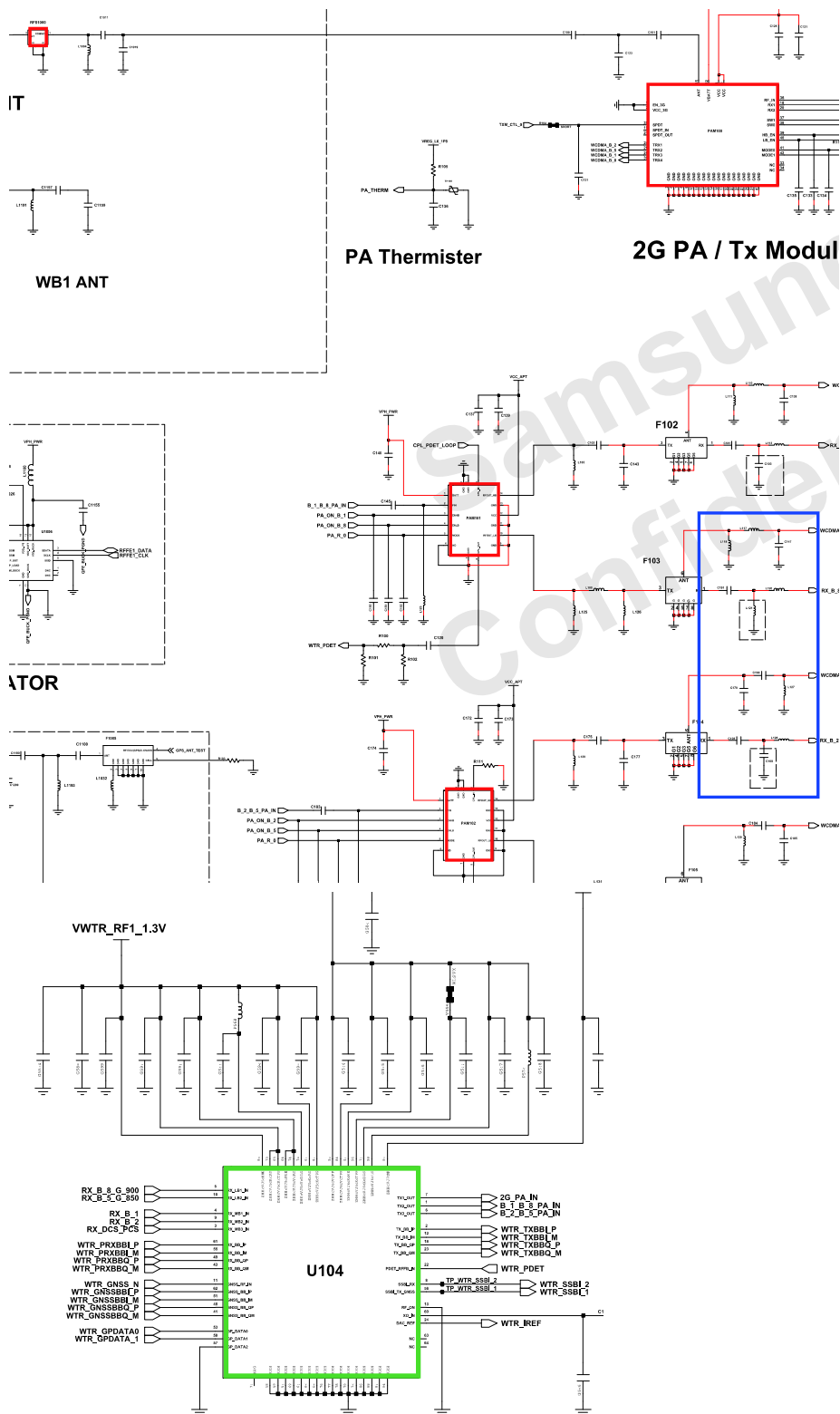


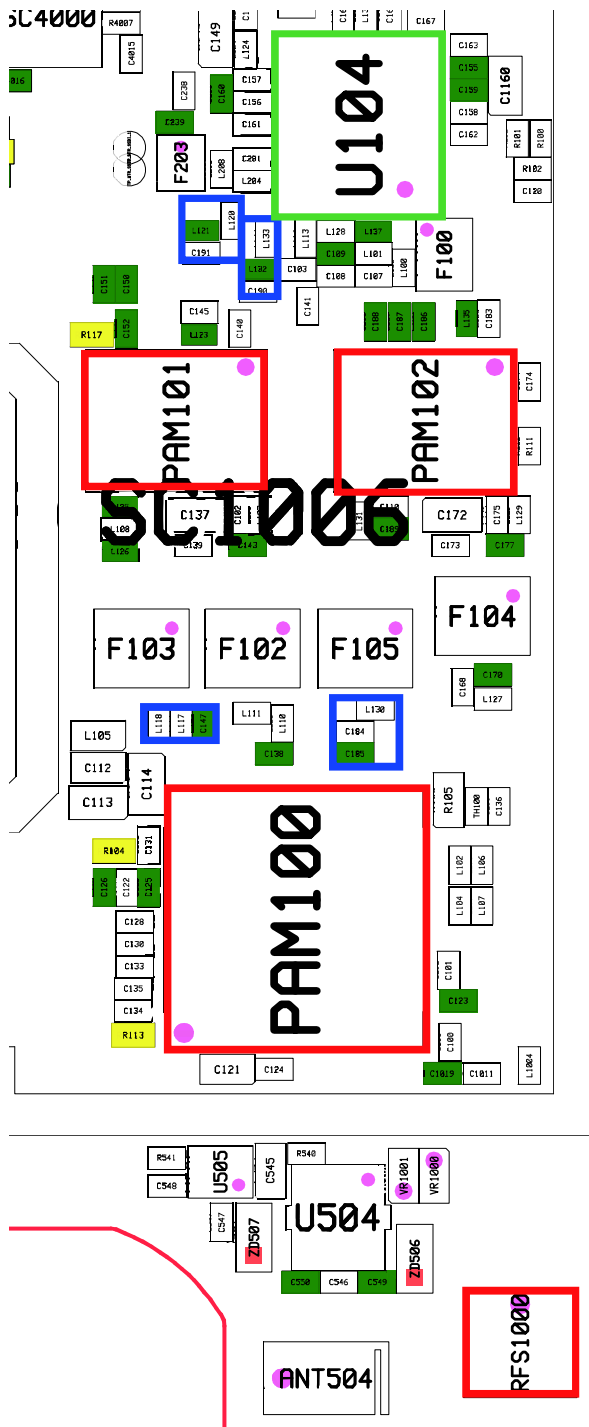




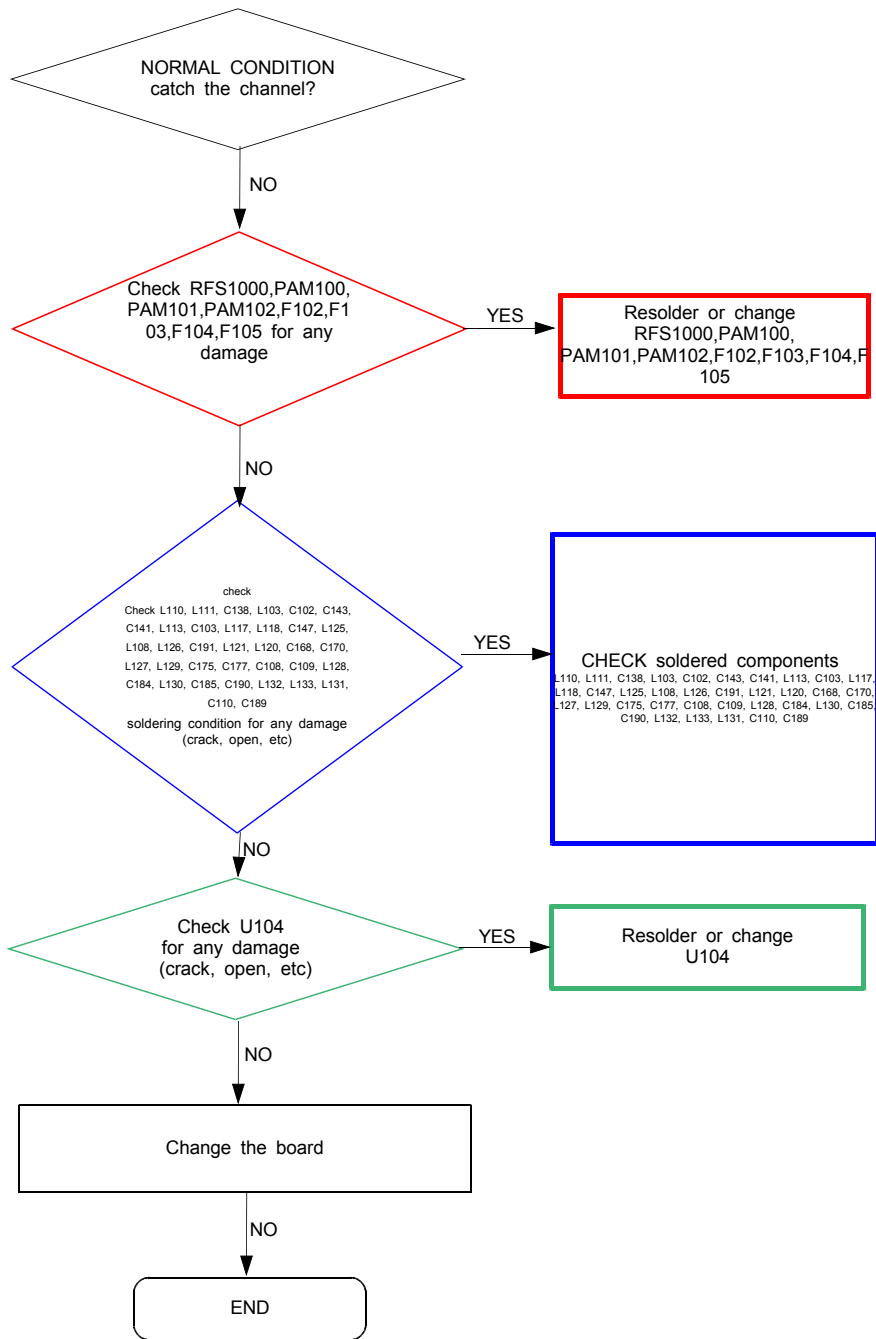
8-3-20. GSM 1800, 1900 Rx

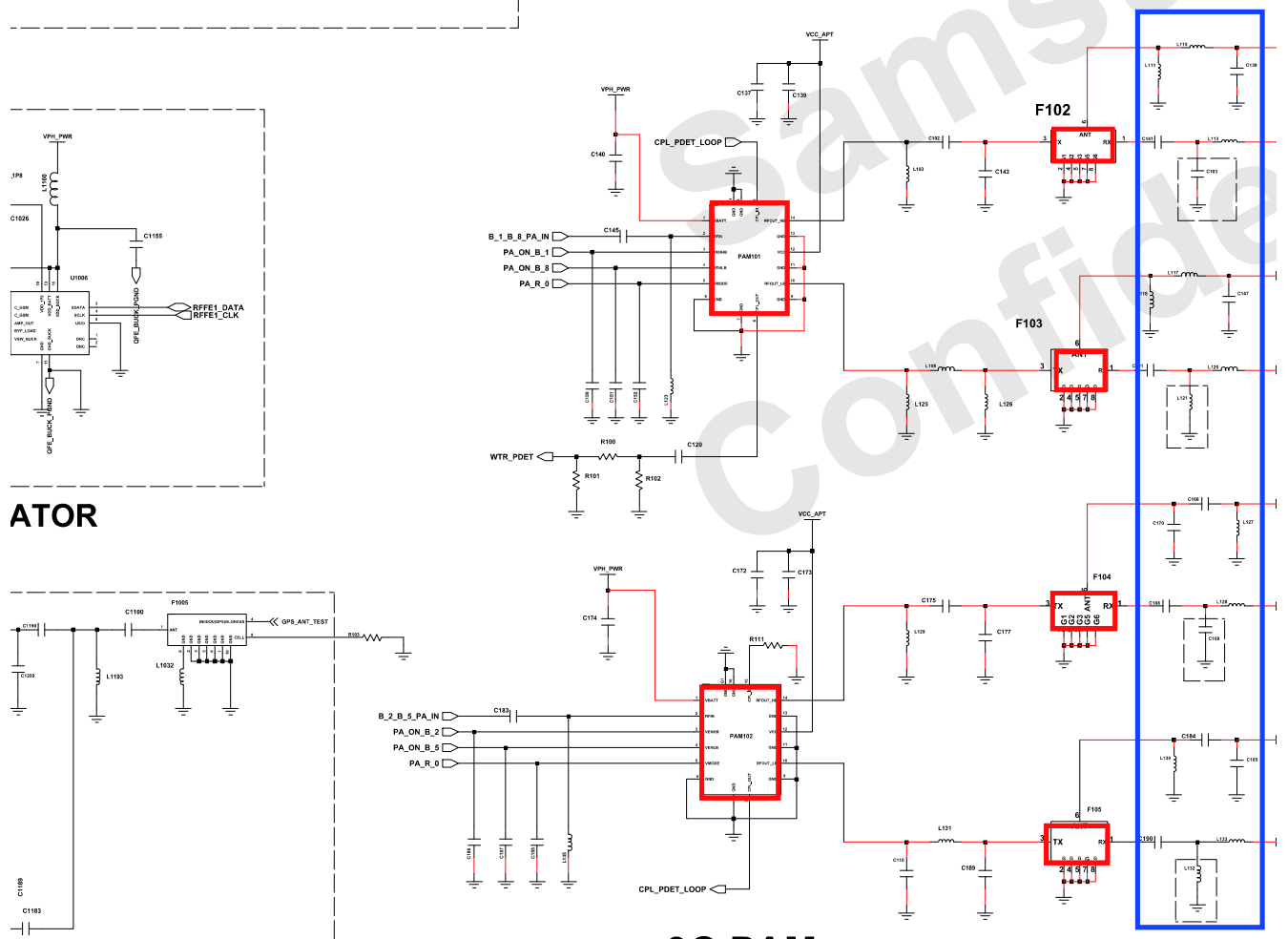
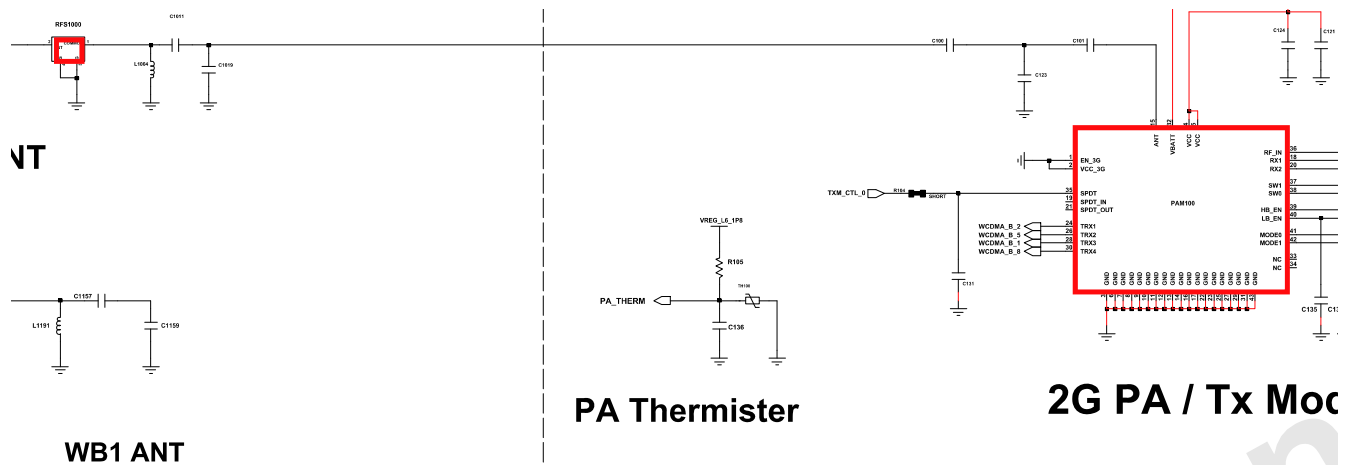


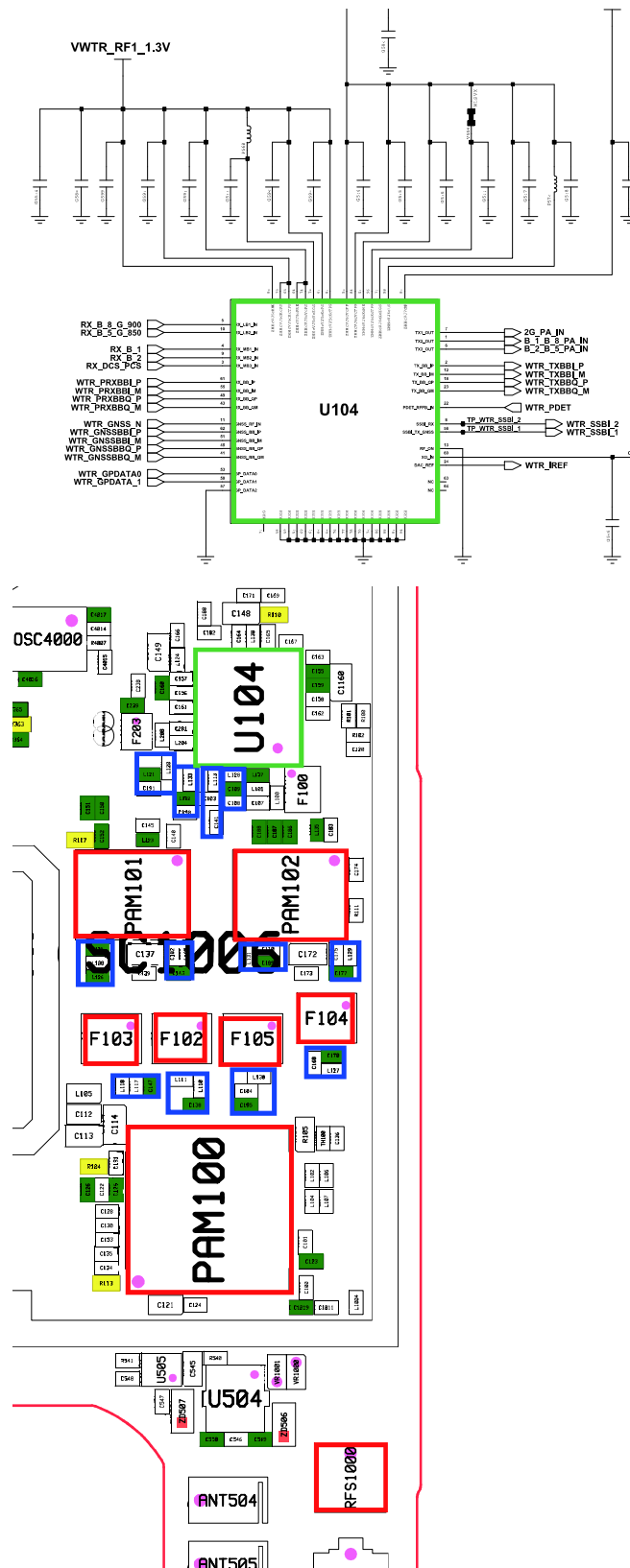




8-3-21. WCDMA B1,B2,B5,B8





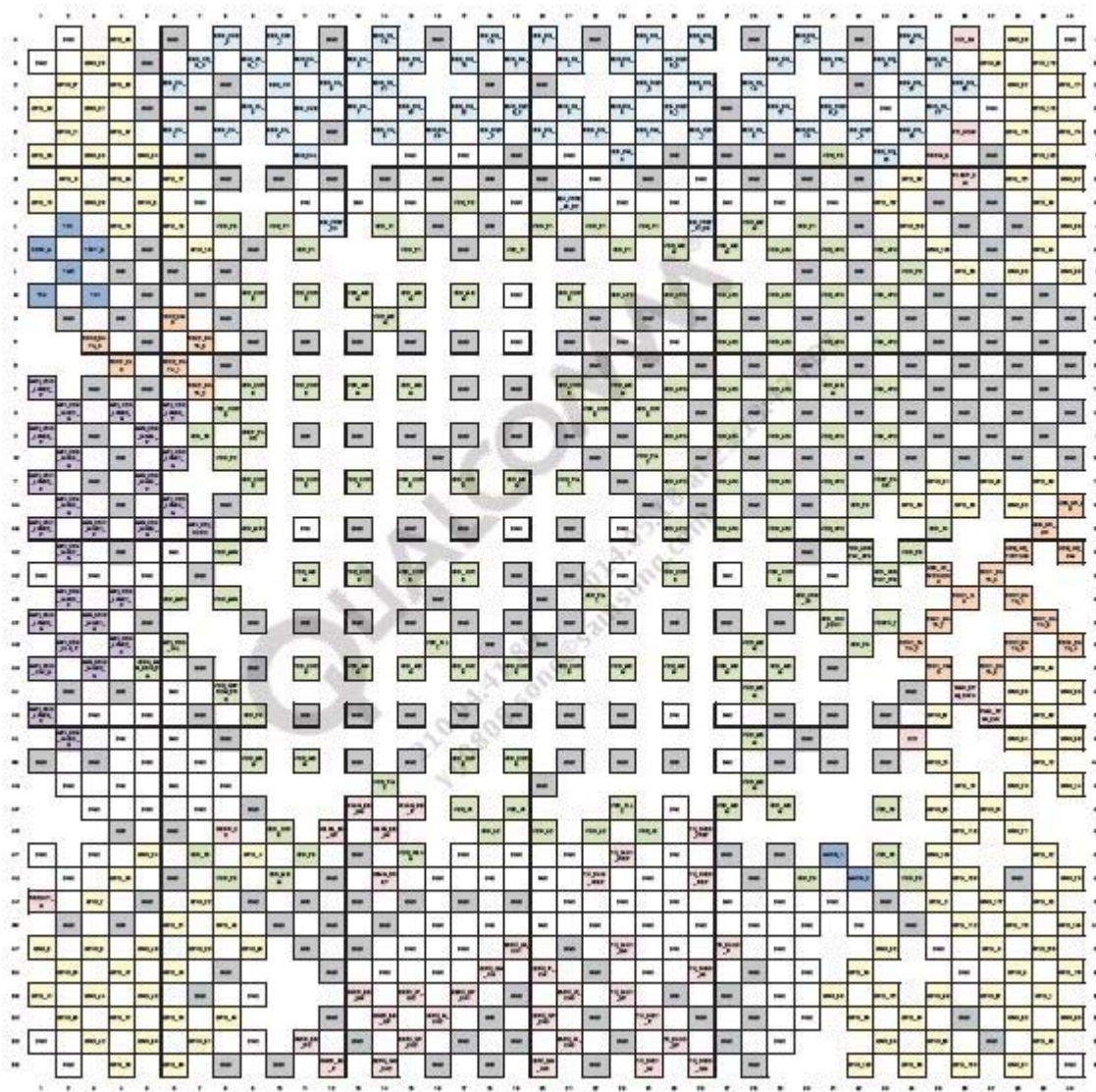


-NC Point(Top View)

●: NC

	1	2	3	4	5	6	7	8	9	10	11	12	13	14
A														
B														
C	●													●
D	●								●	●	●	●	●	●
E	●	●	●	●	●	●	●	●	●	●	●	●	●	●
F	●					●	●							●
G	●					●	●							●
H	●					●	●							●
I	●					●	●							●
J	●					●	●							●
K	●					●	●							●
L	●					●	●							●
M	●					●	●							●
N	●					●	●							●
P	●					●	●							●
R	●					●	●							●
T	●					●	●							●
U	●					●	●							●
V	●					●	●							●
W	●					●	●							●
Y	●					●	●							●
AA						●	●							
AB						●	●							

UME500



The image displays a large, complex grid of data, likely a repair data table for a Samsung device. The grid is organized into rows and columns, with each cell containing a numerical value. The values are color-coded: blue for positive values, red for negative values, and green for zero. The grid is divided into several sections by vertical and horizontal lines, suggesting a hierarchical or categorical structure. The overall layout is dense and technical, typical of a repair data sheet.

UCP301

	<u>1</u>	<u>2</u>	<u>3</u>	<u>4</u>	<u>5</u>	<u>6</u>	<u>7</u>	<u>8</u>	<u>9</u>	<u>10</u>	<u>11</u>	<u>12</u>	<u>13</u>	<u>14</u>
<u>A</u>														
<u>B</u>														
<u>C</u>										●				
<u>D</u>								●	●					
<u>E</u>						●								
<u>F</u>				●		●								
<u>G</u>														
<u>H</u>	●			●					●					●
<u>J</u>									●					
<u>K</u>						●	●					●		
<u>L</u>					●	●	●		●					
<u>M</u>														●
<u>N</u>														
<u>P</u>											●			

PM4000